AUTOMATIC GREENHOUSE WATERING SYSTEM USING MICROCONTROLLER

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APPENDIXA: PROGRAMMING FOR THE PROJECT

```
REG       EQU   $1000
PORTA     EQU   0
PORTC     EQU   3
PORTB     EQU   4
DDRC      EQU   7
PORTE     EQU   10
OPTION    EQU   $39
ADCTL     EQU   $30
ADR1      EQU   $31

START     ORG   $B600
          LDS   #$FF
          LDX   #REG
          LDAA  #$FF
          STAA  DDRC, X

LOOP      BSR   LED
          BSR   ADC
          BSR   COMP
          BRA   LOOP

LED       CLC
          BCLR  PORTC, X      %11111111
          LDAA        #$01
          STAA  PORTB, X
          BSR   DELAY

ULANG     ROLA
          STAA  PORTB, X
          BSR   DELAY
          BCC   ULANG
          RTS

ADC       LDAA  #$80          ;
          STAA  OPTION, X     ; on ADPU,clear CSEL( using E clock)
          BSR   DELAY1        ; delay for stabilizing adc, at least 100us
          LDAA        #0      ;
          STAA  ADCTL, X      ; set adc control for single mode

SCAN      BRCLR ADCTL, X $80 SCAN ; scan conversion flag=1
          LDAA  ADR1, X       ; load data from adr1
          ADDA        #10     ;start process to convert value to
                              hexadecimal
          TAB
          CLRA
          LDX   #$A
          IDIV
          PSHB
```

```
            PSHX
            LDAA #$10
            PULB
            PULB
            MUL
            PULA
            STAB  $14
            ADDA $14            ; data convert to hexadecimal
            RTS

DELAY1      LDAA        #$26    ; short delay
AGAIN       DECA
            BNE   AGAIN
            RTS

DELAY       LDY   #$FFFF
REPEAT      DEY
            BNE   REPEAT
            RTS

DELAY2      PSHY
            PSHX
            LDY  #$390
REPEAT1     LDX  #$FFFF
REPEAT2     DEX
            BNE  REPEAT2
            DEY
            BNE  REPEAT1
            PULX
            PULY
            RTS

COMP        LDX   #REG
            CMPA #$25
            BLS   OFF
            BSR   ON
            RTS
ON          LDAB #$01
            STAB  PORTC, X
            LDAB #$FF
            STAB  PORTB, X
            BSR   DELAY2
            BRA   OFF
            RTS
OFF         LDAB #$00
            STAB  PORTC, X
            LDAB #$00
            STAB  PORTB, X
            RTS
            END
```

19-4323; Rev 11; 2/03

+5V-Powered, Multichannel RS-232 Drivers/Receivers

General Description

The MAX220–MAX249 family of line drivers/receivers is intended for all EIA/TIA-232E and V.28/V.24 communications interfaces, particularly applications where ±12V is not available.

These parts are especially useful in battery-powered systems, since their low-power shutdown mode reduces power dissipation to less than 5µW. The MAX225, MAX233, MAX235, and MAX245/MAX246/MAX247 use no external components and are recommended for applications where printed circuit board space is critical.

Applications

Portable Computers

Low-Power Modems

Interface Translation

Battery-Powered RS-232 Systems

Multidrop RS-232 Networks

Features

Superior to Bipolar

- ♦ **Operate from Single +5V Power Supply (+5V and +12V—MAX231/MAX239)**
- ♦ **Low-Power Receive Mode in Shutdown (MAX223/MAX242)**
- ♦ **Meet All EIA/TIA-232E and V.28 Specifications**
- ♦ **Multiple Drivers and Receivers**
- ♦ **3-State Driver and Receiver Outputs**
- ♦ **Open-Line Detection (MAX243)**

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX220CPE	0°C to +70°C	16 Plastic DIP
MAX220CSE	0°C to +70°C	16 Narrow SO
MAX220CWE	0°C to +70°C	16 Wide SO
MAX220C/D	0°C to +70°C	Dice*
MAX220EPE	-40°C to +85°C	16 Plastic DIP
MAX220ESE	-40°C to +85°C	16 Narrow SO
MAX220EWE	-40°C to +85°C	16 Wide SO
MAX220EJE	-40°C to +85°C	16 CERDIP
MAX220MJE	-55°C to +125°C	16 CERDIP

Ordering Information continued at end of data sheet.

**Contact factory for dice specifications.*

Selection Table

Part Number	Power Supply (V)	No. of RS-232 Drivers/Rx	No. of Ext. Caps	Nominal Cap. Value (µF)	SHDN & Three-State	Rx Active in SHDN	Data Rate (kbps)	Features
MAX220	+5	2/2	4	0.1	No	—	120	Ultra-low-power, industry-standard pinout
MAX222	+5	2/2	4	0.1	Yes	—	200	Low-power shutdown
MAX223 (MAX213)	+5	4/5	4	1.0 (0.1)	Yes	✔	120	MAX241 and receivers active in shutdown
MAX225	+5	5/5	0	—	Yes	✔	120	Available in SO
MAX230 (MAX200)	+5	5/0	4	1.0 (0.1)	Yes	—	120	5 drivers with shutdown
MAX231 (MAX201)	+5 and +7.5 to +13.2	2/2	2	1.0 (0.1)	No	—	120	Standard +5/+12V or battery supplies; same functions as MAX232
MAX232 (MAX202)	+5	2/2	4	1.0 (0.1)	No	—	120 (64)	Industry standard
MAX232A	+5	2/2	4	0.1	No	—	200	Higher slew rate, small caps
MAX233 (MAX203)	+5	2/2	0	—	No	—	120	No external caps
MAX233A	+5	2/2	0	—	No	—	200	No external caps, high slew rate
MAX234 (MAX204)	+5	4/0	4	1.0 (0.1)	No	—	120	Replaces 1488
MAX235 (MAX205)	+5	5/5	0	—	Yes	—	120	No external caps
MAX236 (MAX206)	+5	4/3	4	1.0 (0.1)	Yes	—	120	Shutdown, three state
MAX237 (MAX207)	+5	5/3	4	1.0 (0.1)	No	—	120	Complements IBM PC serial port
MAX238 (MAX208)	+5	4/4	4	1.0 (0.1)	No	—	120	Replaces 1488 and 1489
MAX239 (MAX209)	+5 and +7.5 to +13.2	3/5	2	1.0 (0.1)	No	—	120	Standard +5/+12V or battery supplies; single-package solution for IBM PC serial port
MAX240	+5	5/5	4	1.0	Yes	—	120	DIP or flatpack package
MAX241 (MAX211)	+5	4/5	4	1.0 (0.1)	Yes	—	120	Complete IBM PC serial port
MAX242	+5	2/2	4	0.1	Yes	✔	200	Separate shutdown and enable
MAX243	+5	2/2	4	0.1	No	—	200	Open-line detection simplifies cabling
MAX244	+5	8/10	4	1.0	No	—	120	High slew rate
MAX245	+5	8/10	0	—	Yes	✔	120	High slew rate, int. caps, two shutdown modes
MAX246	+5	8/10	0	—	Yes	✔	120	High slew rate, int. caps, three shutdown modes
MAX247	+5	8/9	0	—	Yes	✔	120	High slew rate, int. caps, nine operating modes
MAX248	+5	8/8	4	1.0	Yes	✔	120	High slew rate, selective half-chip enables
MAX249	+5	6/10	4	1.0	Yes	✔	120	Available in quad flatpack package

+5V-Powered, Multichannel RS-232 Drivers/Receivers

ABSOLUTE MAXIMUM RATINGS—MAX220/222/232A/233A/242/243

Supply Voltage (V_{CC}) ....-0.3V to +6V
Input Voltages
T_{IN}..-0.3V to (V_{CC} - 0.3V)
R_{IN} (Except MAX220) ....±30V
R_{IN} (MAX220)..±25V
T_{OUT} (Except MAX220) (Note 1) ....±15V
T_{OUT} (MAX220)..±13.2V
Output Voltages
T_{OUT}...±15V
R_{OUT}..-0.3V to (V_{CC} + 0.3V)
Driver/Receiver Output Short Circuited to GND.........Continuous
Continuous Power Dissipation (T_A = +70°C)
16-Pin Plastic DIP (derate 10.53mW/°C above +70°C)....842mW
18-Pin Plastic DIP (derate 11.11mW/°C above +70°C)....889mW
20-Pin Plastic DIP (derate 8.00mW/°C above +70°C) ..440mW
16-Pin Narrow SO (derate 8.70mW/°C above +70°C) ...696mW
16-Pin Wide SO (derate 9.52mW/°C above +70°C)......762mW
18-Pin Wide SO (derate 9.52mW/°C above +70°C)......762mW
20-Pin Wide SO (derate 10.00mW/°C above +70°C)....800mW
20-Pin SSOP (derate 8.00mW/°C above +70°C) 640mW
16-Pin CERDIP (derate 10.00mW/°C above +70°C).....800mW
18-Pin CERDIP (derate 10.53mW/°C above +70°C).....842mW
Operating Temperature Ranges
MAX2_ _AC_ _, MAX2_ _C_ _.............................0°C to +70°C
MAX2_ _AE_ _, MAX2_ _E_ _ ....-40°C to +85°C
MAX2_ _AM_ _, MAX2_ _M_ _.......................-55°C to +125°C
Storage Temperature Range ....-65°C to +160°C
Lead Temperature (soldering, 10s) ....+300°C

Note 1: Input voltage measured with T_{OUT} in high-impedance state, $\overline{SHDN}$ or V_{CC} = 0V.
Note 2: For the MAX220, V+ and V- can have a maximum magnitude of 7V, but their absolute difference cannot exceed 13V.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS—MAX220/222/232A/233A/242/243

(V_{CC} = +5V ±10%, C1–C4 = 0.1µF, MAX220, C1 = 0.047µF, C2–C4 = 0.33µF, T_A = T_{MIN} to T_{MAX}, unless otherwise noted.)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
RS-232 TRANSMITTERS						
Output Voltage Swing	All transmitter outputs loaded with 3kΩ to GND		±5	±8		V
Input Logic Threshold Low				1.4	0.8	V
Input Logic Threshold High	All devices except MAX220		2	1.4		V
	MAX220: V_{CC} = 5.0V		2.4			
Logic Pull-Up/Input Current	All except MAX220, normal operation			5	40	µA
	$\overline{SHDN}$ = 0V, MAX222/242, shutdown, MAX220			±0.01	±1	
Output Leakage Current	V_{CC} = 5.5V, $\overline{SHDN}$ = 0V, V_{OUT} = ±15V, MAX222/242			±0.01	±10	µA
	V_{CC} = $\overline{SHDN}$ = 0V, V_{OUT} = ±15V			±0.01	±10	
Data Rate				200	116	kbps
Transmitter Output Resistance	V_{CC} = V+ = V- = 0V, V_{OUT} = ±2V		300	10M		Ω
Output Short-Circuit Current	V_{OUT} = 0V		±7	±22		mA
RS-232 RECEIVERS						
RS-232 Input Voltage Operating Range					±30	V
RS-232 Input Threshold Low	V_{CC} = 5V	All except MAX243 $R2_{IN}$	0.8	1.3		V
		MAX243 $R2_{IN}$ (Note 2)	-3			
RS-232 Input Threshold High	V_{CC} = 5V	All except MAX243 $R2_{IN}$		1.8	2.4	V
		MAX243 $R2_{IN}$ (Note 2)		-0.5	-0.1	
RS-232 Input Hysteresis	All except MAX243, V_{CC} = 5V, no hysteresis in shdn.		0.2	0.5	1	V
	MAX243			1		
RS-232 Input Resistance			3	5	7	kΩ
TTL/CMOS Output Voltage Low	I_{OUT} = 3.2mA			0.2	0.4	V
TTL/CMOS Output Voltage High	I_{OUT} = -1.0mA		3.5	V_{CC} - 0.2		V
TTL/CMOS Output Short-Circuit Current	Sourcing V_{OUT} = GND		-2	-10		mA
	Shrinking V_{OUT} = V_{CC}		10	30		

ELECTRICAL CHARACTERISTICS—MAX220/222/232A/233A/242/243 (continued)

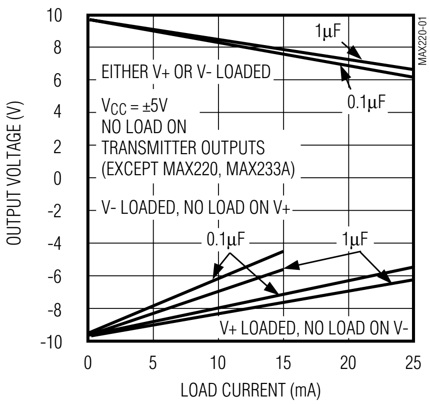
(V_{CC} = +5V ±10%, C1–C4 = 0.1µF, MAX220, C1 = 0.047µF, C2–C4 = 0.33µF, T_A = T_{MIN} to T_{MAX}, unless otherwise noted.)

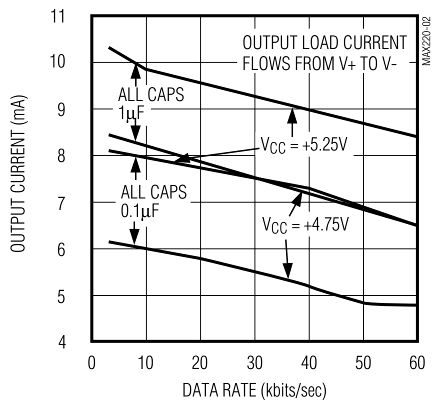
PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
TTL/CMOS Output Leakage Current	$\overline{SHDN}$ = V_{CC} or $\overline{EN}$ = V_{CC} ($\overline{SHDN}$ = 0V for MAX222), 0V ≤ V_{OUT} ≤ V_{CC}			±0.05	±10	µA
$\overline{EN}$ Input Threshold Low	MAX242			1.4	0.8	V
$\overline{EN}$ Input Threshold High	MAX242		2.0	1.4		V
Operating Supply Voltage			4.5		5.5	V
V_{CC} Supply Current ($\overline{SHDN}$ = V_{CC}), Figures 5, 6, 11, 19	No load	MAX220		0.5	2	mA
		MAX222/232A/233A/242/243		4	10	
	3kΩ load both inputs	MAX220		12		
		MAX222/232A/233A/242/243		15		
Shutdown Supply Current	MAX222/242	T_A = +25°C		0.1	10	µA
		T_A = 0°C to +70°C		2	50	
		T_A = -40°C to +85°C		2	50	
		T_A = -55°C to +125°C		35	100	
$\overline{SHDN}$ Input Leakage Current	MAX222/242				±1	µA
$\overline{SHDN}$ Threshold Low	MAX222/242			1.4	0.8	V
$\overline{SHDN}$ Threshold High	MAX222/242		2.0	1.4		V
Transition Slew Rate	C_L = 50pF to 2500pF, R_L = 3kΩ to 7kΩ, V_{CC} = 5V, T_A = +25°C, measured from +3V to -3V or -3V to +3V	MAX222/232A/233A/242/243	6	12	30	V/µs
		MAX220	1.5	3	30	
Transmitter Propagation Delay TLL to RS-232 (Normal Operation), Figure 1	t_{PHLT}	MAX222/232A/233A/242/243		1.3	3.5	µs
		MAX220		4	10	
	t_{PLHT}	MAX222/232A/233A/242/243		1.5	3.5	
		MAX220		5	10	
Receiver Propagation Delay RS-232 to TLL (Normal Operation), Figure 2	t_{PHLR}	MAX222/232A/233A/242/243		0.5	1	µs
		MAX220		0.6	3	
	t_{PLHR}	MAX222/232A/233A/242/243		0.6	1	
		MAX220		0.8	3	
Receiver Propagation Delay RS-232 to TLL (Shutdown), Figure 2	t_{PHLS}	MAX242		0.5	10	µs
	t_{PLHS}	MAX242		2.5	10	
Receiver-Output Enable Time, Figure 3	t_{ER}	MAX242		125	500	ns
Receiver-Output Disable Time, Figure 3	t_{DR}	MAX242		160	500	ns
Transmitter-Output Enable Time ($\overline{SHDN}$ Goes High), Figure 4	t_{ET}	MAX222/242, 0.1µF caps (includes charge-pump start-up)		250		µs
Transmitter-Output Disable Time ($\overline{SHDN}$ Goes Low), Figure 4	t_{DT}	MAX222/242, 0.1µF caps		600		ns
Transmitter + to - Propagation Delay Difference (Normal Operation)	t_{PHLT} - t_{PLHT}	MAX222/232A/233A/242/243		300		ns
		MAX220		2000		
Receiver + to - Propagation Delay Difference (Normal Operation)	t_{PHLR} - t_{PLHR}	MAX222/232A/233A/242/243		100		ns
		MAX220		225		

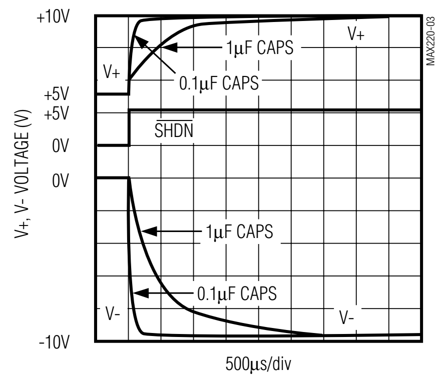
Note 3: MAX243 $R2_{OUT}$ is guaranteed to be low when $R2_{IN}$ is ≥ 0V or is floating.

Typical Operating Characteristics

MAX220/MAX222/MAX232A/MAX233A/MAX242/MAX243







ABSOLUTE MAXIMUM RATINGS—MAX223/MAX230–MAX241

V_{CC} ....-0.3V to +6V
V+ ....(V_{CC} - 0.3V) to +14V
V- ....+0.3V to -14V
Input Voltages
  T_{IN} ....-0.3V to (V_{CC} + 0.3V)
  R_{IN}...±30V
Output Voltages
  T_{OUT} ....(V+ + 0.3V) to (V- - 0.3V)
  R_{OUT}..-0.3V to (V_{CC} + 0.3V)
Short-Circuit Duration, T_{OUT} ....Continuous
Continuous Power Dissipation (T_A = +70°C)
  14-Pin Plastic DIP (derate 10.00mW/°C above +70°C)....800mW
  16-Pin Plastic DIP (derate 10.53mW/°C above +70°C)....842mW
  20-Pin Plastic DIP (derate 11.11mW/°C above +70°C)....889mW
  24-Pin Narrow Plastic DIP
    (derate 13.33mW/°C above +70°C) 1.07W
  24-Pin Plastic DIP (derate 9.09mW/°C above +70°C)......500mW
  16-Pin Wide SO (derate 9.52mW/°C above +70°C).........762mW
  20-Pin Wide SO (derate 10 00mW/°C above +70°C).......800mW
  24-Pin Wide SO (derate 11.76mW/°C above +70°C).......941mW
  28-Pin Wide SO (derate 12.50mW/°C above +70°C) 1W
  44-Pin Plastic FP (derate 11.11mW/°C above +70°C) 889mW
  14-Pin CERDIP (derate 9.09mW/°C above +70°C)..........727mW
  16-Pin CERDIP (derate 10.00mW/°C above +70°C)........800mW
  20-Pin CERDIP (derate 11.11mW/°C above +70°C)........889mW
  24-Pin Narrow CERDIP
    (derate 12.50mW/°C above +70°C) 1W
  24-Pin Sidebraze (derate 20.0mW/°C above +70°C)..........1.6W
  28-Pin SSOP (derate 9.52mW/°C above +70°C).............762mW
Operating Temperature Ranges
  MAX2 _ _ C _ _...0°C to +70°C
  MAX2 _ _ E _ _..-40°C to +85°C
  MAX2 _ _ M _ _ ....-55°C to +125°C
Storage Temperature Range ....-65°C to +160°C
Lead Temperature (soldering, 10s) ....+300°C

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS—MAX223/MAX230–MAX241

(MAX223/230/232/234/236/237/238/240/241, V_{CC} = +5V ±10; MAX233/MAX235, V_{CC} = 5V ±5%, C1–C4 = 1.0µF; MAX231/MAX239, V_{CC} = 5V ±10%; V+ = 7.5V to 13.2V; T_A = T_{MIN} to T_{MAX}; unless otherwise noted.)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Output Voltage Swing	All transmitter outputs loaded with 3kΩ to ground		±5.0	±7.3		V
V_{CC} Power-Supply Current	No load, T_A = +25°C	MAX232/233		5	10	mA
		MAX223/230/234–238/240/241		7	15	
		MAX231/239		0.4	1	
V+ Power-Supply Current		MAX231		1.8	5	mA
		MAX239		5	15	
Shutdown Supply Current	T_A = +25°C	MAX223		15	50	µA
		MAX230/235/236/240/241		1	10	
Input Logic Threshold Low	T_{IN}; EN, $\overline{SHDN}$ (MAX233); $\overline{EN}$, SHDN (MAX230/235–241)				0.8	V
Input Logic Threshold High	T_{IN}		2.0			V
	EN, $\overline{SHDN}$ (MAX223); $\overline{EN}$, SHDN (MAX230/235/236/240/241)		2.4			
Logic Pull-Up Current	T_{IN} = 0V			1.5	200	µA
Receiver Input Voltage Operating Range			-30		30	V

ELECTRICAL CHARACTERISTICS—MAX223/MAX230–MAX241 (continued)

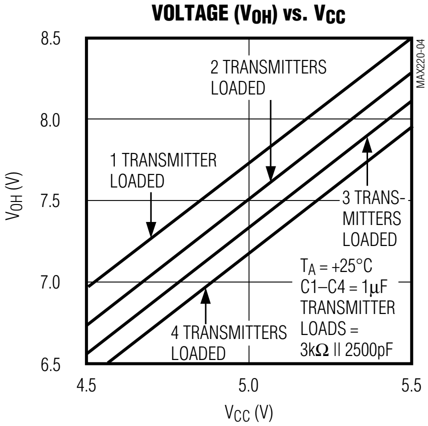
(MAX223/230/232/234/236/237/238/240/241, V_{CC} = +5V ±10; MAX233/MAX235, V_{CC} = 5V ±5%, C1–C4 = 1.0µF; MAX231/MAX239, V_{CC} = 5V ±10%; V+ = 7.5V to 13.2V; T_A = T_{MIN} to T_{MAX}; unless otherwise noted.)

PARAMETER	CONDITIONS			MIN	TYP	MAX	UNITS
RS-232 Input Threshold Low	T_A = +25°C, V_{CC} = 5V	Normal operation $\overline{SHDN}$ = 5V (MAX223) SHDN = 0V (MAX235/236/240/241)		0.8	1.2		V
		Shutdown (MAX223) $\overline{SHDN}$ = 0V, EN = 5V ($R4_{IN}$, $R5_{IN}$)		0.6	1.5		
RS-232 Input Threshold High	T_A = +25°C, V_{CC} = 5V	Normal operation $\overline{SHDN}$ = 5V (MAX223) SHDN = 0V (MAX235/236/240/241)			1.7	2.4	V
		Shutdown (MAX223) $\overline{SHDN}$ = 0V, EN = 5V ($R4_{IN}$, $R5_{IN}$)			1.5	2.4	
RS-232 Input Hysteresis	V_{CC} = 5V, no hysteresis in shutdown			0.2	0.5	1.0	V
RS-232 Input Resistance	T_A = +25°C, V_{CC} = 5V			3	5	7	kΩ
TTL/CMOS Output Voltage Low	I_{OUT} = 1.6mA (MAX231/232/233, I_{OUT} = 3.2mA)					0.4	V
TTL/CMOS Output Voltage High	I_{OUT} = -1mA			3.5	V_{CC} - 0.4		V
TTL/CMOS Output Leakage Current	0V ≤ R_{OUT} ≤ V_{CC}; EN = 0V (MAX223); $\overline{EN}$ = V_{CC} (MAX235–241)				0.05	±10	µA
Receiver Output Enable Time	Normal operation	MAX223			600		ns
		MAX235/236/239/240/241			400		
Receiver Output Disable Time	Normal operation	MAX223			900		ns
		MAX235/236/239/240/241			250		
Propagation Delay	RS-232 IN to TTL/CMOS OUT, C_L = 150pF	Normal operation			0.5	10	µs
		$\overline{SHDN}$ = 0V (MAX223)	t_{PHLS}		4	40	
			t_{PLHS}		6	40	
Transition Region Slew Rate	MAX223/MAX230/MAX234–241, T_A = +25°C, V_{CC} = 5V, R_L = 3kΩ to 7kΩ, C_L = 50pF to 2500pF, measured from +3V to -3V or -3V to +3V			3	5.1	30	V/µs
	MAX231/MAX232/MAX233, T_A = +25°C, V_{CC} = 5V, R_L = 3kΩ to 7kΩ, C_L = 50pF to 2500pF, measured from +3V to -3V or -3V to +3V				4	30	
Transmitter Output Resistance	V_{CC} = V+ = V- = 0V, V_{OUT} = ±2V			300			Ω
Transmitter Output Short-Circuit Current					±10		mA

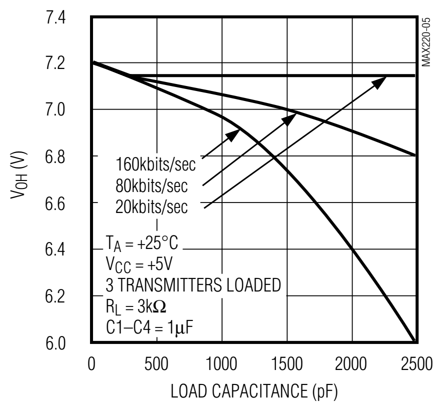
Typical Operating Characteristics

MAX223/MAX230–MAX241

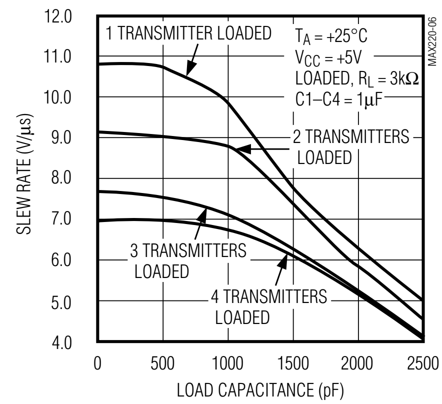
TRANSMITTER OUTPUT VOLTAGE (V_{OH}) vs. V_{CC}



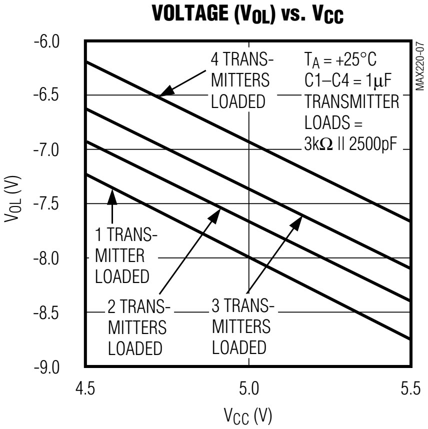
TRANSMITTER OUTPUT VOLTAGE (V_{OH}) vs. LOAD CAPACITANCE AT DIFFERENT DATA RATES



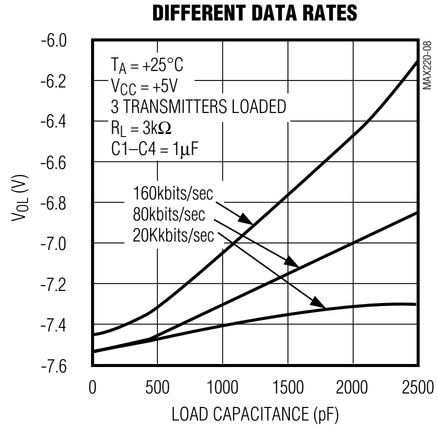
TRANSMITTER SLEW RATE vs. LOAD CAPACITANCE



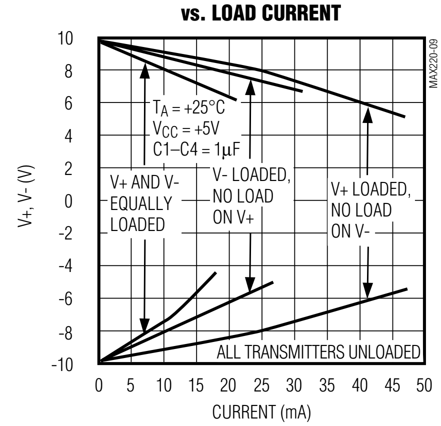
TRANSMITTER OUTPUT VOLTAGE (V_{OL}) vs. V_{CC}



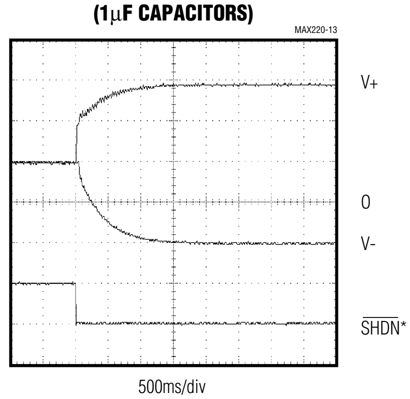
TRANSMITTER OUTPUT VOLTAGE (V_{OL}) vs. LOAD CAPACITANCE AT DIFFERENT DATA RATES



TRANSMITTER OUTPUT VOLTAGE (V+, V-) vs. LOAD CURRENT



V+, V- WHEN EXITING SHUTDOWN (1µF CAPACITORS)



*SHUTDOWN POLARITY IS REVERSED FOR NON MAX241 PARTS

ABSOLUTE MAXIMUM RATINGS—MAX225/MAX244–MAX249

Supply Voltage (V_{CC}) ....-0.3V to +6V
Input Voltages
T_{IN}, $\overline{ENA}$, $\overline{ENB}$, $\overline{ENR}$, $\overline{ENT}$, $\overline{ENRA}$,
$\overline{ENRB}$, $\overline{ENTA}$, $\overline{ENTB}$.................................-0.3V to (V_{CC} + 0.3V)
R_{IN} ....±25V
T_{OUT} (Note 3)..±15V
R_{OUT} ....-0.3V to (V_{CC} + 0.3V)
Short Circuit (one output at a time)
T_{OUT} to GND ....Continuous
R_{OUT} to GND...Continuous

Continuous Power Dissipation (T_A = +70°C)
28-Pin Wide SO (derate 12.50mW/°C above +70°C) 1W
40-Pin Plastic DIP (derate 11.11mW/°C above +70°C) ...611mW
44-Pin PLCC (derate 13.33mW/°C above +70°C) 1.07W
Operating Temperature Ranges
MAX225C_ _, MAX24_C_ _ ....0°C to +70°C
MAX225E_ _, MAX24_E_ _ ....-40°C to +85°C
Storage Temperature Range ....-65°C to +160°C
Lead Temperature (soldering,10s) ....+300°C

Note 4: Input voltage measured with transmitter output in a high-impedance state, shutdown, or V_{CC} = 0V.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS—MAX225/MAX244–MAX249

(MAX225, V_{CC} = 5.0V ±5%; MAX244–MAX249, V_{CC} = +5.0V ±10%, external capacitors C1–C4 = 1µF; T_A = T_{MIN} to T_{MAX}; unless otherwise noted.)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
RS-232 TRANSMITTERS						
Input Logic Threshold Low				1.4	0.8	V
Input Logic Threshold High			2	1.4		V
Logic Pull-Up/Input Current	Tables 1a–1d	Normal operation		10	50	µA
		Shutdown		±0.01	±1	
Data Rate	Tables 1a–1d, normal operation			120	64	kbps
Output Voltage Swing	All transmitter outputs loaded with 3kΩ to GND		±5	±7.5		V
Output Leakage Current (Shutdown)	Tables 1a–1d	$\overline{ENA}$, $\overline{ENB}$, $\overline{ENT}$, $\overline{ENTA}$, $\overline{ENTB}$ = V_{CC}, V_{OUT} = ±15V		±0.01	±25	µA
		V_{CC} = 0V, V_{OUT} = ±15V		±0.01	±25	
Transmitter Output Resistance	V_{CC} = V+ = V- = 0V, V_{OUT} = ±2V (Note 4)		300	10M		Ω
Output Short-Circuit Current	V_{OUT} = 0V		±7	±30		mA
RS-232 RECEIVERS						
RS-232 Input Voltage Operating Range					±25	V
RS-232 Input Threshold Low	V_{CC} = 5V		0.8	1.3		V
RS-232 Input Threshold High	V_{CC} = 5V			1.8	2.4	V
RS-232 Input Hysteresis	V_{CC} = 5V		0.2	0.5	1.0	V
RS-232 Input Resistance			3	5	7	kΩ
TTL/CMOS Output Voltage Low	I_{OUT} = 3.2mA			0.2	0.4	V
TTL/CMOS Output Voltage High	I_{OUT} = -1.0mA		3.5	V_{CC} - 0.2		V
TTL/CMOS Output Short-Circuit Current	Sourcing V_{OUT} = GND		-2	-10		mA
	Shrinking V_{OUT} = V_{CC}		10	30		
TTL/CMOS Output Leakage Current	Normal operation, outputs disabled, Tables 1a–1d, 0V ≤ V_{OUT} ≤ V_{CC}, $\overline{ENR\_}$ = V_{CC}			±0.05	±0.10	µA

ELECTRICAL CHARACTERISTICS—MAX225/MAX244–MAX249 (continued)

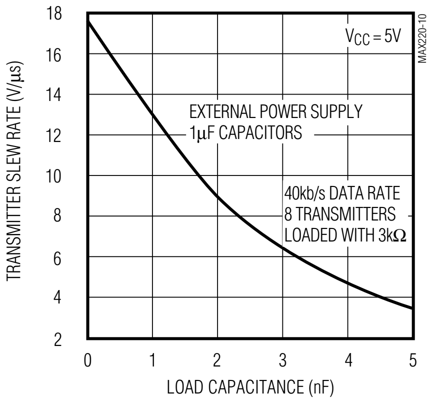
(MAX225, V_{CC} = 5.0V ±5%; MAX244–MAX249, V_{CC} = +5.0V ±10%, external capacitors C1–C4 = 1µF; T_A = T_{MIN} to T_{MAX}; unless otherwise noted.)

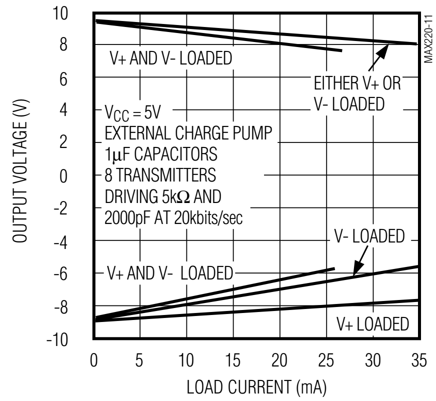
PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
POWER SUPPLY AND CONTROL LOGIC						
Operating Supply Voltage		MAX225	4.75		5.25	V
		MAX244–MAX249	4.5		5.5	
V_{CC} Supply Current (Normal Operation)	No load	MAX225		10	20	mA
		MAX244–MAX249		11	30	
	3kΩ loads on all outputs	MAX225		40		
		MAX244–MAX249		57		
Shutdown Supply Current	T_A = +25°C			8	25	µA
	T_A = T_{MIN} to T_{MAX}				50	
Control Input	Leakage current				±1	µA
	Threshold low			1.4	0.8	V
	Threshold high		2.4	1.4		
AC CHARACTERISTICS						
Transition Slew Rate	C_L = 50pF to 2500pF, R_L = 3kΩ to 7kΩ, V_{CC} = 5V, T_A = +25°C, measured from +3V to -3V or -3V to +3V		5	10	30	V/µs
Transmitter Propagation Delay TLL to RS-232 (Normal Operation), Figure 1	t_{PHLT}			1.3	3.5	µs
	t_{PLHT}			1.5	3.5	
Receiver Propagation Delay TLL to RS-232 (Normal Operation), Figure 2	t_{PHLR}			0.6	1.5	µs
	t_{PLHR}			0.6	1.5	
Receiver Propagation Delay TLL to RS-232 (Low-Power Mode), Figure 2	t_{PHLS}			0.6	10	µs
	t_{PLHS}			3.0	10	
Transmitter + to - Propagation Delay Difference (Normal Operation)	t_{PHLT} - t_{PLHT}			350		ns
Receiver + to - Propagation Delay Difference (Normal Operation)	t_{PHLR} - t_{PLHR}			350		ns
Receiver-Output Enable Time, Figure 3	t_{ER}			100	500	ns
Receiver-Output Disable Time, Figure 3	t_{DR}			100	500	ns
Transmitter Enable Time	t_{ET}	MAX246–MAX249 (excludes charge-pump startup)		5		µs
		MAX225/MAX245–MAX249 (includes charge-pump startup)		10		ms
Transmitter Disable Time, Figure 4	t_{DT}			100		ns

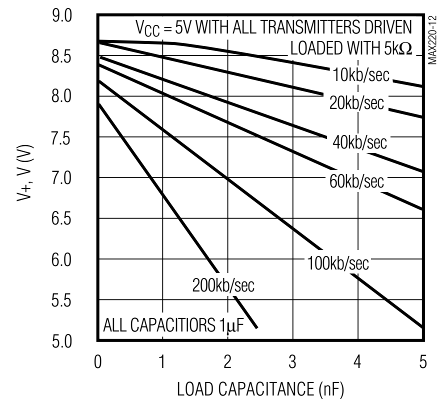
Note 5: The 300Ω minimum specification complies with EIA/TIA-232E, but the actual resistance when in shutdown mode or V_{CC} = 0V is 10MΩ as is implied by the leakage specification.

Typical Operating Characteristics

MAX225/MAX244–MAX249







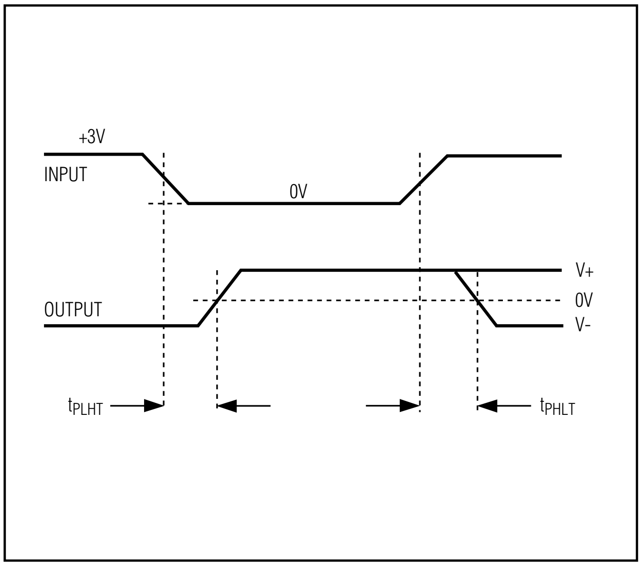


Figure 1. Transmitter Propagation-Delay Timing

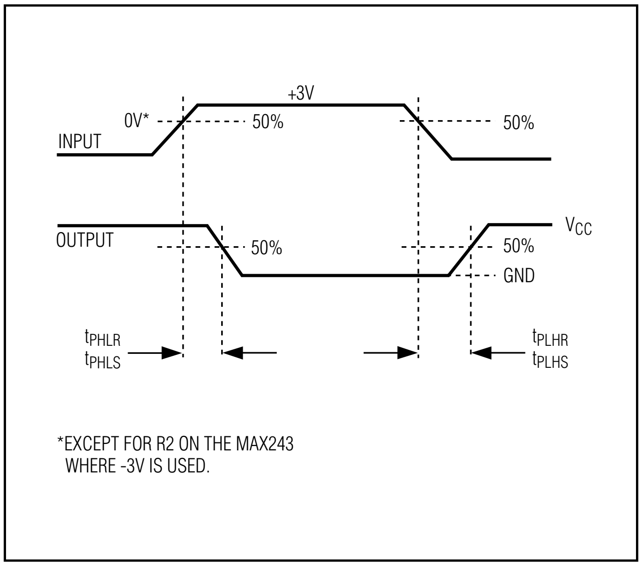


Figure 2. Receiver Propagation-Delay Timing

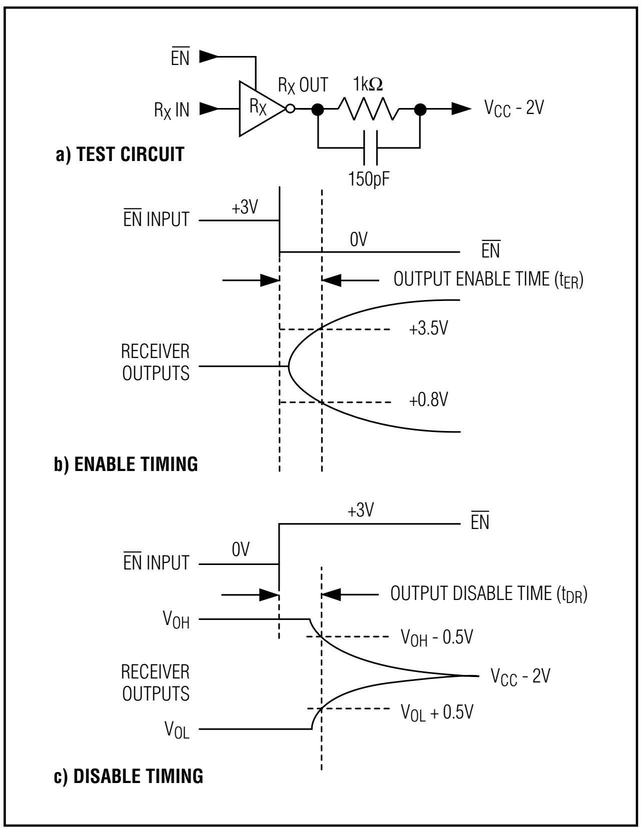


Figure 3. Receiver-Output Enable and Disable Timing

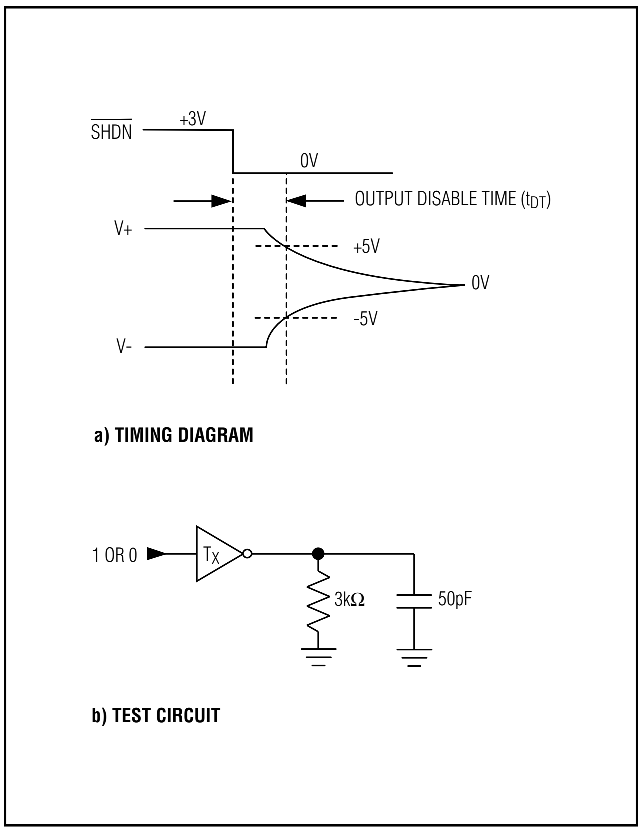


Figure 4. Transmitter-Output Disable Timing

Table 1a. MAX245 Control Pin Configurations

$\overline{ENT}$	$\overline{ENR}$	OPERATION STATUS	TRANSMITTERS	RECEIVERS
0	0	Normal Operation	All Active	All Active
0	1	Normal Operation	All Active	All 3-State
1	0	Shutdown	All 3-State	All Low-Power Receive Mode
1	1	Shutdown	All 3-State	All 3-State

Table 1b. MAX245 Control Pin Configurations

$\overline{ENT}$	$\overline{ENR}$	OPERATION STATUS	TRANSMITTERS		RECEIVERS	
			TA1–TA4	TB1–TB4	RA1–RA5	RB1–RB5
0	0	Normal Operation	All Active	All Active	All Active	All Active
0	1	Normal Operation	All Active	All Active	RA1–RA4 3-State, RA5 Active	RB1–RB4 3-State, RB5 Active
1	0	Shutdown	All 3-State	All 3-State	All Low-Power Receive Mode	All Low-Power Receive Mode
1	1	Shutdown	All 3-State	All 3-State	RA1–RA4 3-State, RA5 Low-Power Receive Mode	RB1–RB4 3-State, RB5 Low-Power Receive Mode

Table 1c. MAX246 Control Pin Configurations

$\overline{ENA}$	$\overline{ENB}$	OPERATION STATUS	TRANSMITTERS		RECEIVERS	
			TA1–TA4	TB1–TB4	RA1–RA5	RB1–RB5
0	0	Normal Operation	All Active	All Active	All Active	All Active
0	1	Normal Operation	All Active	All 3-State	All Active	RB1–RB4 3-State, RB5 Active
1	0	Shutdown	All 3-State	All Active	RA1–RA4 3-State, RA5 Active	All Active
1	1	Shutdown	All 3-State	All 3-State	RA1–RA4 3-State, RA5 Low-Power Receive Mode	RB1–RB4 3-State, RA5 Low-Power Receive Mode

Table 1d. MAX247/MAX248/MAX249 Control Pin Configurations

$\overline{ENTA}$	$\overline{ENTB}$	$\overline{ENRA}$	$\overline{ENRB}$	OPERATION STATUS		TRANSMITTERS		RECEIVERS	
					MAX247	TA1–TA4	TB1–TB4	RA1–RA4	RB1–RB5
					MAX248	TA1–TA4	TB1–TB4	RA1–RA4	RB1–RB4
					MAX249	TA1–TA3	TB1–TB3	RA1–RA5	RB1–RB5
0	0	0	0	Normal Operation		All Active	All Active	All Active	All Active
0	0	0	1	Normal Operation		All Active	All Active	All Active	All 3-State, except RB5 stays active on MAX247
0	0	1	0	Normal Operation		All Active	All Active	All 3-State	All Active
0	0	1	1	Normal Operation		All Active	All Active	All 3-State	All 3-State, except RB5 stays active on MAX247
0	1	0	0	Normal Operation		All Active	All 3-State	All Active	All Active
0	1	0	1	Normal Operation		All Active	All 3-State	All Active	All 3-State, except RB5 stays active on MAX247
0	1	1	0	Normal Operation		All Active	All 3-State	All 3-State	All Active
0	1	1	1	Normal Operation		All Active	All 3-State	All 3-State	All 3-State, except RB5 stays active on MAX247
1	0	0	0	Normal Operation		All 3-State	All Active	All Active	All Active
1	0	0	1	Normal Operation		All 3-State	All Active	All Active	All 3-State, except RB5 stays active on MAX247
1	0	1	0	Normal Operation		All 3-State	All Active	All 3-State	All Active
1	0	1	1	Normal Operation		All 3-State	All Active	All 3-State	All 3-State, except RB5 stays active on MAX247
1	1	0	0	Shutdown		All 3-State	All 3-State	Low-Power Receive Mode	Low-Power Receive Mode
1	1	0	1	Shutdown		All 3-State	All 3-State	Low-Power Receive Mode	All 3-State, except RB5 stays active on MAX247
1	1	1	0	Shutdown		All 3-State	All 3-State	All 3-State	Low-Power Receive Mode
1	1	1	1	Shutdown		All 3-State	All 3-State	All 3-State	All 3-State, except RB5 stays active on MAX247

+5V-Powered, Multichannel RS-232 Drivers/Receivers

Detailed Description

The MAX220–MAX249 contain four sections: dual charge-pump DC-DC voltage converters, RS-232 drivers, RS-232 receivers, and receiver and transmitter enable control inputs.

Dual Charge-Pump Voltage Converter

The MAX220–MAX249 have two internal charge-pumps that convert +5V to ±10V (unloaded) for RS-232 driver operation. The first converter uses capacitor C1 to double the +5V input to +10V on C3 at the V+ output. The second converter uses capacitor C2 to invert +10V to -10V on C4 at the V- output.

A small amount of power may be drawn from the +10V (V+) and -10V (V-) outputs to power external circuitry (see the *Typical Operating Characteristics* section), except on the MAX225 and MAX245–MAX247, where these pins are not available. V+ and V- are not regulated, so the output voltage drops with increasing load current. Do not load V+ and V- to a point that violates the minimum ±5V EIA/TIA-232E driver output voltage when sourcing current from V+ and V- to external circuitry.

When using the shutdown feature in the MAX222, MAX225, MAX230, MAX235, MAX236, MAX240, MAX241, and MAX245–MAX249, avoid using V+ and V- to power external circuitry. When these parts are shut down, V- falls to 0V, and V+ falls to +5V. For applications where a +10V external supply is applied to the V+ pin (instead of using the internal charge pump to generate +10V), the C1 capacitor must not be installed and the $\overline{SHDN}$ pin must be tied to V_{CC}. This is because V+ is internally connected to V_{CC} in shutdown mode.

RS-232 Drivers

The typical driver output voltage swing is ±8V when loaded with a nominal 5kΩ RS-232 receiver and V_{CC} = +5V. Output swing is guaranteed to meet the EIA/TIA-232E and V.28 specification, which calls for ±5V minimum driver output levels under worst-case conditions. These include a minimum 3kΩ load, V_{CC} = +4.5V, and maximum operating temperature. Unloaded driver output voltage ranges from (V+ -1.3V) to (V- +0.5V).

Input thresholds are both TTL and CMOS compatible. The inputs of unused drivers can be left unconnected since 400kΩ input pull-up resistors to V_{CC} are built in (except for the MAX220). The pull-up resistors force the outputs of unused drivers low because all drivers invert. The internal input pull-up resistors typically source 12µA, except in shutdown mode where the pull-ups are disabled. Driver outputs turn off and enter a high-impedance state—where leakage current is typically microamperes (maximum 25µA)—when in shutdown mode, in three-state mode, or when device power is removed. Outputs can be driven to ±15V. The power-supply current typically drops to 8µA in shutdown mode. The MAX220 does not have pull-up resistors to force the outputs of the unused drivers low. Connect unused inputs to GND or V_{CC}.

The MAX239 has a receiver three-state control line, and the MAX223, MAX225, MAX235, MAX236, MAX240, and MAX241 have both a receiver three-state control line and a low-power shutdown control. Table 2 shows the effects of the shutdown control and receiver three-state control on the receiver outputs.

The receiver TTL/CMOS outputs are in a high-impedance, three-state mode whenever the three-state enable line is high (for the MAX225/MAX235/MAX236/MAX239–MAX241), and are also high-impedance whenever the shutdown control line is high.

When in low-power shutdown mode, the driver outputs are turned off and their leakage current is less than 1µA with the driver output pulled to ground. The driver output leakage remains less than 1µA, even if the transmitter output is backdriven between 0V and (V_{CC} + 6V). Below -0.5V, the transmitter is diode clamped to ground with 1kΩ series impedance. The transmitter is also zener clamped to approximately V_{CC} + 6V, with a series impedance of 1kΩ.

The driver output slew rate is limited to less than 30V/µs as required by the EIA/TIA-232E and V.28 specifications. Typical slew rates are 24V/µs unloaded and 10V/µs loaded with 3Ω and 2500pF.

RS-232 Receivers

EIA/TIA-232E and V.28 specifications define a voltage level greater than 3V as a logic 0, so all receivers invert. Input thresholds are set at 0.8V and 2.4V, so receivers respond to TTL level inputs as well as EIA/TIA-232E and V.28 levels.

The receiver inputs withstand an input overvoltage up to ±25V and provide input terminating resistors with

Table 2. Three-State Control of Receivers

PART	SHDN	$\overline{SHDN}$	EN	$\overline{EN(R)}$	RECEIVERS
MAX223	—	Low High High	X Low High	—	High Impedance Active High Impedance
MAX225	—	—	—	Low High	High Impedance Active
MAX235 MAX236 MAX240	Low Low High	—	—	Low High X	High Impedance Active High Impedance

nominal 5kΩ values. The receivers implement Type 1 interpretation of the fault conditions of V.28 and EIA/TIA-232E.

The receiver input hysteresis is typically 0.5V with a guaranteed minimum of 0.2V. This produces clear output transitions with slow-moving input signals, even with moderate amounts of noise and ringing. The receiver propagation delay is typically 600ns and is independent of input swing direction.

Low-Power Receive Mode

The low-power receive-mode feature of the MAX223, MAX242, and MAX245–MAX249 puts the IC into shutdown mode but still allows it to receive information. This is important for applications where systems are periodically awakened to look for activity. Using low-power receive mode, the system can still receive a signal that will activate it on command and prepare it for communication at faster data rates. This operation conserves system power.

Negative Threshold—MAX243

The MAX243 is pin compatible with the MAX232A, differing only in that RS-232 cable fault protection is removed on one of the two receiver inputs. This means that control lines such as CTS and RTS can either be driven or left floating without interrupting communication. Different cables are not needed to interface with different pieces of equipment.

The input threshold of the receiver without cable fault protection is -0.8V rather than +1.4V. Its output goes positive only if the input is connected to a control line that is actively driven negative. If not driven, it defaults to the 0 or “OK to send” state. Normally, the MAX243’s other receiver (+1.4V threshold) is used for the data line (TD or RD), while the negative threshold receiver is connected to the control line (DTR, DTS, CTS, RTS, etc.).

Other members of the RS-232 family implement the optional cable fault protection as specified by EIA/TIA-232E specifications. This means a receiver output goes high whenever its input is driven negative, left floating, or shorted to ground. The high output tells the serial communications IC to stop sending data. To avoid this, the control lines must either be driven or connected with jumpers to an appropriate positive voltage level.

Shutdown—MAX222–MAX242

On the MAX222, MAX235, MAX236, MAX240, and MAX241, all receivers are disabled during shutdown. On the MAX223 and MAX242, two receivers continue to operate in a reduced power mode when the chip is in shutdown. Under these conditions, the propagation delay increases to about 2.5μs for a high-to-low input transition. When in shutdown, the receiver acts as a CMOS inverter with no hysteresis. The MAX223 and MAX242 also have a receiver output enable input ($\overline{EN}$ for the MAX242 and EN for the MAX223) that allows receiver output control independent of $\overline{SHDN}$ (SHDN for MAX241). With all other devices, $\overline{SHDN}$ (SHDN for MAX241) also disables the receiver outputs.

The MAX225 provides five transmitters and five receivers, while the MAX245 provides ten receivers and eight transmitters. Both devices have separate receiver and transmitter-enable controls. The charge pumps turn off and the devices shut down when a logic high is applied to the ENT input. In this state, the supply current drops to less than 25μA and the receivers continue to operate in a low-power receive mode. Driver outputs enter a high-impedance state (three-state mode). On the MAX225, all five receivers are controlled by the $\overline{ENR}$ input. On the MAX245, eight of the receiver outputs are controlled by the $\overline{ENR}$ input, while the remaining two receivers (RA5 and RB5) are always active. RA1–RA4 and RB1–RB4 are put in a three-state mode when $\overline{ENR}$ is a logic high.

Receiver and Transmitter Enable Control Inputs

The MAX225 and MAX245–MAX249 feature transmitter and receiver enable controls.

The receivers have three modes of operation: full-speed receive (normal active), three-state (disabled), and low-power receive (enabled receivers continue to function at lower data rates). The receiver enable inputs control the full-speed receive and three-state modes. The transmitters have two modes of operation: full-speed transmit (normal active) and three-state (disabled). The transmitter enable inputs also control the shutdown mode. The device enters shutdown mode when all transmitters are disabled. Enabled receivers function in the low-power receive mode when in shutdown.

Tables 1a–1d define the control states. The MAX244 has no control pins and is not included in these tables.

The MAX246 has ten receivers and eight drivers with two control pins, each controlling one side of the device. A logic high at the A-side control input ($\overline{\text{ENA}}$) causes the four A-side receivers and drivers to go into a three-state mode. Similarly, the B-side control input ($\overline{\text{ENB}}$) causes the four B-side drivers and receivers to go into a three-state mode. As in the MAX245, one A-side and one B-side receiver (RA5 and RB5) remain active at all times. The entire device is put into shutdown mode when both the A and B sides are disabled ($\overline{\text{ENA}}$ = $\overline{\text{ENB}}$ = +5V).

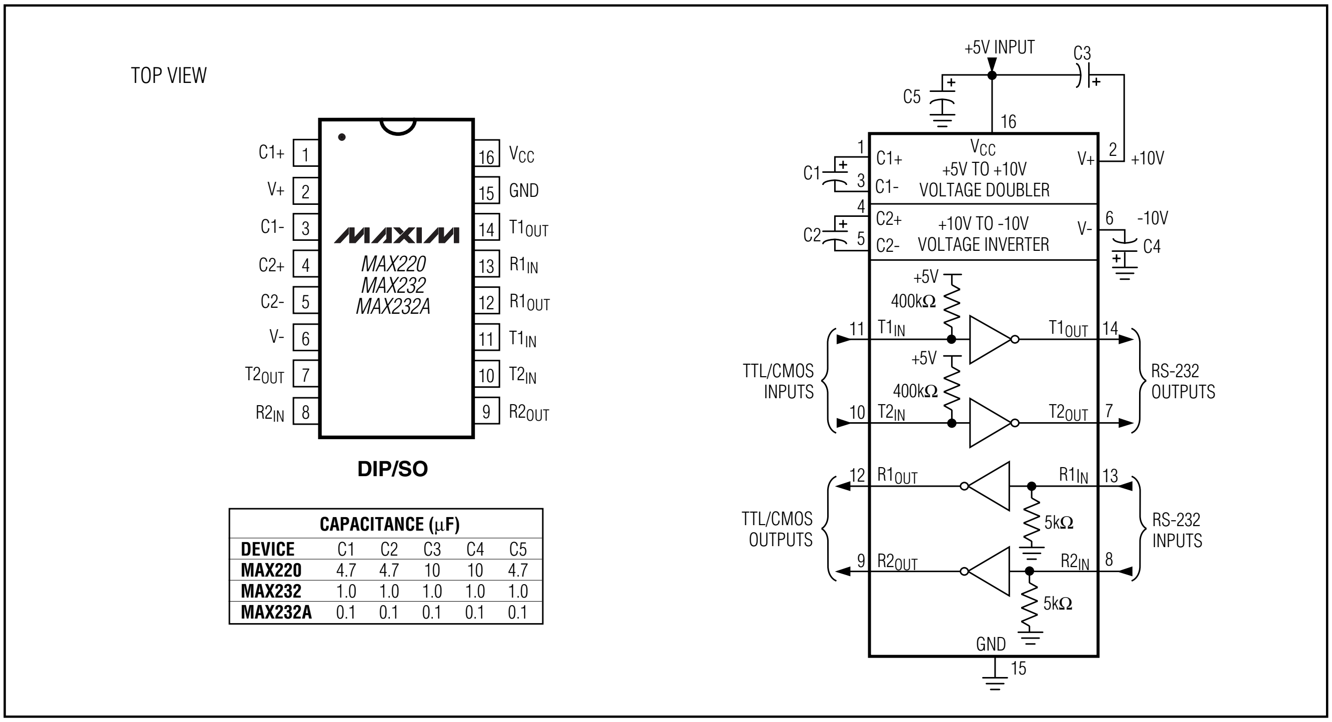
The MAX247 provides nine receivers and eight drivers with four control pins. The $\overline{\text{ENRA}}$ and $\overline{\text{ENRB}}$ receiver enable inputs each control four receiver outputs. The $\overline{\text{ENTA}}$ and $\overline{\text{ENTB}}$ transmitter enable inputs each control four drivers. The ninth receiver (RB5) is always active. The device enters shutdown mode with a logic high on both $\overline{\text{ENTA}}$ and $\overline{\text{ENTB}}$.

The MAX248 provides eight receivers and eight drivers with four control pins. The $\overline{\text{ENRA}}$ and $\overline{\text{ENRB}}$ receiver enable inputs each control four receiver outputs. The $\overline{\text{ENTA}}$ and $\overline{\text{ENTB}}$ transmitter enable inputs control four drivers each. This part does not have an always-active receiver. The device enters shutdown mode and transmitters go into a three-state mode with a logic high on both $\overline{\text{ENTA}}$ and $\overline{\text{ENTB}}$.

The MAX249 provides ten receivers and six drivers with four control pins. The $\overline{\text{ENRA}}$ and $\overline{\text{ENRB}}$ receiver enable inputs each control five receiver outputs. The $\overline{\text{ENTA}}$ and $\overline{\text{ENTB}}$ transmitter enable inputs control three drivers each. There is no always-active receiver. The device enters shutdown mode and transmitters go into a three-state mode with a logic high on both $\overline{\text{ENTA}}$ and $\overline{\text{ENTB}}$. In shutdown mode, active receivers operate in a low-power receive mode at data rates up to 20kbits/sec.

Applications Information

Figures 5 through 25 show pin configurations and typical operating circuits. In applications that are sensitive to power-supply noise, V_{CC} should be decoupled to ground with a capacitor of the same value as C1 and C2 connected as close as possible to the device.



CAPACITANCE (μF)					
DEVICE	C1	C2	C3	C4	C5
MAX220	4.7	4.7	10	10	4.7
MAX232	1.0	1.0	1.0	1.0	1.0
MAX232A	0.1	0.1	0.1	0.1	0.1

Figure 5. MAX220/MAX232/MAX232A Pin Configuration and Typical Operating Circuit

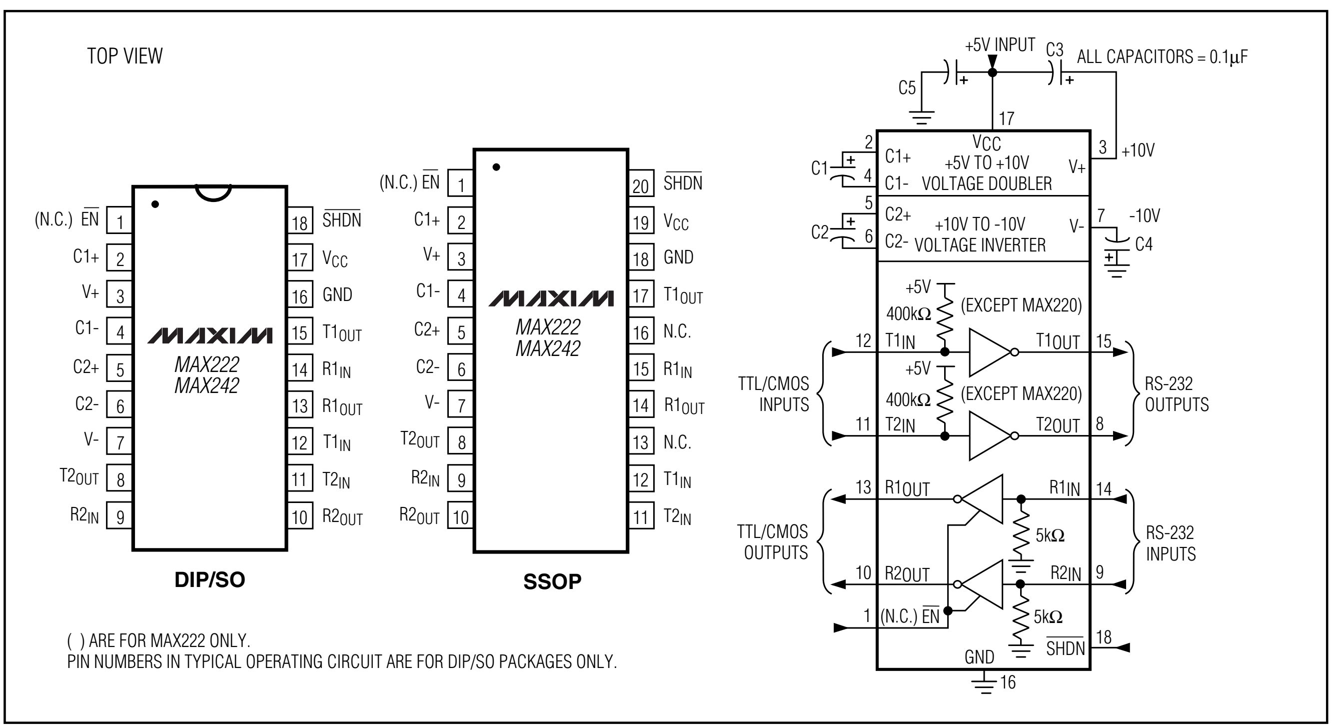
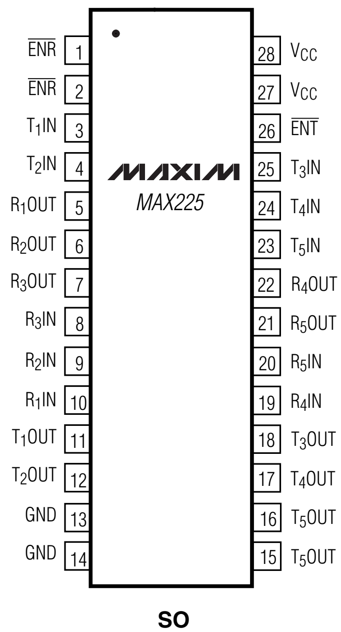
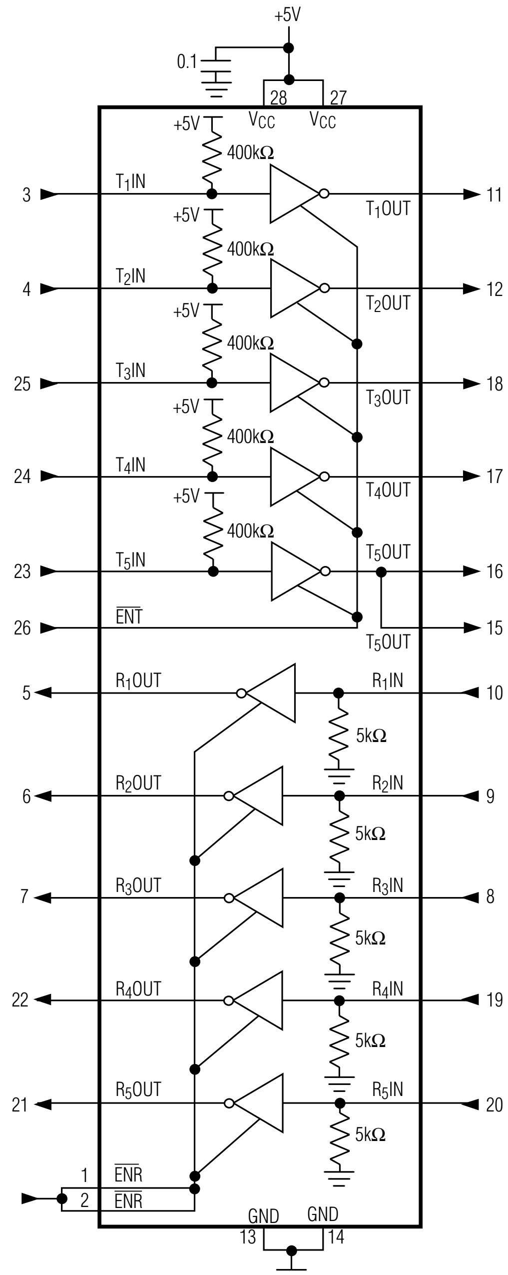


Figure 6. MAX222/MAX242 Pin Configurations and Typical Operating Circuit

+5V-Powered, Multichannel RS-232 Drivers/Receivers

TOP VIEW





MAX225 FUNCTIONAL DESCRIPTION

5 RECEIVERS

5 TRANSMITTERS

2 CONTROL PINS

1 RECEIVER ENABLE ($\overline{ENR}$)

1 TRANSMITTER ENABLE ($\overline{ENT}$)

PINS ($\overline{ENR}$, GND, V_{CC}, T_5OUT) ARE INTERNALLY CONNECTED. CONNECT EITHER OR BOTH EXTERNALLY. T_5OUT IS A SINGLE DRIVER.

Figure 7. MAX225 Pin Configuration and Typical Operating Circuit

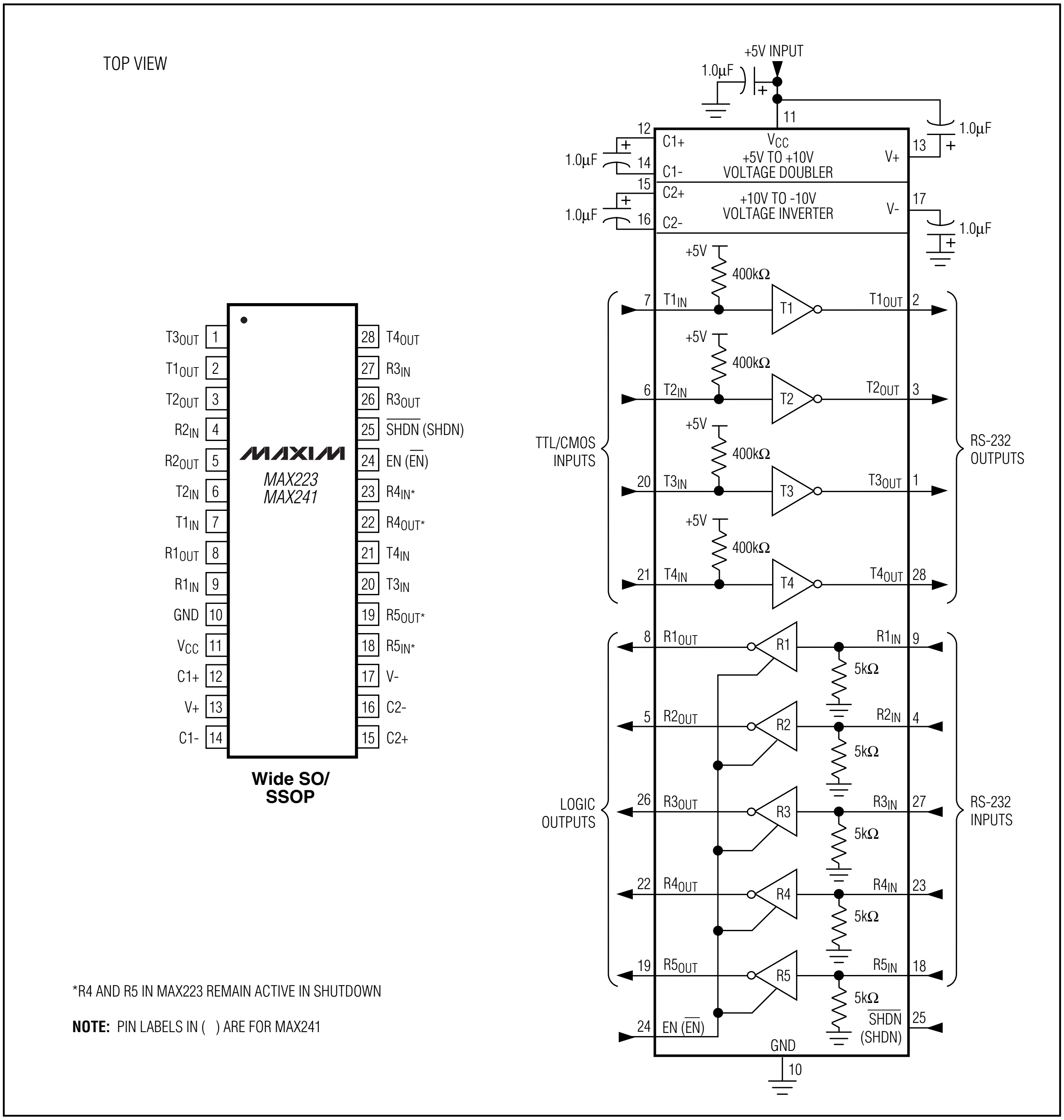


Figure 8. MAX223/MAX241 Pin Configuration and Typical Operating Circuit

+5V-Powered, Multichannel RS-232 Drivers/Receivers

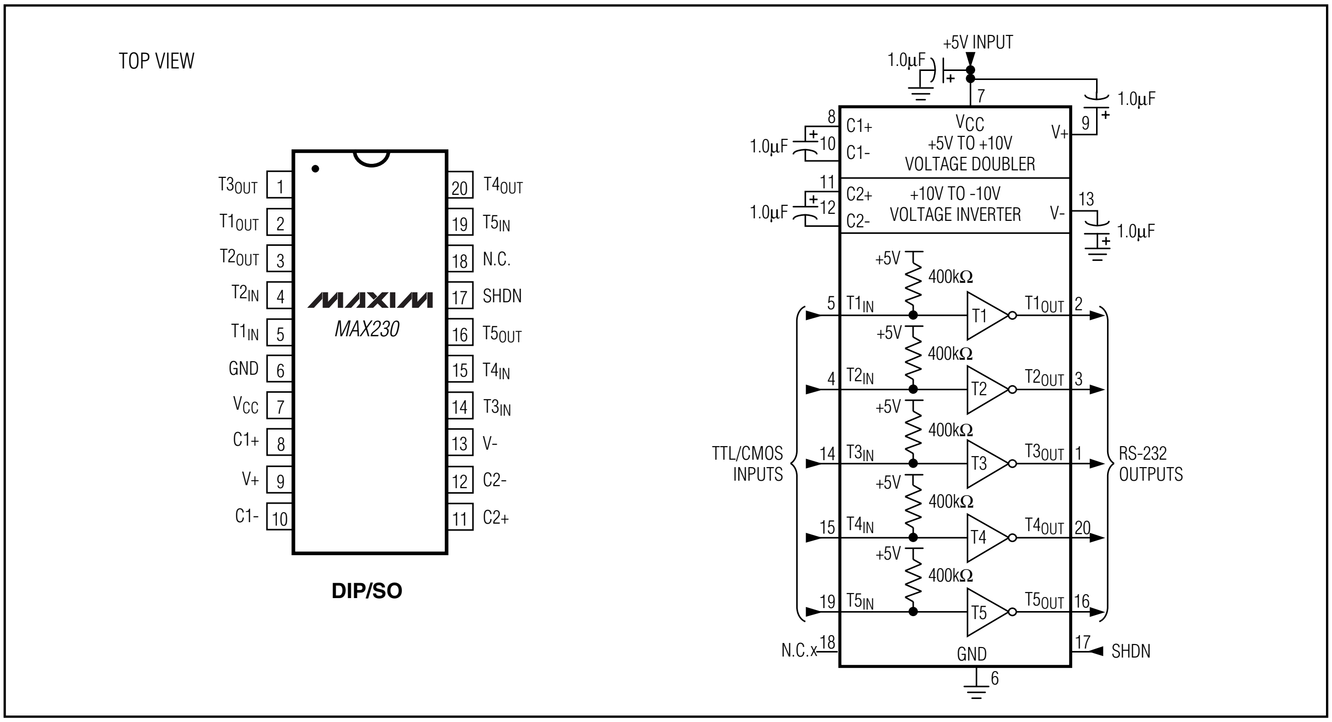


Figure 9. MAX230 Pin Configuration and Typical Operating Circuit

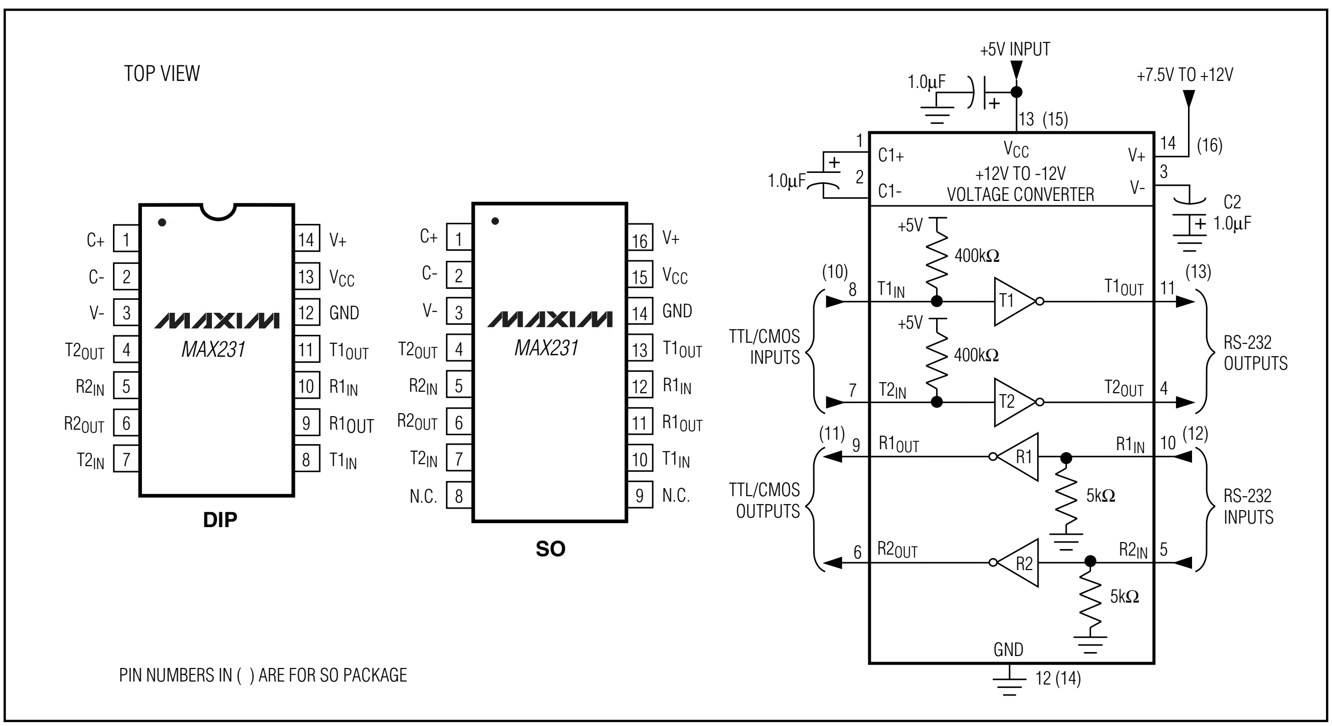


Figure 10. MAX231 Pin Configurations and Typical Operating Circuit

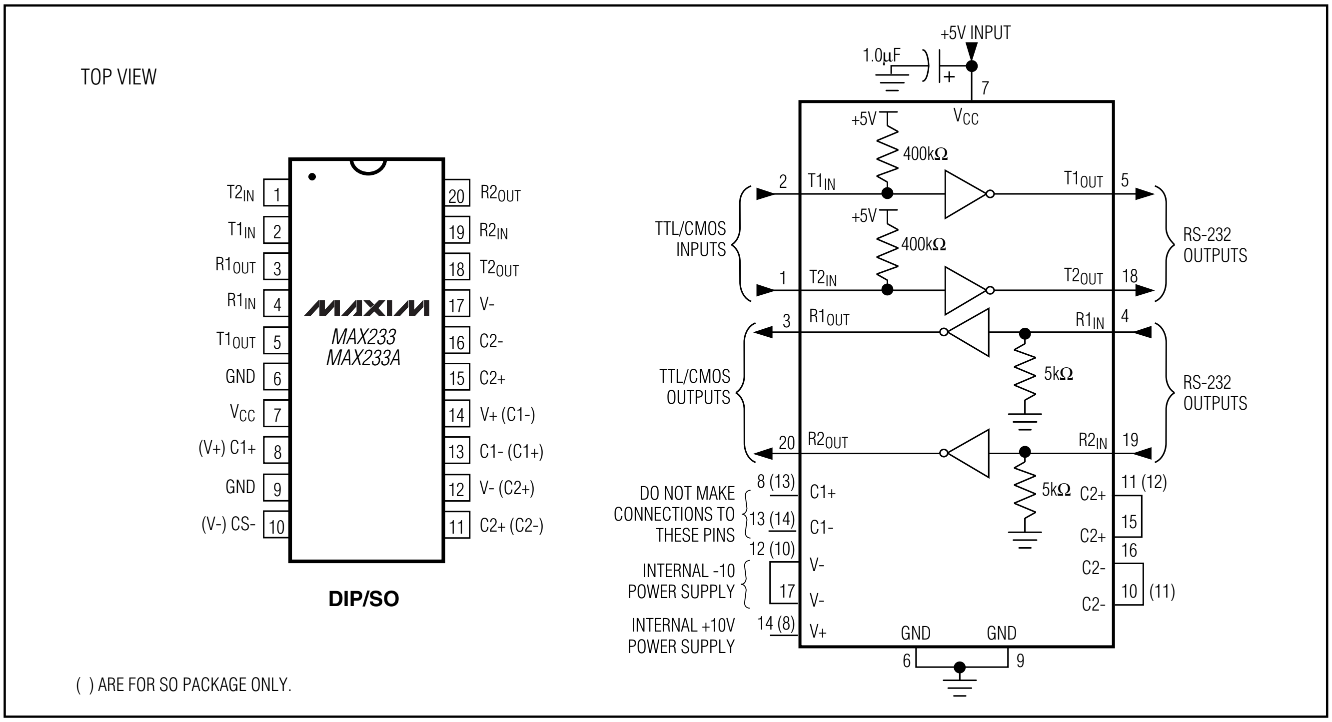


Figure 11. MAX233/MAX233A Pin Configuration and Typical Operating Circuit

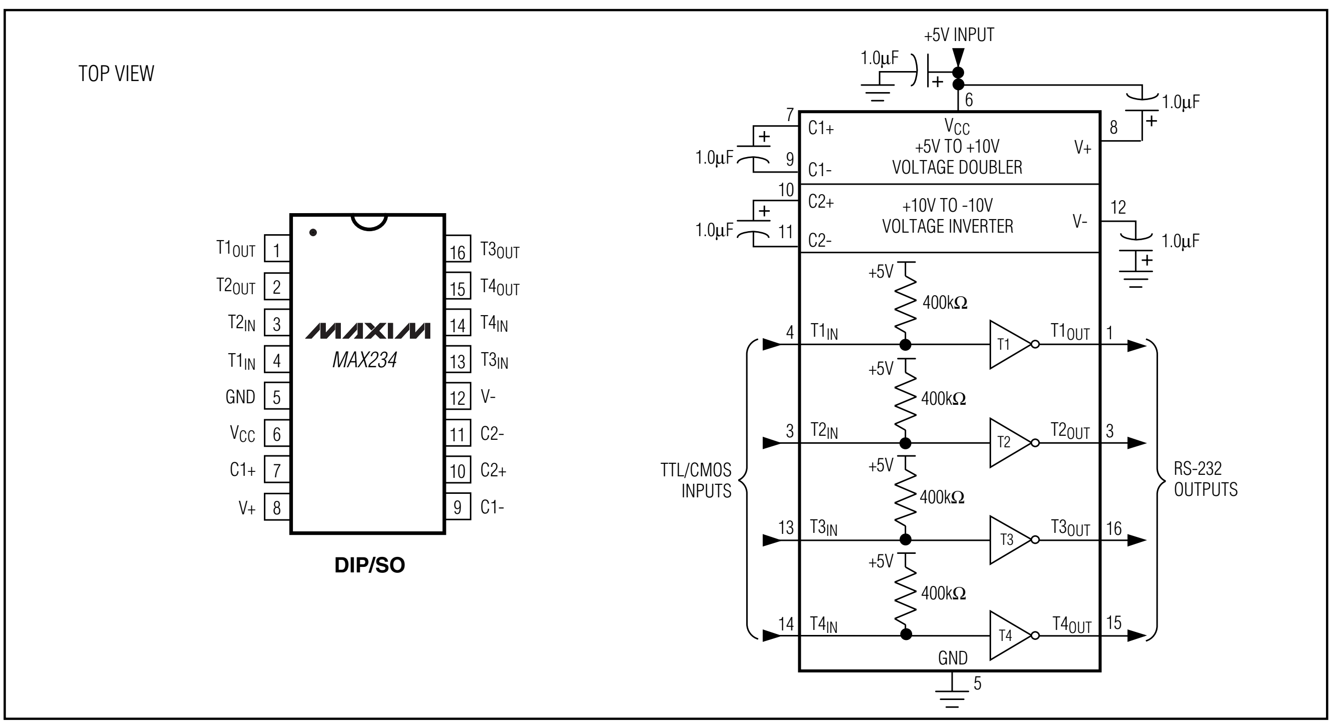


Figure 12. MAX234 Pin Configuration and Typical Operating Circuit

+5V-Powered, Multichannel RS-232 Drivers/Receivers

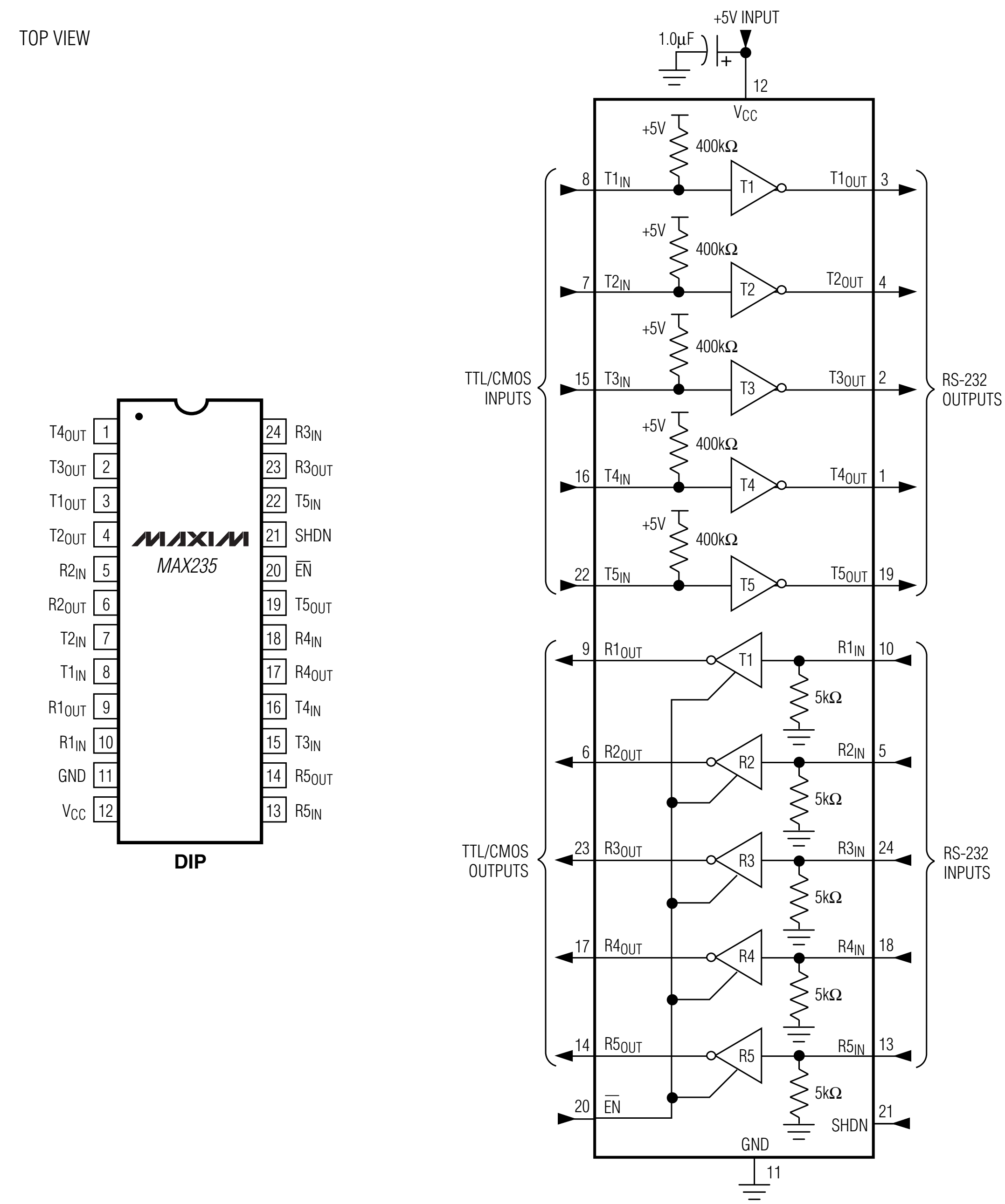


Figure 13. MAX235 Pin Configuration and Typical Operating Circuit

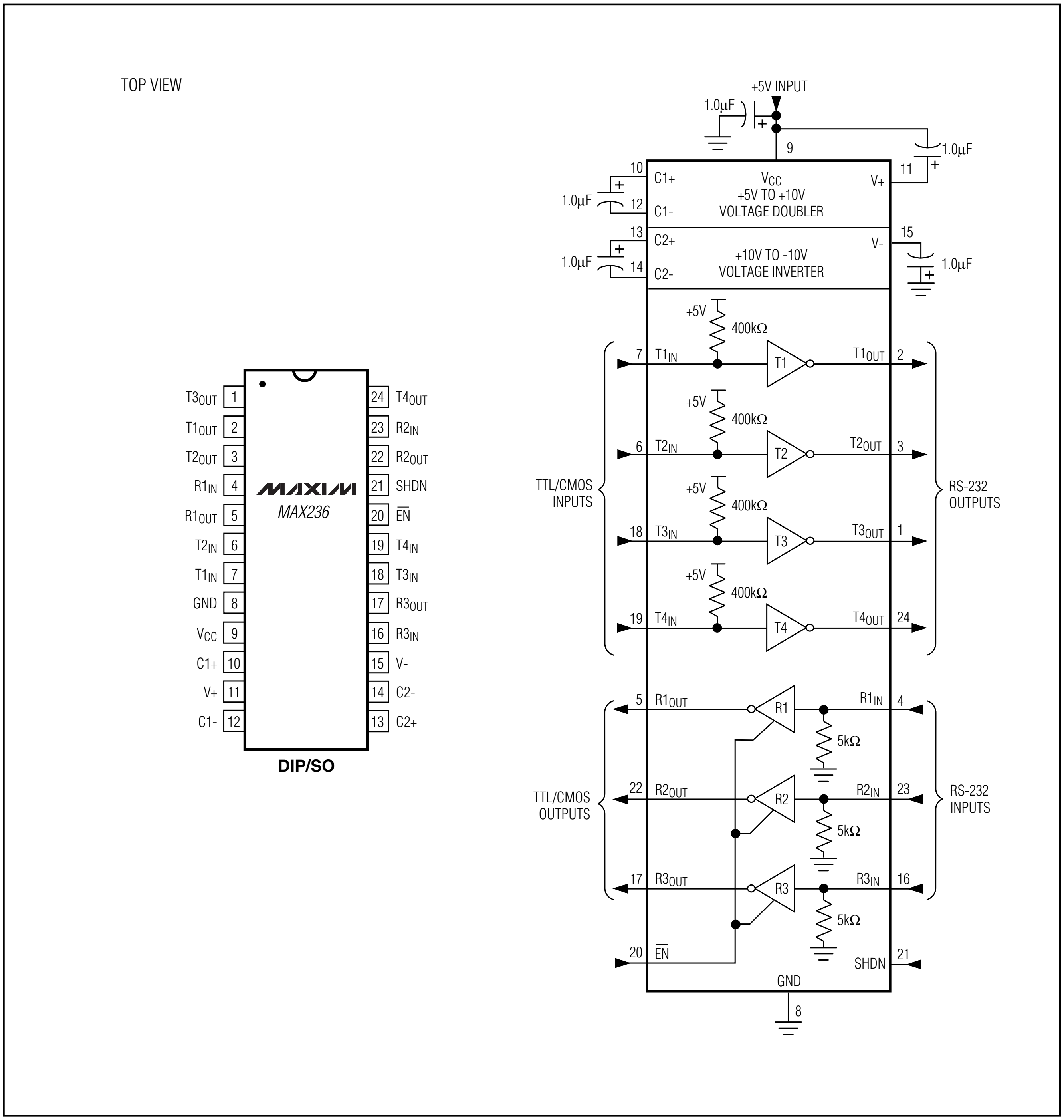


Figure 14. MAX236 Pin Configuration and Typical Operating Circuit

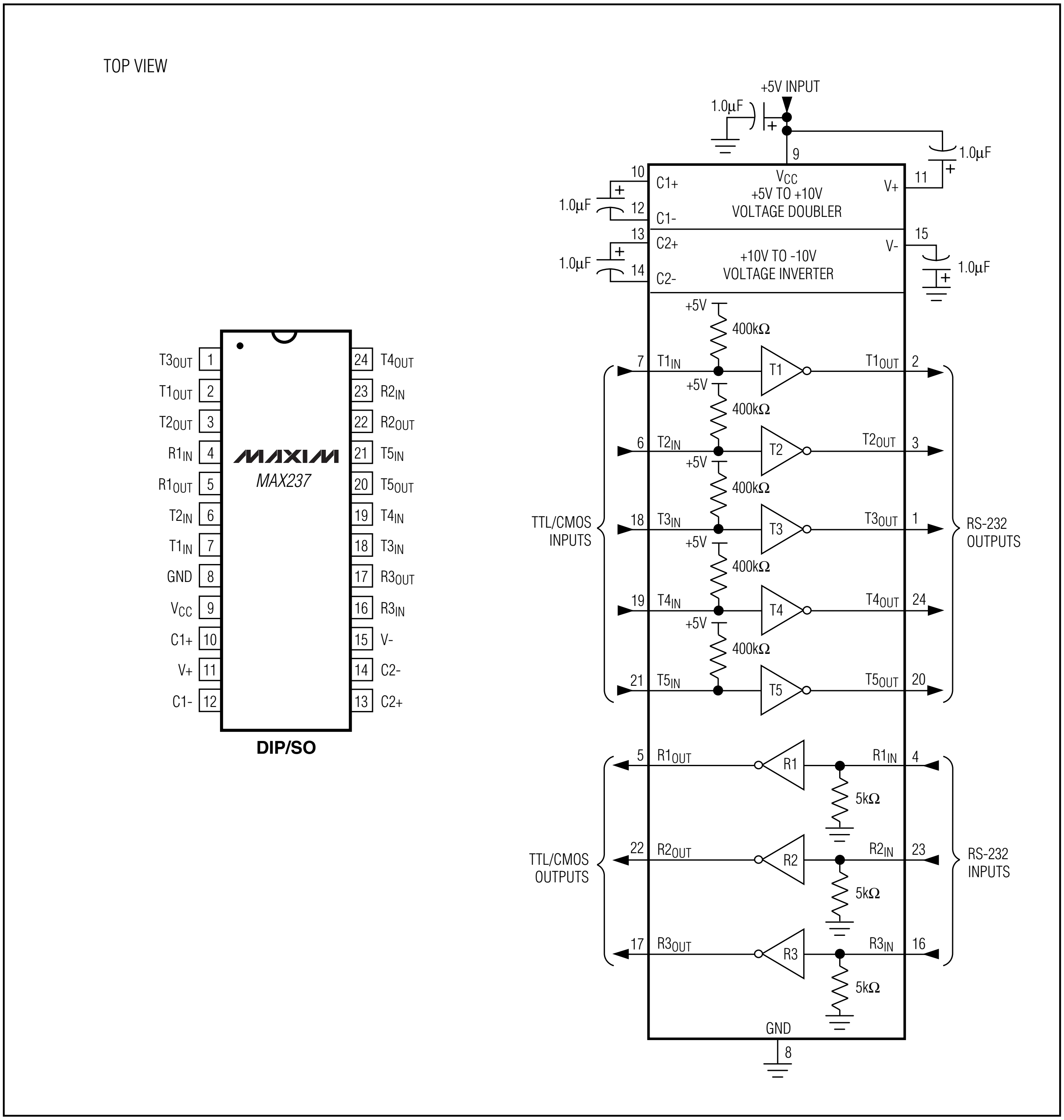


Figure 15. MAX237 Pin Configuration and Typical Operating Circuit

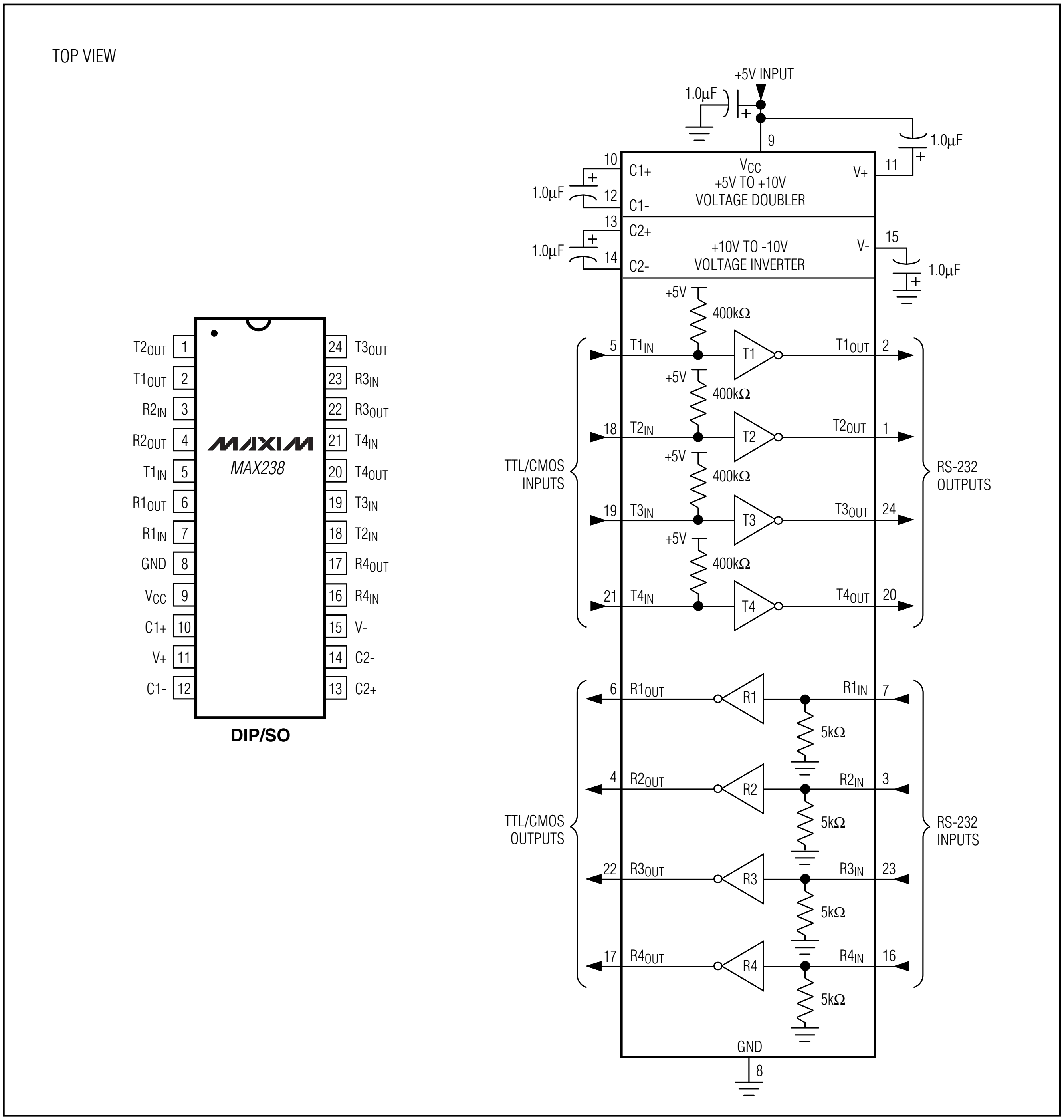


Figure 16. MAX238 Pin Configuration and Typical Operating Circuit

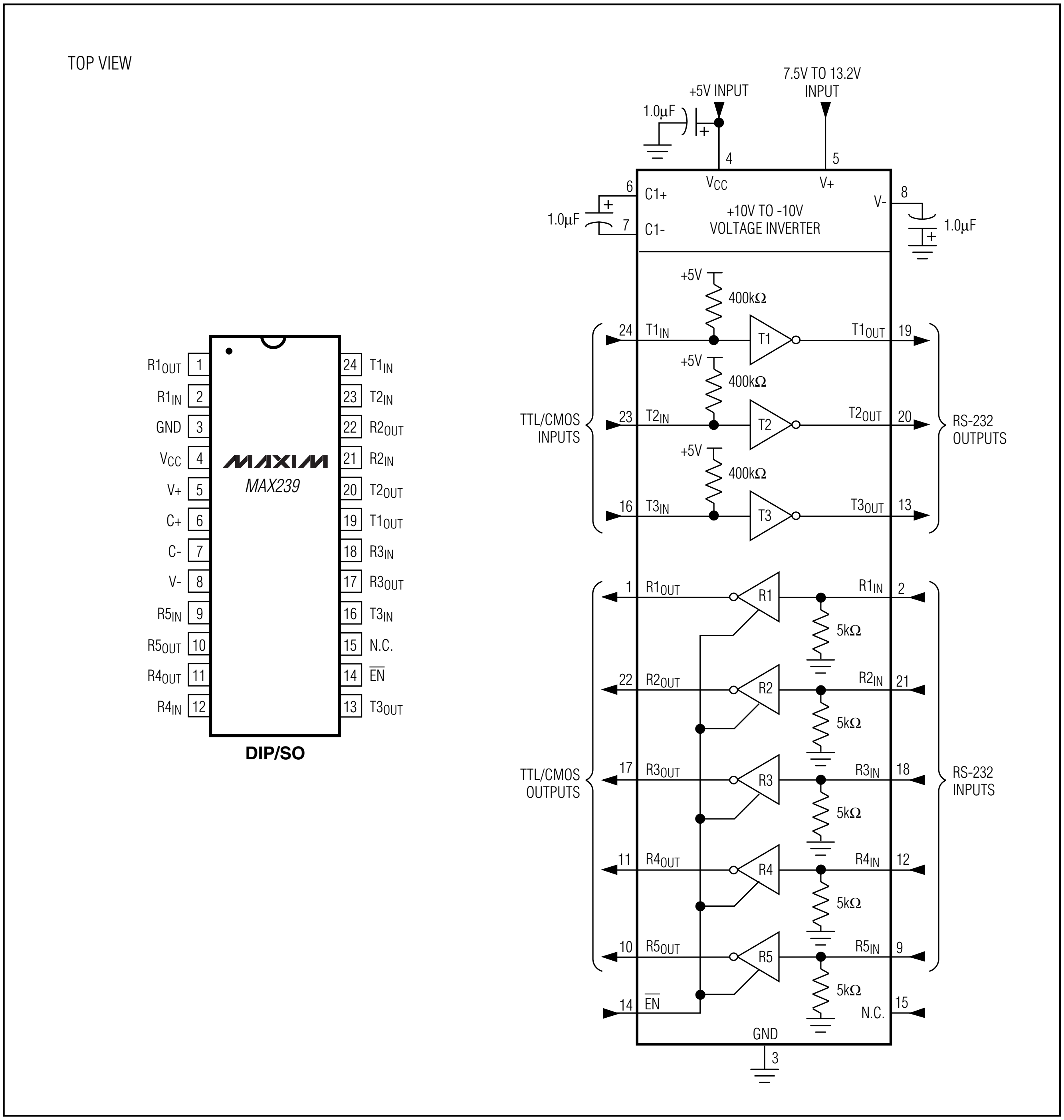


Figure 17. MAX239 Pin Configuration and Typical Operating Circuit

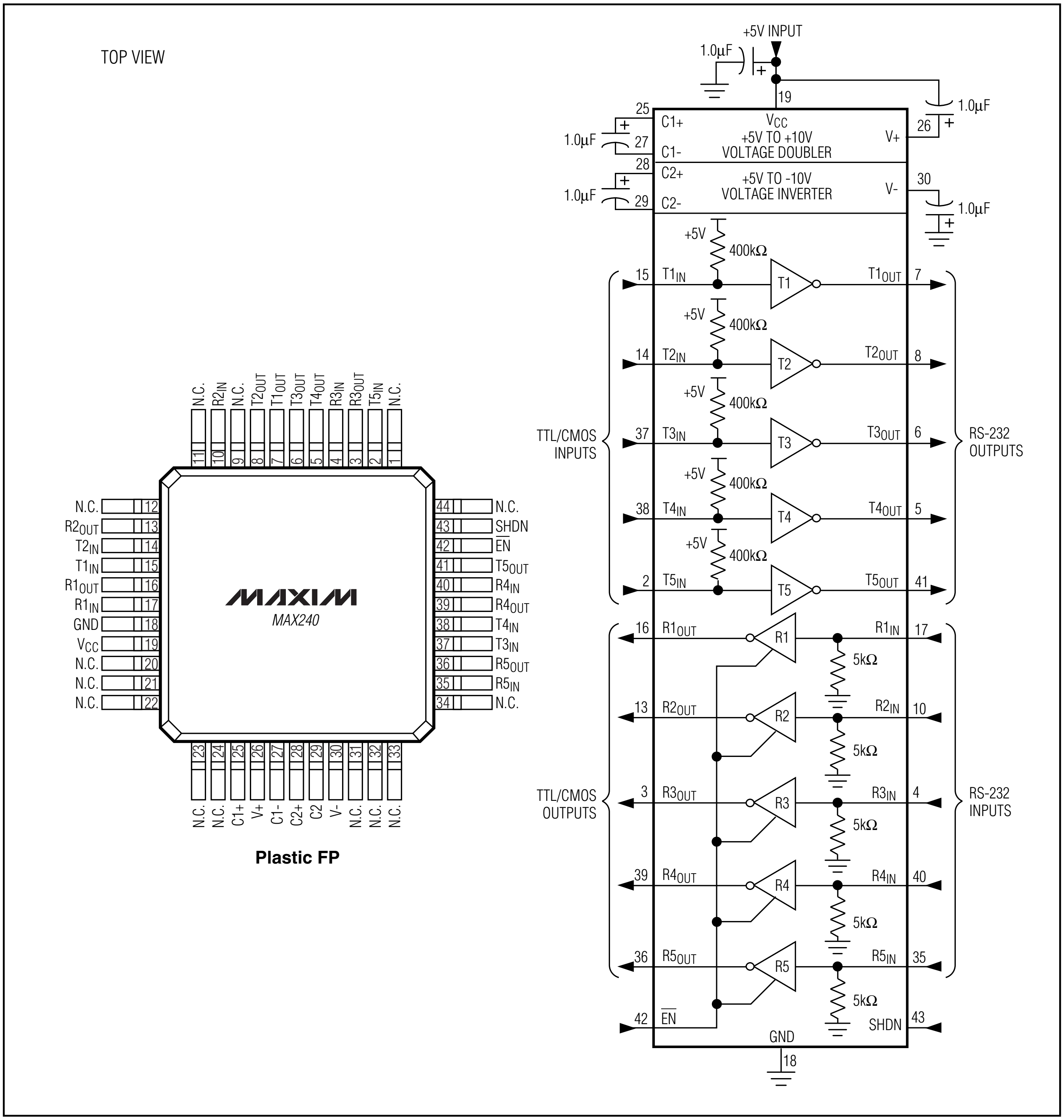
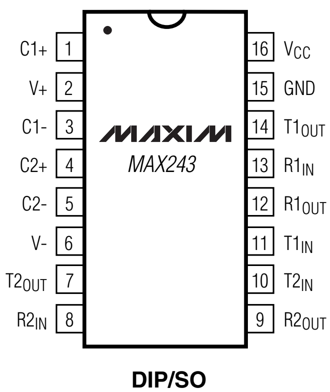
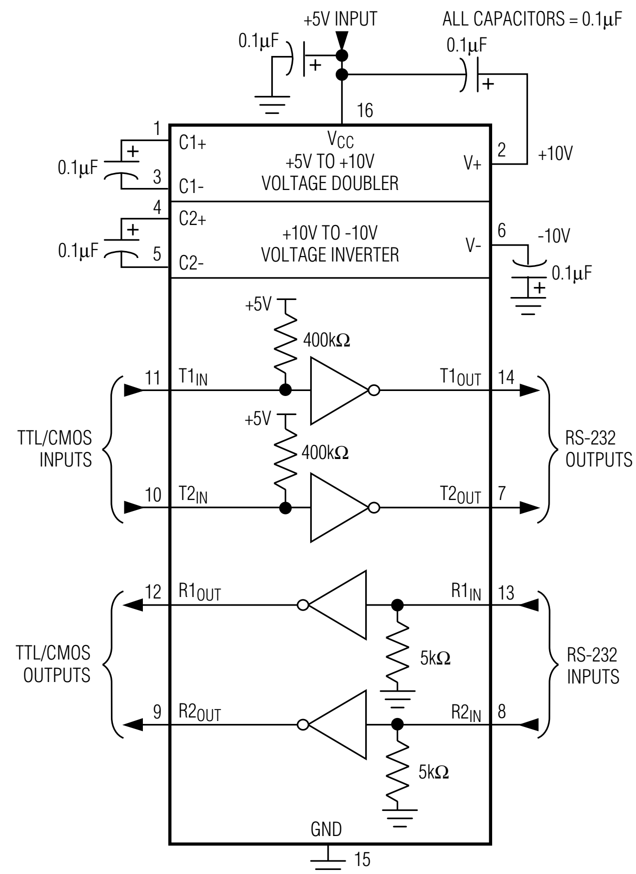


Figure 18. MAX240 Pin Configuration and Typical Operating Circuit

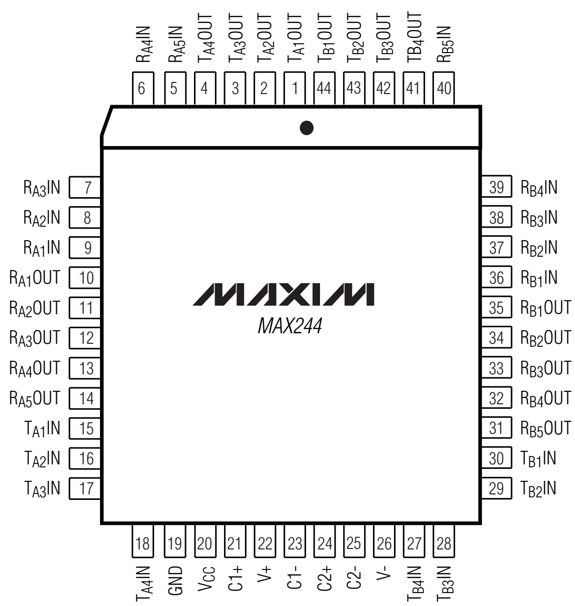




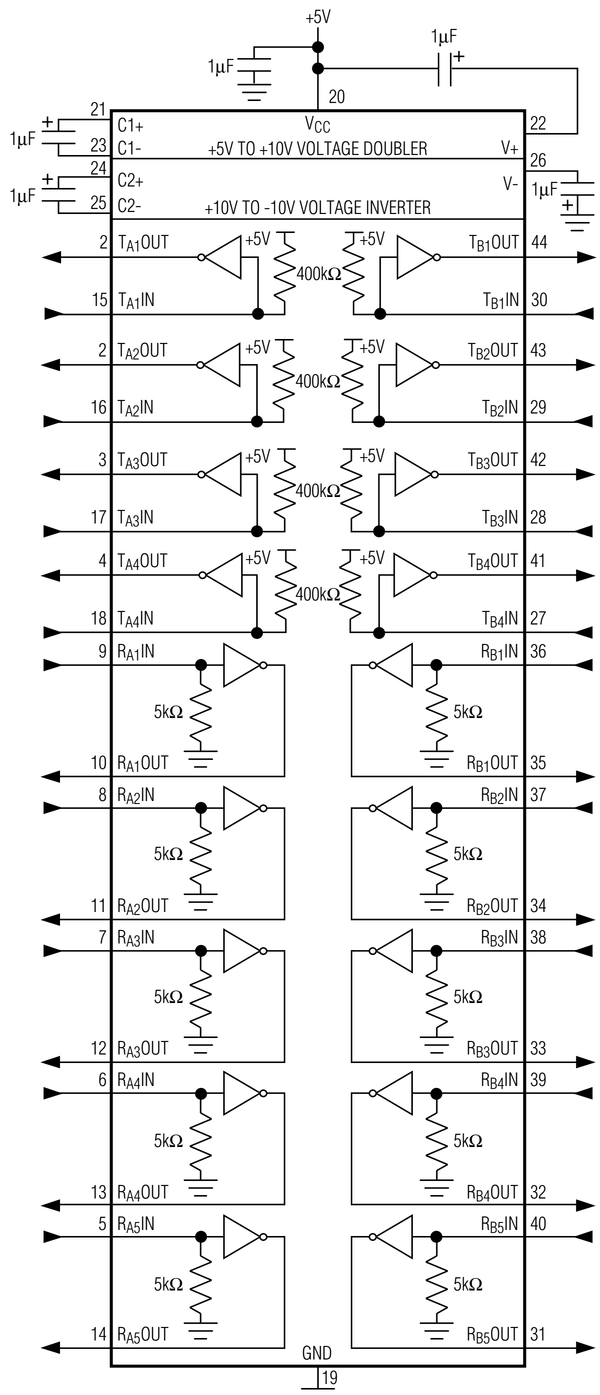
RECEIVER INPUT	R1 OUTPUT	R2 OUTPUT
≤ -3 V	HIGH	HIGH
OPEN	HIGH	LOW
≥ +3V	LOW	LOW

Figure 19. MAX243 Pin Configuration and Typical Operating Circuit

TOP VIEW



PLCC



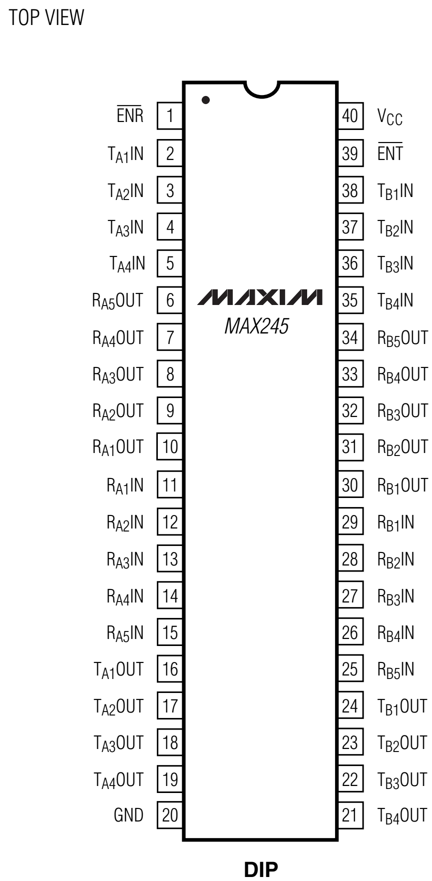
MAX249 FUNCTIONAL DESCRIPTION

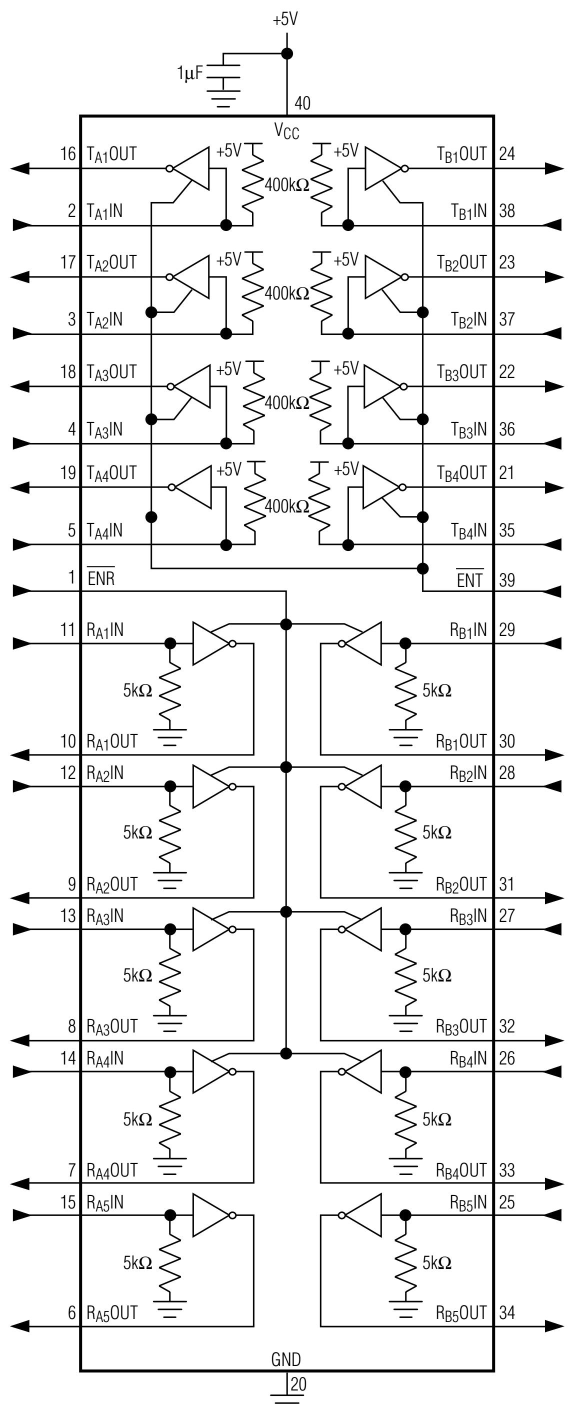
10 RECEIVERS
- 5 A-SIDE RECEIVER
- 5 B-SIDE RECEIVER

8 TRANSMITTERS
- 4 A-SIDE TRANSMITTERS
- 4 B-SIDE TRANSMITTERS

NO CONTROL PINS

Figure 20. MAX244 Pin Configuration and Typical Operating Circuit





MAX245 FUNCTIONAL DESCRIPTION

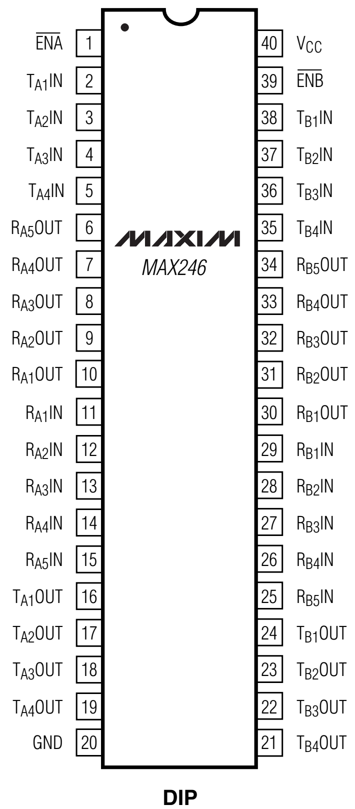
10 RECEIVERS
- 5 A-SIDE RECEIVERS (RA5 ALWAYS ACTIVE)
- 5 B-SIDE RECEIVERS (RB5 ALWAYS ACTIVE)

8 TRANSMITTTERS
- 4 A-SIDE TRANSMITTERS

2 CONTROL PINS
- 1 RECEIVER ENABLE ($\overline{ENR}$)
- 1 TRANSMITTER ENABLE ($\overline{ENT}$)

Figure 21. MAX245 Pin Configuration and Typical Operating Circuit

TOP VIEW



MAX246 FUNCTIONAL DESCRIPTION

10 RECEIVERS
- 5 A-SIDE RECEIVERS (R_{A5} ALWAYS ACTIVE)
- 5 B-SIDE RECEIVERS (R_{B5} ALWAYS ACTIVE)

8 TRANSMITTERS
- 4 A-SIDE TRANSMITTERS
- 4 B-SIDE TRANSMITTERS

2 CONTROL PINS
- ENABLE A-SIDE ($\overline{ENA}$)
- ENABLE B-SIDE ($\overline{ENB}$)

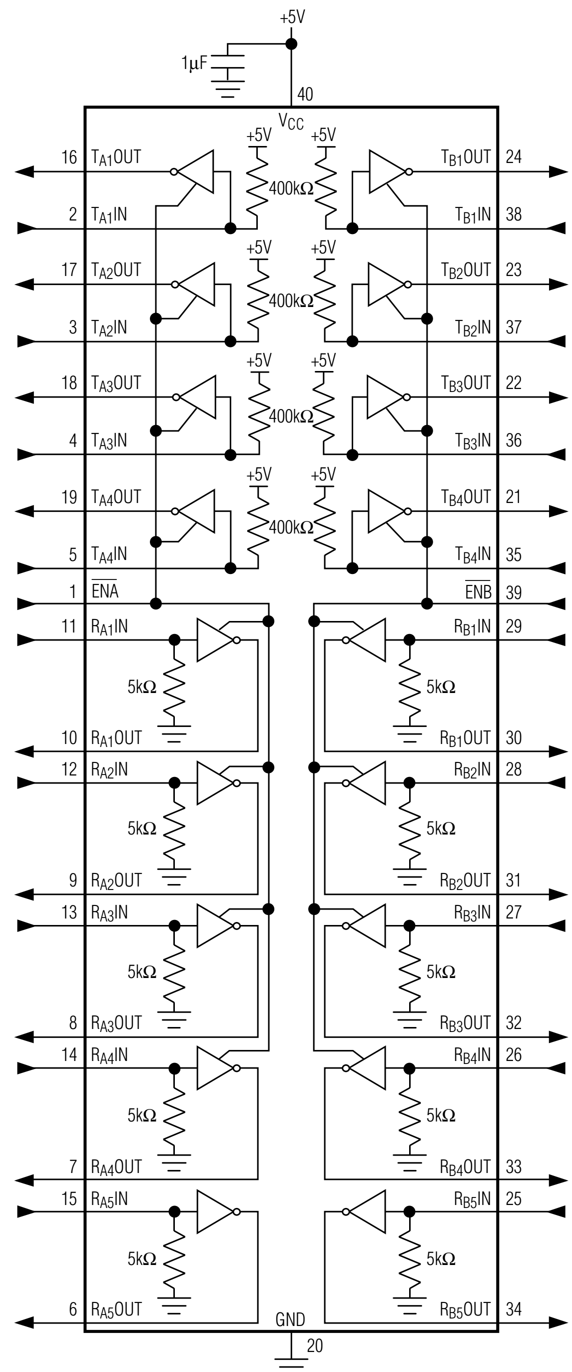
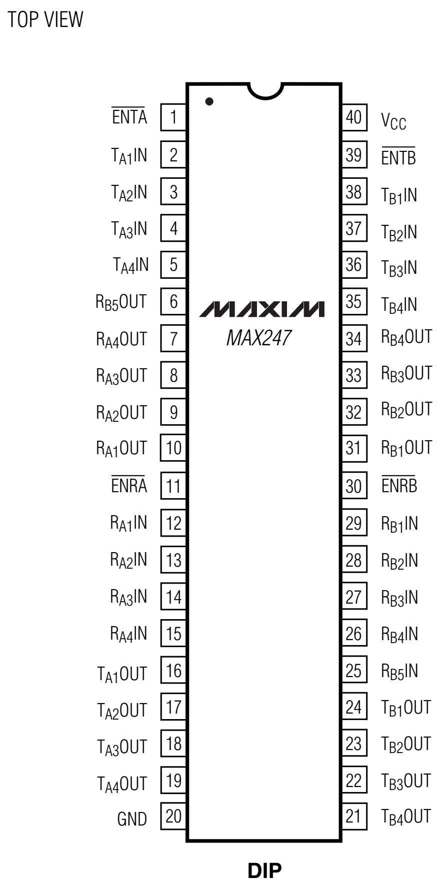


Figure 22. MAX246 Pin Configuration and Typical Operating Circuit



MAX247 FUNCTIONAL DESCRIPTION

9 RECEIVERS
- 4 A-SIDE RECEIVERS
- 5 B-SIDE RECEIVERS (R_{B5} ALWAYS ACTIVE)

8 TRANSMITTERS
- 4 A-SIDE TRANSMITTERS
- 4 B-SIDE TRANSMITTERS

4 CONTROL PINS
- ENABLE RECEIVER A-SIDE (ENRA)
- ENABLE RECEIVER B-SIDE (ENRB)
- ENABLE RECEIVER A-SIDE (ENTA)
- ENABLE RECEIVERr B-SIDE (ENTB)

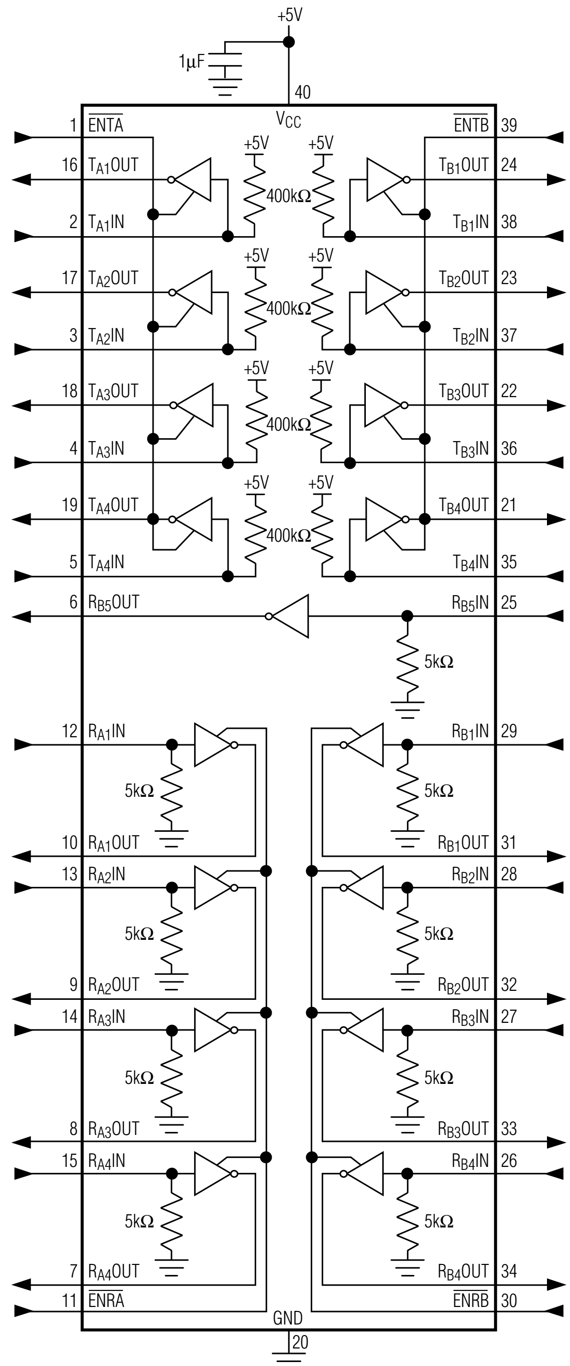
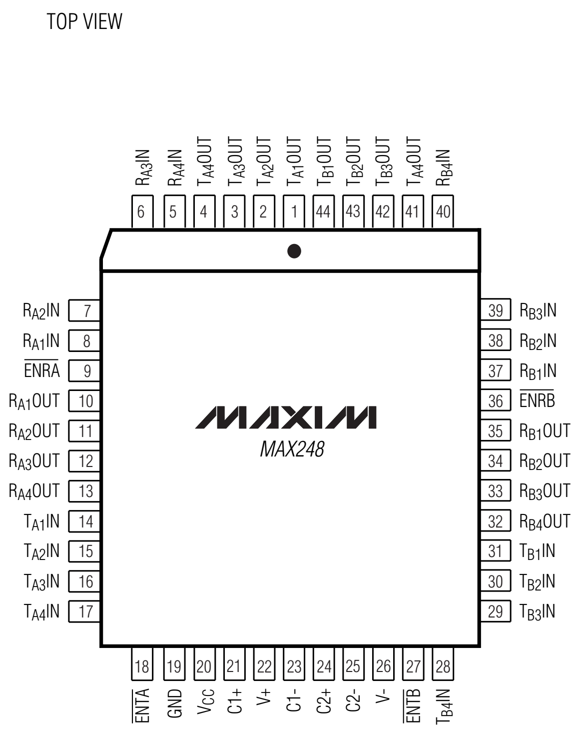


Figure 23. MAX247 Pin Configuration and Typical Operating Circuit



MAX248 FUNCTIONAL DESCRIPTION

8 RECEIVERS
- 4 A-SIDE RECEIVERS
- 4 B-SIDE RECEIVERS

8 TRANSMITTERS
- 4 A-SIDE TRANSMITTERS
- 4 B-SIDE TRANSMITTERS

4 CONTROL PINS
- ENABLE RECEIVER A-SIDE ($\overline{ENRA}$)
- ENABLE RECEIVER B-SIDE ($\overline{ENRB}$)
- ENABLE RECEIVER A-SIDE ($\overline{ENTA}$)
- ENABLE RECEIVER B-SIDE ($\overline{ENTB}$)

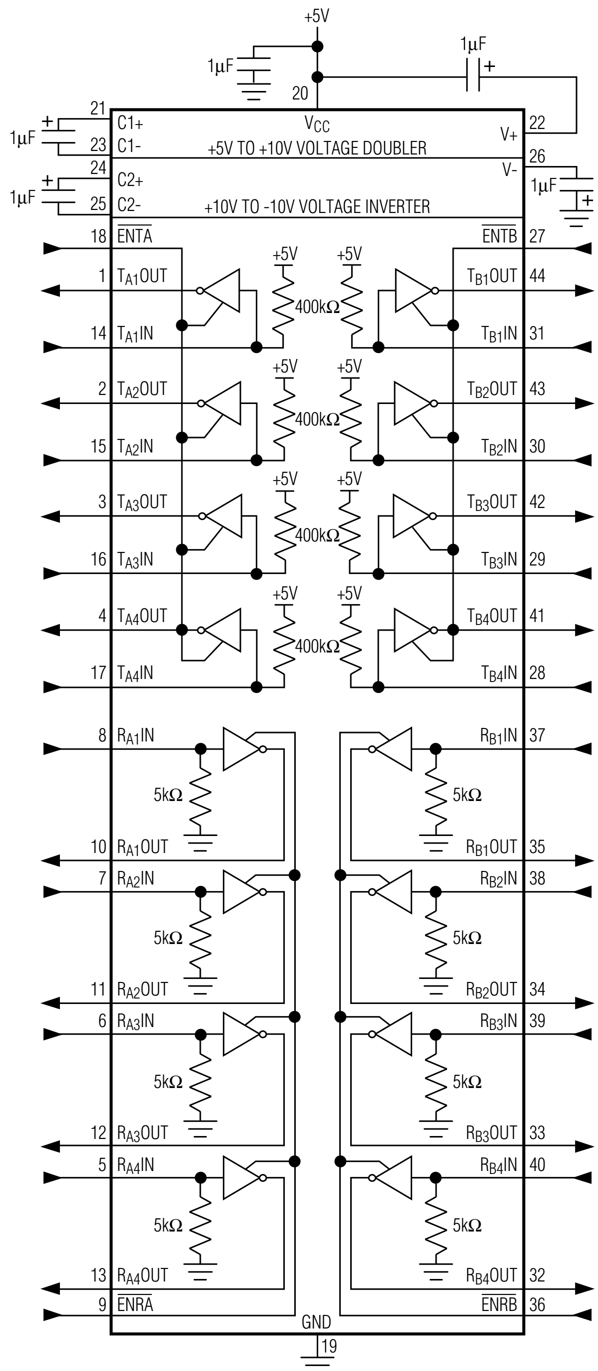
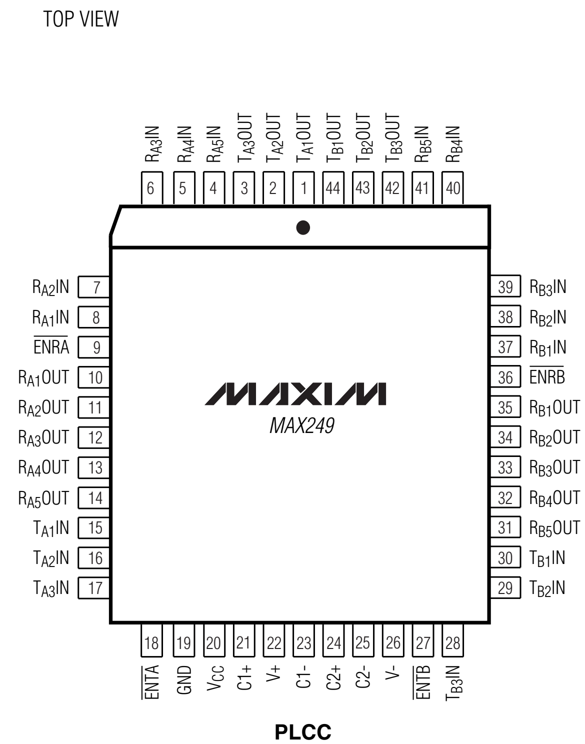


Figure 24. MAX248 Pin Configuration and Typical Operating Circuit



MAX249 FUNCTIONAL DESCRIPTION

10 RECEIVERS
- 5 A-SIDE RECEIVERS
- 5 B-SIDE RECEIVERS

6 TRANSMITTERS
- 3 A-SIDE TRANSMITTERS
- 3 B-SIDE TRANSMITTERS

4 CONTROL PINS
- ENABLE RECEIVER A-SIDE ($\overline{ENRA}$)
- ENABLE RECEIVER B-SIDE ($\overline{ENRB}$)
- ENABLE RECEIVER A-SIDE ($\overline{ENTA}$)
- ENABLE RECEIVER B-SIDE ($\overline{ENTB}$)

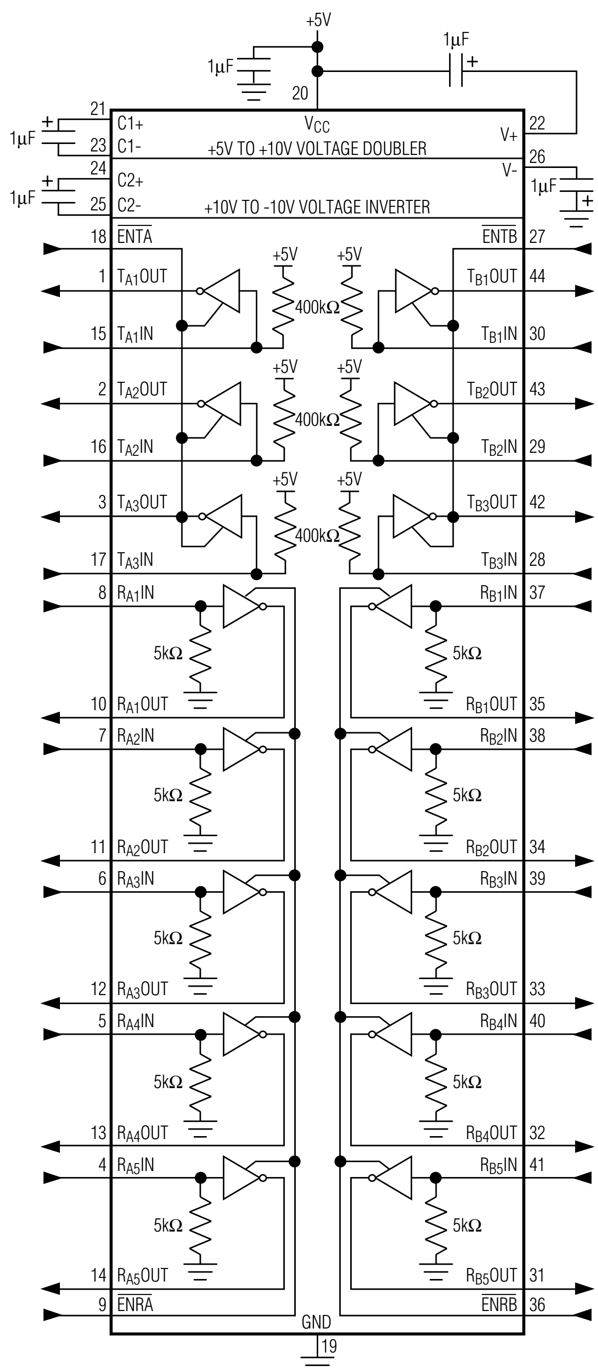


Figure 25. MAX249 Pin Configuration and Typical Operating Circuit

Ordering Information (continued)

PART	TEMP RANGE	PIN-PACKAGE
MAX222CPN	0°C to +70°C	18 Plastic DIP
MAX222CWN	0°C to +70°C	18 Wide SO
MAX222C/D	0°C to +70°C	Dice*
MAX222EPN	-40°C to +85°C	18 Plastic DIP
MAX222EWN	-40°C to +85°C	18 Wide SO
MAX222EJN	-40°C to +85°C	18 CERDIP
MAX222MJN	-55°C to +125°C	18 CERDIP
MAX223CAI	0°C to +70°C	28 SSOP
MAX223CWI	0°C to +70°C	28 Wide SO
MAX223C/D	0°C to +70°C	Dice*
MAX223EAI	-40°C to +85°C	28 SSOP
MAX223EWI	-40°C to +85°C	28 Wide SO
MAX225CWI	0°C to +70°C	28 Wide SO
MAX225EWI	-40°C to +85°C	28 Wide SO
MAX230CPP	0°C to +70°C	20 Plastic DIP
MAX230CWP	0°C to +70°C	20 Wide SO
MAX230C/D	0°C to +70°C	Dice*
MAX230EPP	-40°C to +85°C	20 Plastic DIP
MAX230EWP	-40°C to +85°C	20 Wide SO
MAX230EJP	-40°C to +85°C	20 CERDIP
MAX230MJP	-55°C to +125°C	20 CERDIP
MAX231CPD	0°C to +70°C	14 Plastic DIP
MAX231CWE	0°C to +70°C	16 Wide SO
MAX231CJD	0°C to +70°C	14 CERDIP
MAX231C/D	0°C to +70°C	Dice*
MAX231EPD	-40°C to +85°C	14 Plastic DIP
MAX231EWE	-40°C to +85°C	16 Wide SO
MAX231EJD	-40°C to +85°C	14 CERDIP
MAX231MJD	-55°C to +125°C	14 CERDIP
MAX232CPE	0°C to +70°C	16 Plastic DIP
MAX232CSE	0°C to +70°C	16 Narrow SO
MAX232CWE	0°C to +70°C	16 Wide SO
MAX232C/D	0°C to +70°C	Dice*
MAX232EPE	-40°C to +85°C	16 Plastic DIP
MAX232ESE	-40°C to +85°C	16 Narrow SO
MAX232EWE	-40°C to +85°C	16 Wide SO
MAX232EJE	-40°C to +85°C	16 CERDIP
MAX232MJE	-55°C to +125°C	16 CERDIP
MAX232MLP	-55°C to +125°C	20 LCC
MAX232ACPE	0°C to +70°C	16 Plastic DIP
MAX232ACSE	0°C to +70°C	16 Narrow SO
MAX232ACWE	0°C to +70°C	16 Wide SO

PART	TEMP RANGE	PIN-PACKAGE
MAX232AC/D	0°C to +70°C	Dice*
MAX232AEPE	-40°C to +85°C	16 Plastic DIP
MAX232AESE	-40°C to +85°C	16 Narrow SO
MAX232AEWE	-40°C to +85°C	16 Wide SO
MAX232AEJE	-40°C to +85°C	16 CERDIP
MAX232AMJE	-55°C to +125°C	16 CERDIP
MAX232AMLP	-55°C to +125°C	20 LCC
MAX233CPP	0°C to +70°C	20 Plastic DIP
MAX233EPP	-40°C to +85°C	20 Plastic DIP
MAX233ACPP	0°C to +70°C	20 Plastic DIP
MAX233ACWP	0°C to +70°C	20 Wide SO
MAX233AEPP	-40°C to +85°C	20 Plastic DIP
MAX233AEWP	-40°C to +85°C	20 Wide SO
MAX234CPE	0°C to +70°C	16 Plastic DIP
MAX234CWE	0°C to +70°C	16 Wide SO
MAX234C/D	0°C to +70°C	Dice*
MAX234EPE	-40°C to +85°C	16 Plastic DIP
MAX234EWE	-40°C to +85°C	16 Wide SO
MAX234EJE	-40°C to +85°C	16 CERDIP
MAX234MJE	-55°C to +125°C	16 CERDIP
MAX235CPG	0°C to +70°C	24 Wide Plastic DIP
MAX235EPG	-40°C to +85°C	24 Wide Plastic DIP
MAX235EDG	-40°C to +85°C	24 Ceramic SB
MAX235MDG	-55°C to +125°C	24 Ceramic SB
MAX236CNG	0°C to +70°C	24 Narrow Plastic DIP
MAX236CWG	0°C to +70°C	24 Wide SO
MAX236C/D	0°C to +70°C	Dice*
MAX236ENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX236EWG	-40°C to +85°C	24 Wide SO
MAX236ERG	-40°C to +85°C	24 Narrow CERDIP
MAX236MRG	-55°C to +125°C	24 Narrow CERDIP
MAX237CNG	0°C to +70°C	24 Narrow Plastic DIP
MAX237CWG	0°C to +70°C	24 Wide SO
MAX237C/D	0°C to +70°C	Dice*
MAX237ENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX237EWG	-40°C to +85°C	24 Wide SO
MAX237ERG	-40°C to +85°C	24 Narrow CERDIP
MAX237MRG	-55°C to +125°C	24 Narrow CERDIP
MAX238CNG	0°C to +70°C	24 Narrow Plastic DIP
MAX238CWG	0°C to +70°C	24 Wide SO
MAX238C/D	0°C to +70°C	Dice*
MAX238ENG	-40°C to +85°C	24 Narrow Plastic DIP

** Contact factory for dice specifications.*

Ordering Information (continued)

PART	TEMP RANGE	PIN-PACKAGE
MAX238EWG	-40°C to +85°C	24 Wide SO
MAX238ERG	-40°C to +85°C	24 Narrow CERDIP
MAX238MRG	-55°C to +125°C	24 Narrow CERDIP
MAX239CNG	0°C to +70°C	24 Narrow Plastic DIP
MAX239CWG	0°C to +70°C	24 Wide SO
MAX239C/D	0°C to +70°C	Dice*
MAX239ENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX239EWG	-40°C to +85°C	24 Wide SO
MAX239ERG	-40°C to +85°C	24 Narrow CERDIP
MAX239MRG	-55°C to +125°C	24 Narrow CERDIP
MAX240CMH	0°C to +70°C	44 Plastic FP
MAX240C/D	0°C to +70°C	Dice*
MAX241CAI	0°C to +70°C	28 SSOP
MAX241CWI	0°C to +70°C	28 Wide SO
MAX241C/D	0°C to +70°C	Dice*
MAX241EAI	-40°C to +85°C	28 SSOP
MAX241EWI	-40°C to +85°C	28 Wide SO
MAX242CAP	0°C to +70°C	20 SSOP
MAX242CPN	0°C to +70°C	18 Plastic DIP
MAX242CWN	0°C to +70°C	18 Wide SO
MAX242C/D	0°C to +70°C	Dice*
MAX242EPN	-40°C to +85°C	18 Plastic DIP
MAX242EWN	-40°C to +85°C	18 Wide SO
MAX242EJN	-40°C to +85°C	18 CERDIP
MAX242MJN	-55°C to +125°C	18 CERDIP

PART	TEMP RANGE	PIN-PACKAGE
MAX243CPE	0°C to +70°C	16 Plastic DIP
MAX243CSE	0°C to +70°C	16 Narrow SO
MAX243CWE	0°C to +70°C	16 Wide SO
MAX243C/D	0°C to +70°C	Dice*
MAX243EPE	-40°C to +85°C	16 Plastic DIP
MAX243ESE	-40°C to +85°C	16 Narrow SO
MAX243EWE	-40°C to +85°C	16 Wide SO
MAX243EJE	-40°C to +85°C	16 CERDIP
MAX243MJE	-55°C to +125°C	16 CERDIP
MAX244CQH	0°C to +70°C	44 PLCC
MAX244C/D	0°C to +70°C	Dice*
MAX244EQH	-40°C to +85°C	44 PLCC
MAX245CPL	0°C to +70°C	40 Plastic DIP
MAX245C/D	0°C to +70°C	Dice*
MAX245EPL	-40°C to +85°C	40 Plastic DIP
MAX246CPL	0°C to +70°C	40 Plastic DIP
MAX246C/D	0°C to +70°C	Dice*
MAX246EPL	-40°C to +85°C	40 Plastic DIP
MAX247CPL	0°C to +70°C	40 Plastic DIP
MAX247C/D	0°C to +70°C	Dice*
MAX247EPL	-40°C to +85°C	40 Plastic DIP
MAX248CQH	0°C to +70°C	44 PLCC
MAX248C/D	0°C to +70°C	Dice*
MAX248EQH	-40°C to +85°C	44 PLCC
MAX249CQH	0°C to +70°C	44 PLCC
MAX249EQH	-40°C to +85°C	44 PLCC

** Contact factory for dice specifications.*

Package Information

For the latest package outline information, go to **www.maxim-ic.com/packages**.

National Semiconductor

November 2000

LM35
Precision Centigrade Temperature Sensors

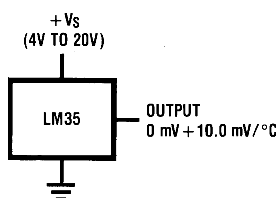
General Description

The LM35 series are precision integrated-circuit temperature sensors, whose output voltage is linearly proportional to the Celsius (Centigrade) temperature. The LM35 thus has an advantage over linear temperature sensors calibrated in ° Kelvin, as the user is not required to subtract a large constant voltage from its output to obtain convenient Centigrade scaling. The LM35 does not require any external calibration or trimming to provide typical accuracies of ±¼˚C at room temperature and ±¾˚C over a full −55 to +150˚C temperature range. Low cost is assured by trimming and calibration at the wafer level. The LM35's low output impedance, linear output, and precise inherent calibration make interfacing to readout or control circuitry especially easy. It can be used with single power supplies, or with plus and minus supplies. As it draws only 60 µA from its supply, it has very low self-heating, less than 0.1˚C in still air. The LM35 is rated to operate over a −55˚ to +150˚C temperature range, while the LM35C is rated for a −40˚ to +110˚C range (−10˚ with improved accuracy). The LM35 series is available packaged in hermetic TO-46 transistor packages, while the LM35C, LM35CA, and LM35D are also available in the plastic TO-92 transistor package. The LM35D is also available in an 8-lead surface mount small outline package and a plastic TO-220 package.

Features

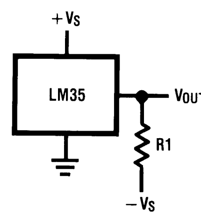
- Calibrated directly in ˚ Celsius (Centigrade)
- Linear + 10.0 mV/˚C scale factor
- 0.5˚C accuracy guaranteeable (at +25˚C)
- Rated for full −55˚ to +150˚C range
- Suitable for remote applications
- Low cost due to wafer-level trimming
- Operates from 4 to 30 volts
- Less than 60 µA current drain
- Low self-heating, 0.08˚C in still air
- Nonlinearity only ±¼˚C typical
- Low impedance output, 0.1 Ω for 1 mA load

Typical Applications



DS005516-3

FIGURE 1. Basic Centigrade Temperature Sensor (+2˚C to +150˚C)



DS005516-4

Choose $R_1 = -V_S/50\ \mu A$

V_{OUT}=+1,500 mV at +150˚C

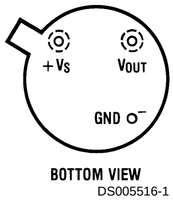
= +250 mV at +25˚C

= −550 mV at −55˚C

FIGURE 2. Full-Range Centigrade Temperature Sensor

Connection Diagrams

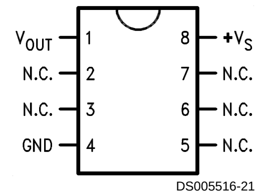
TO-46
Metal Can Package*



*Case is connected to negative pin (GND)

Order Number LM35H, LM35AH, LM35CH, LM35CAH or LM35DH
See NS Package Number H03H

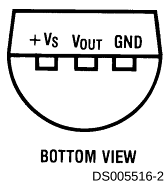
SO-8
Small Outline Molded Package



N.C. = No Connection

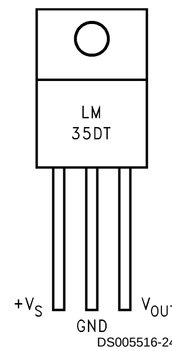
Top View
Order Number LM35DM
See NS Package Number M08A

TO-92
Plastic Package



Order Number LM35CZ, LM35CAZ or LM35DZ
See NS Package Number Z03A

TO-220
Plastic Package*



*Tab is connected to the negative pin (GND).

Note: The LM35DT pinout is different than the discontinued LM35DP.

Order Number LM35DT
See NS Package Number TA03F

Absolute Maximum Ratings (Note 10)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage	+35V to −0.2V
Output Voltage	+6V to −1.0V
Output Current	10 mA
Storage Temp.;	
TO-46 Package,	−60˚C to +180˚C
TO-92 Package,	−60˚C to +150˚C
SO-8 Package,	−65˚C to +150˚C
TO-220 Package,	−65˚C to +150˚C
Lead Temp.:	
TO-46 Package, (Soldering, 10 seconds)	300˚C
TO-92 and TO-220 Package, (Soldering, 10 seconds)	260˚C
SO Package (Note 12)	
Vapor Phase (60 seconds)	215˚C
Infrared (15 seconds)	220˚C
ESD Susceptibility (Note 11)	2500V

Specified Operating Temperature Range: T_{MIN} to T_{MAX} (Note 2)

LM35, LM35A	−55˚C to +150˚C
LM35C, LM35CA	−40˚C to +110˚C
LM35D	0˚C to +100˚C

Electrical Characteristics

(Notes 1, 6)

Parameter	Conditions	LM35A			LM35CA			Units (Max.)
		Typical	Tested Limit (Note 4)	Design Limit (Note 5)	Typical	Tested Limit (Note 4)	Design Limit (Note 5)	
Accuracy (Note 7)	T_A=+25˚C	±0.2	±0.5		±0.2	±0.5		˚C
	T_A=−10˚C	±0.3			±0.3		±1.0	˚C
	$T_A=T_{MAX}$	±0.4	±1.0		±0.4	±1.0		˚C
	$T_A=T_{MIN}$	±0.4	±1.0		±0.4		±1.5	˚C
Nonlinearity (Note 8)	$T_{MIN}≤T_A≤T_{MAX}$	**±0.18**		**±0.35**	**±0.15**		**±0.3**	˚C
Sensor Gain (Average Slope)	$T_{MIN}≤T_A≤T_{MAX}$	**+10.0**	**+9.9, +10.1**		**+10.0**		**+9.9, +10.1**	mV/˚C
Load Regulation (Note 3) $0≤I_L≤1$ mA	T_A=+25˚C	±0.4	±1.0		±0.4	±1.0		mV/mA
	$T_{MIN}≤T_A≤T_{MAX}$	**±0.5**		**±3.0**	**±0.5**		**±3.0**	mV/mA
Line Regulation (Note 3)	T_A=+25˚C	±0.01	±0.05		±0.01	±0.05		mV/V
	$4V≤V_S≤30V$	**±0.02**		**±0.1**	**±0.02**		**±0.1**	mV/V
Quiescent Current (Note 9)	V_S=+5V, +25˚C	56	67		56	67		µA
	V_S=+5V	**105**		**131**	**91**		**114**	µA
	V_S=+30V, +25˚C	56.2	68		56.2	68		µA
	V_S=+30V	**105.5**		**133**	**91.5**		**116**	µA
Change of Quiescent Current (Note 3)	$4V≤V_S≤30V$, +25˚C	0.2	1.0		0.2	1.0		µA
	$4V≤V_S≤30V$	**0.5**		**2.0**	**0.5**		**2.0**	µA
Temperature Coefficient of Quiescent Current		**+0.39**		**+0.5**	**+0.39**		**+0.5**	µA/˚C
Minimum Temperature for Rated Accuracy	In circuit of *Figure 1*, I_L=0	+1.5		+2.0	+1.5		+2.0	˚C
Long Term Stability	$T_J=T_{MAX}$, for 1000 hours	±0.08			±0.08			˚C

Electrical Characteristics

(Notes 1, 6)

Parameter	Conditions	LM35			LM35C, LM35D			Units
		Typical	Tested Limit (Note 4)	Design Limit (Note 5)	Typical	Tested Limit (Note 4)	Design Limit (Note 5)	(Max.)
Accuracy, LM35, LM35C (Note 7)	T_A=+25˚C	±0.4	±1.0		±0.4	±1.0		˚C
	T_A=−10˚C	±0.5			±0.5		±1.5	˚C
	$T_A=T_{MAX}$	±0.8	±1.5		±0.8		±1.5	˚C
	$T_A=T_{MIN}$	±0.8		±1.5	±0.8		±2.0	˚C
Accuracy, LM35D (Note 7)	T_A=+25˚C				±0.6	±1.5		˚C
	$T_A=T_{MAX}$				±0.9		±2.0	˚C
	$T_A=T_{MIN}$				±0.9		±2.0	˚C
Nonlinearity (Note 8)	$T_{MIN} \leq T_A \leq T_{MAX}$	**±0.3**		**±0.5**	**±0.2**		**±0.5**	˚C
Sensor Gain (Average Slope)	$T_{MIN} \leq T_A \leq T_{MAX}$	**+10.0**	**+9.8, +10.2**		**+10.0**		**+9.8, +10.2**	mV/˚C
Load Regulation (Note 3) $0 \leq I_L \leq 1$ mA	T_A=+25˚C	±0.4	±2.0		±0.4	±2.0		mV/mA
	$T_{MIN} \leq T_A \leq T_{MAX}$	**±0.5**		**±5.0**	**±0.5**		**±5.0**	mV/mA
Line Regulation (Note 3)	T_A=+25˚C	±0.01	±0.1		±0.01	±0.1		mV/V
	$4V \leq V_S \leq 30V$	**±0.02**		**±0.2**	**±0.02**		**±0.2**	mV/V
Quiescent Current (Note 9)	V_S=+5V, +25˚C	56	80		56	80		µA
	V_S=+5V	**105**		**158**	**91**		**138**	µA
	V_S=+30V, +25˚C	56.2	82		56.2	82		µA
	V_S=+30V	**105.5**		**161**	**91.5**		**141**	µA
Change of Quiescent Current (Note 3)	$4V \leq V_S \leq 30V$, +25˚C	0.2	2.0		0.2	2.0		µA
	$4V \leq V_S \leq 30V$	**0.5**		**3.0**	**0.5**		**3.0**	µA
Temperature Coefficient of Quiescent Current		**+0.39**		**+0.7**	**+0.39**		**+0.7**	µA/˚C
Minimum Temperature for Rated Accuracy	In circuit of *Figure 1*, I_L=0	+1.5		+2.0	+1.5		+2.0	˚C
Long Term Stability	$T_J=T_{MAX}$, for 1000 hours	±0.08			±0.08			˚C

Note 1: Unless otherwise noted, these specifications apply: $-55˚C \leq T_J \leq +150˚C$ for the LM35 and LM35A; $-40˚C \leq T_J \leq +110˚C$ for the LM35C and LM35CA; and $0˚C \leq T_J \leq +100˚C$ for the LM35D. V_S=+5Vdc and I_{LOAD}=50 µA, in the circuit of *Figure 2*. These specifications also apply from +2˚C to T_{MAX} in the circuit of *Figure 1*. Specifications in **boldface** apply over the full rated temperature range.

Note 2: Thermal resistance of the TO-46 package is 400˚C/W, junction to ambient, and 24˚C/W junction to case. Thermal resistance of the TO-92 package is 180˚C/W junction to ambient. Thermal resistance of the small outline molded package is 220˚C/W junction to ambient. Thermal resistance of the TO-220 package is 90˚C/W junction to ambient. For additional thermal resistance information see table in the Applications section.

Note 3: Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance.

Note 4: Tested Limits are guaranteed and 100% tested in production.

Note 5: Design Limits are guaranteed (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are not used to calculate outgoing quality levels.

Note 6: Specifications in **boldface** apply over the full rated temperature range.

Note 7: Accuracy is defined as the error between the output voltage and 10mv/˚C times the device's case temperature, at specified conditions of voltage, current, and temperature (expressed in ˚C).

Note 8: Nonlinearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the device's rated temperature range.

Note 9: Quiescent current is defined in the circuit of *Figure 1.*

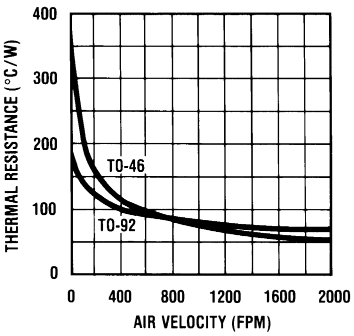
Note 10: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions. See Note 1.

Note 11: Human body model, 100 pF discharged through a 1.5 kΩ resistor.

Note 12: See AN-450 “Surface Mounting Methods and Their Effect on Product Reliability” or the section titled “Surface Mount” found in a current National Semiconductor Linear Data Book for other methods of soldering surface mount devices.

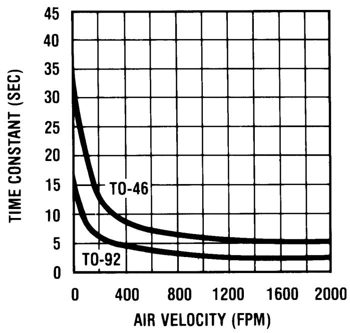
Typical Performance Characteristics

Thermal Resistance Junction to Air



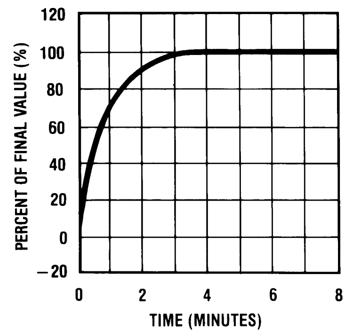
DS005516-25

Thermal Time Constant



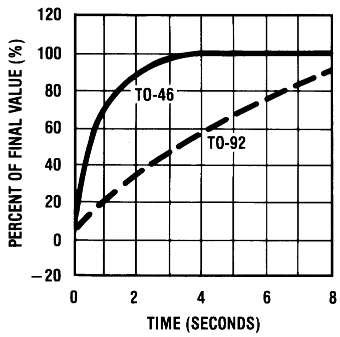
DS005516-26

Thermal Response in Still Air



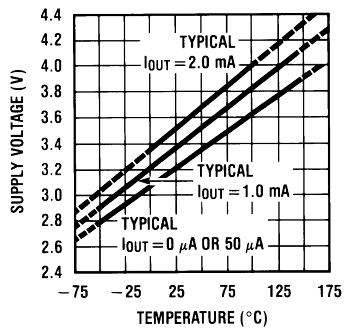
DS005516-27

Thermal Response in Stirred Oil Bath



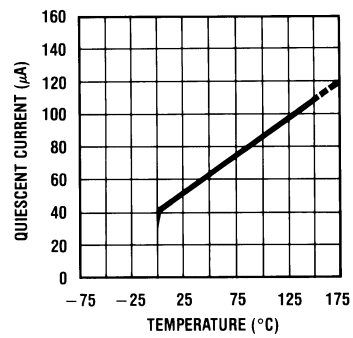
DS005516-28

Minimum Supply Voltage vs. Temperature



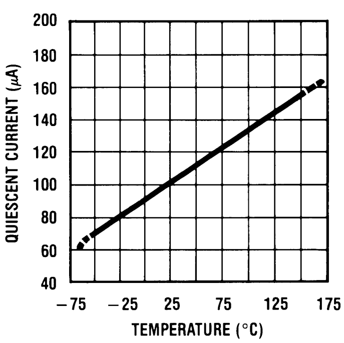
DS005516-29

Quiescent Current vs. Temperature (In Circuit of ***Figure 1*****.)**



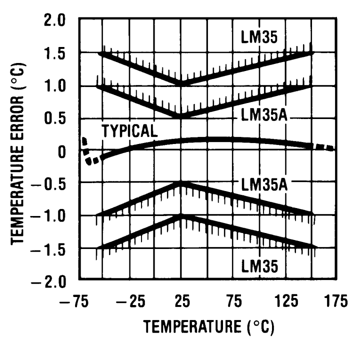
DS005516-30

Quiescent Current vs. Temperature (In Circuit of ***Figure 2*****.)**



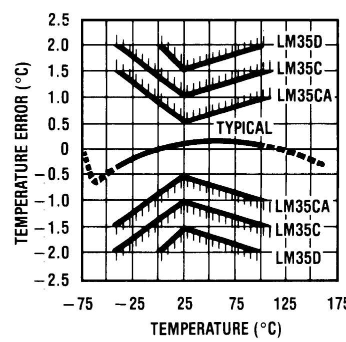
DS005516-31

Accuracy vs. Temperature (Guaranteed)



DS005516-32

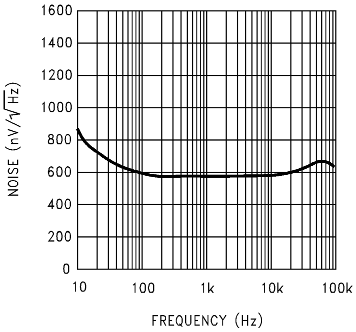
Accuracy vs. Temperature (Guaranteed)



DS005516-33

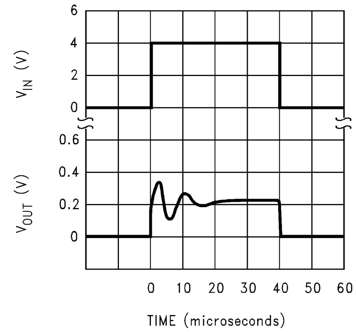
Typical Performance Characteristics (Continued)

Noise Voltage



DS005516-34

Start-Up Response



DS005516-35

Applications

The LM35 can be applied easily in the same way as other integrated-circuit temperature sensors. It can be glued or cemented to a surface and its temperature will be within about 0.01˚C of the surface temperature.

This presumes that the ambient air temperature is almost the same as the surface temperature; if the air temperature were much higher or lower than the surface temperature, the actual temperature of the LM35 die would be at an intermediate temperature between the surface temperature and the air temperature. This is expecially true for the TO-92 plastic package, where the copper leads are the principal thermal path to carry heat into the device, so its temperature might be closer to the air temperature than to the surface temperature.

To minimize this problem, be sure that the wiring to the LM35, as it leaves the device, is held at the same temperature as the surface of interest. The easiest way to do this is to cover up these wires with a bead of epoxy which will insure that the leads and wires are all at the same temperature as the surface, and that the LM35 die's temperature will not be affected by the air temperature.

The TO-46 metal package can also be soldered to a metal surface or pipe without damage. Of course, in that case the V− terminal of the circuit will be grounded to that metal. Alternatively, the LM35 can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the LM35 and accompanying wiring and circuits must be kept insulated and dry, to avoid leakage and corrosion. This is especially true if the circuit may operate at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as Humiseal and epoxy paints or dips are often used to insure that moisture cannot corrode the LM35 or its connections.

These devices are sometimes soldered to a small light-weight heat fin, to decrease the thermal time constant and speed up the response in slowly-moving air. On the other hand, a small thermal mass may be added to the sensor, to give the steadiest reading despite small deviations in the air temperature.

Temperature Rise of LM35 Due To Self-heating (Thermal Resistance, θ_{JA})

	TO-46, no heat sink	**TO-46*, small heat fin**	**TO-92, no heat sink**	**TO-92**, small heat fin**	**SO-8 no heat sink**	**SO-8** small heat fin**	**TO-220 no heat sink**
Still air	400˚C/W	100˚C/W	180˚C/W	140˚C/W	220˚C/W	110˚C/W	90˚C/W
Moving air	100˚C/W	40˚C/W	90˚C/W	70˚C/W	105˚C/W	90˚C/W	26˚C/W
Still oil	100˚C/W	40˚C/W	90˚C/W	70˚C/W			
Stirred oil	50˚C/W	30˚C/W	45˚C/W	40˚C/W			
(Clamped to metal, Infinite heat sink)	(24˚C/W)				(55˚C/W)		

*Wakefield type 201, or 1" disc of 0.020" sheet brass, soldered to case, or similar.
**TO-92 and SO-8 packages glued and leads soldered to 1" square of 1/16" printed circuit board with 2 oz. foil or similar.

Typical Applications

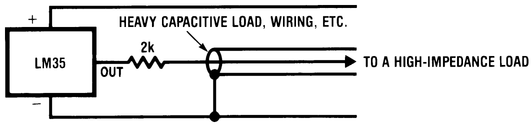


FIGURE 3. LM35 with Decoupling from Capacitive Load

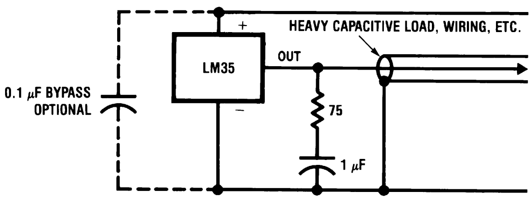


FIGURE 4. LM35 with R-C Damper

CAPACITIVE LOADS

Like most micropower circuits, the LM35 has a limited ability to drive heavy capacitive loads. The LM35 by itself is able to drive 50 pf without special precautions. If heavier loads are anticipated, it is easy to isolate or decouple the load with a resistor; see *Figure 3*. Or you can improve the tolerance of capacitance with a series R-C damper from output to ground; see *Figure 4*.

When the LM35 is applied with a 200Ω load resistor as shown in *Figure 5*, *Figure 6* or *Figure 8* it is relatively immune to wiring capacitance because the capacitance forms a by-pass from ground to input, not on the output. However, as with any linear circuit connected to wires in a hostile environment, its performance can be affected adversely by intense electromagnetic sources such as relays, radio transmitters, motors with arcing brushes, SCR transients, etc, as its wiring can act as a receiving antenna and its internal junctions can act as rectifiers. For best results in such cases, a bypass capacitor from V_{IN} to ground and a series R-C damper such as 75Ω in series with 0.2 or 1 µF from output to ground are often useful. These are shown in *Figure 13*, *Figure 14*, and *Figure 16*.

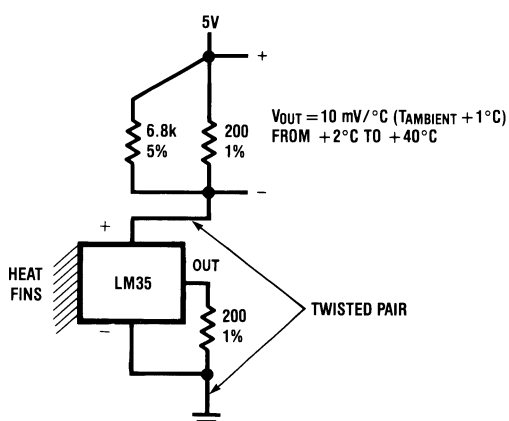


FIGURE 5. Two-Wire Remote Temperature Sensor (Grounded Sensor)

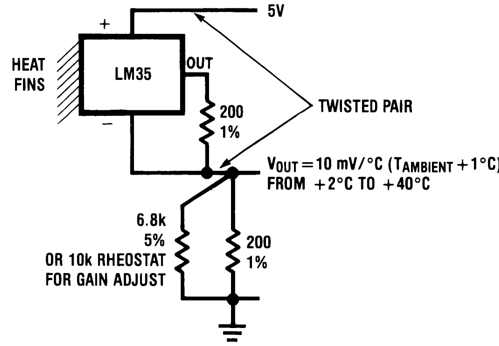


FIGURE 6. Two-Wire Remote Temperature Sensor (Output Referred to Ground)

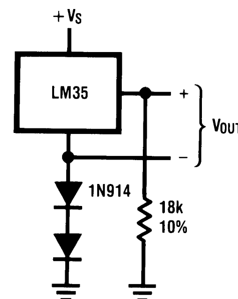


FIGURE 7. Temperature Sensor, Single Supply, −55˚ to +150˚C

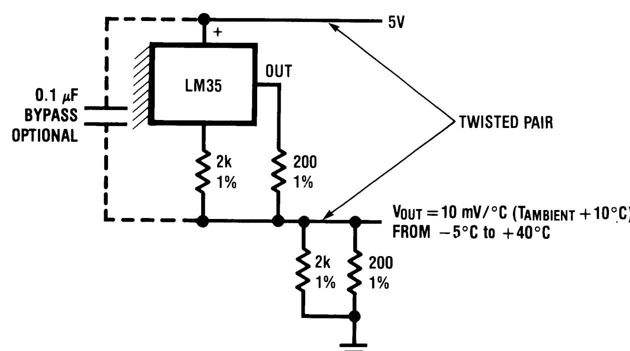


FIGURE 8. Two-Wire Remote Temperature Sensor (Output Referred to Ground)

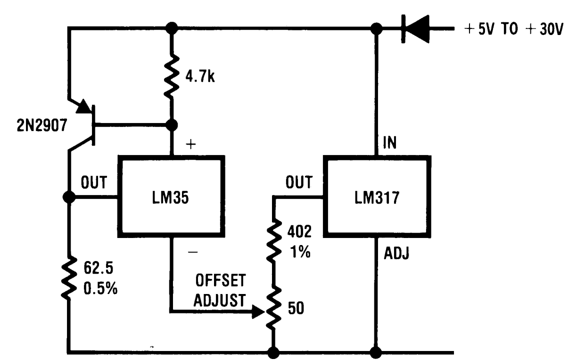


FIGURE 9. 4-To-20 mA Current Source (0˚C to +100˚C)

Typical Applications (Continued)

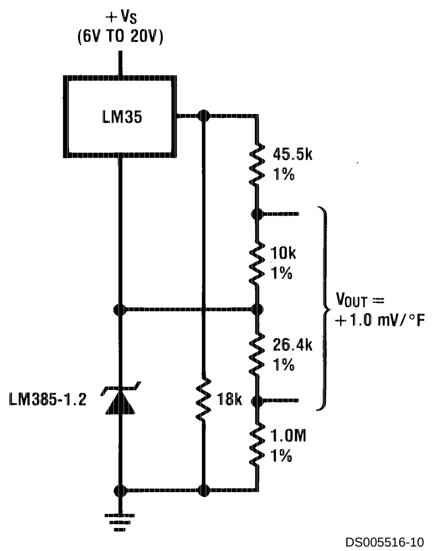


FIGURE 10. Fahrenheit Thermometer

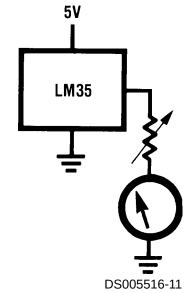


FIGURE 11. Centigrade Thermometer (Analog Meter)

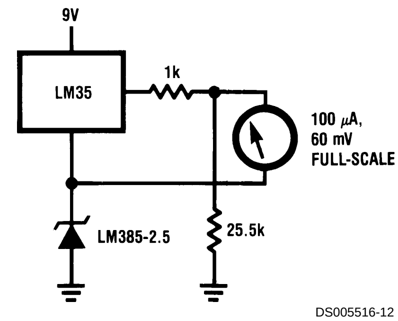


FIGURE 12. Fahrenheit ThermometerExpanded Scale Thermometer
(50˚ to 80˚ Fahrenheit, for Example Shown)

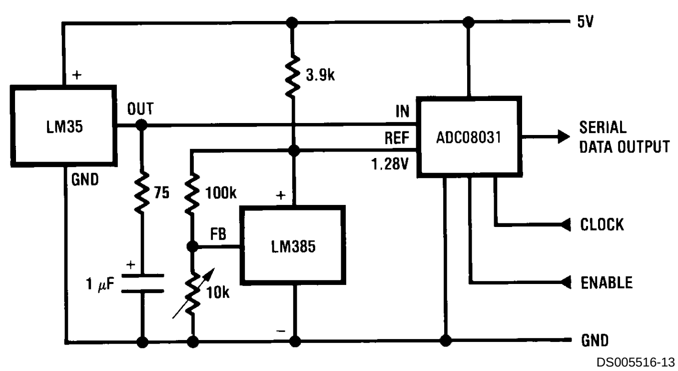


FIGURE 13. Temperature To Digital Converter (Serial Output) (+128˚C Full Scale)

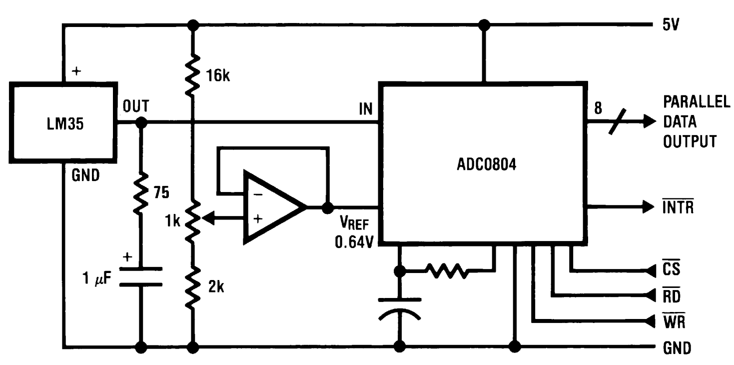
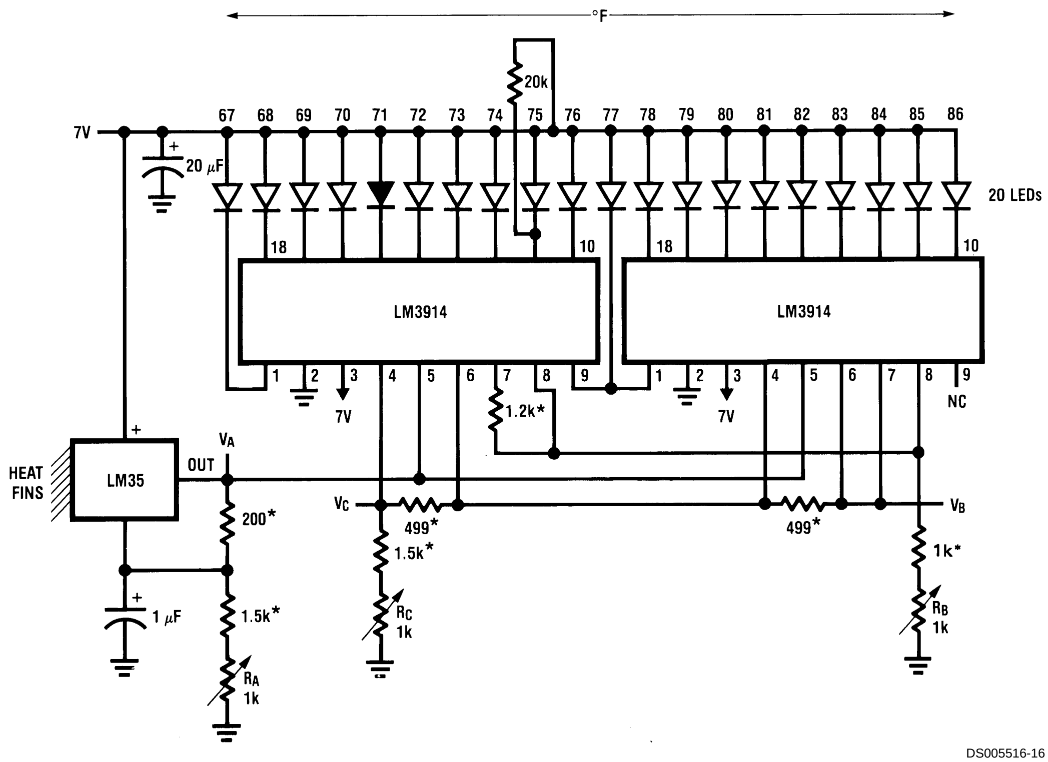


FIGURE 14. Temperature To Digital Converter (Parallel TRI-STATE™ Outputs for Standard Data Bus to µP Interface) (128˚C Full Scale)

Typical Applications (Continued)



*=1% or 2% film resistor
Trim R_B for V_B=3.075V
Trim R_C for V_C=1.955V
Trim R_A for V_A=0.075V + 100mV/˚C x $T_{ambient}$
Example, V_A=2.275V at 22˚C

FIGURE 15. Bar-Graph Temperature Display (Dot Mode)

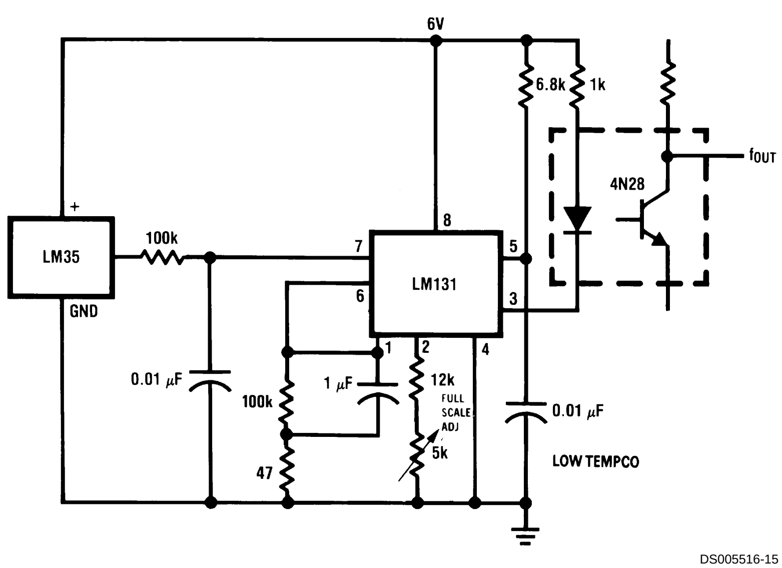
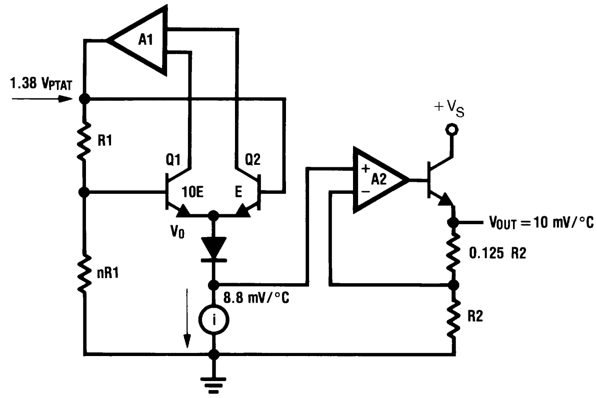


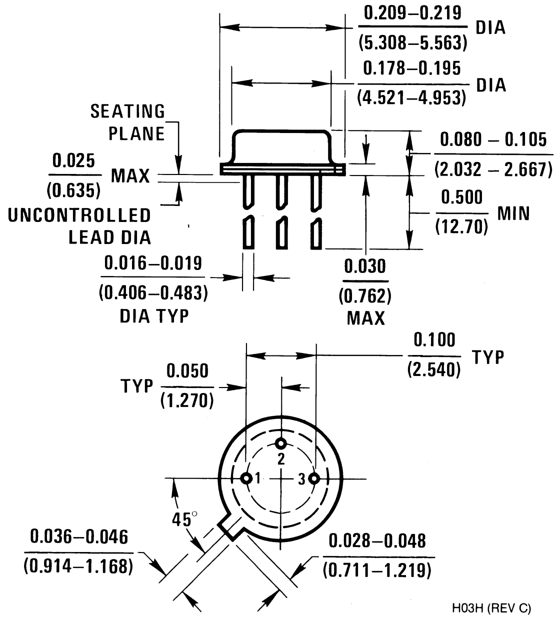
FIGURE 16. LM35 With Voltage-To-Frequency Converter And Isolated Output (2˚C to +150˚C; 20 Hz to 1500 Hz)

Block Diagram

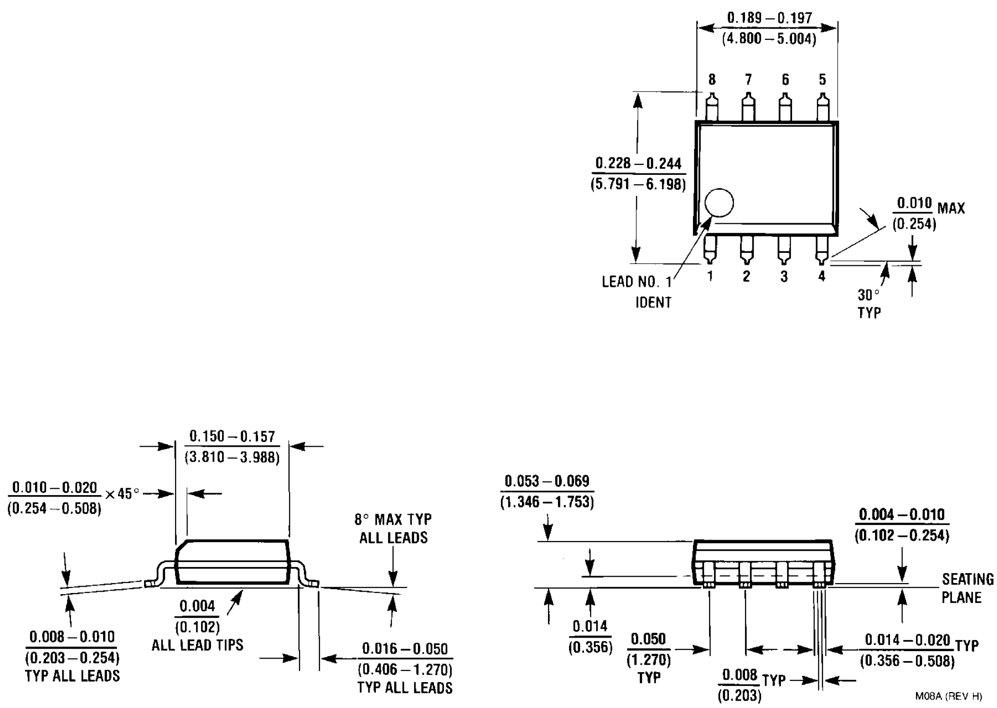


DS005516-23

Physical Dimensions inches (millimeters) unless otherwise noted

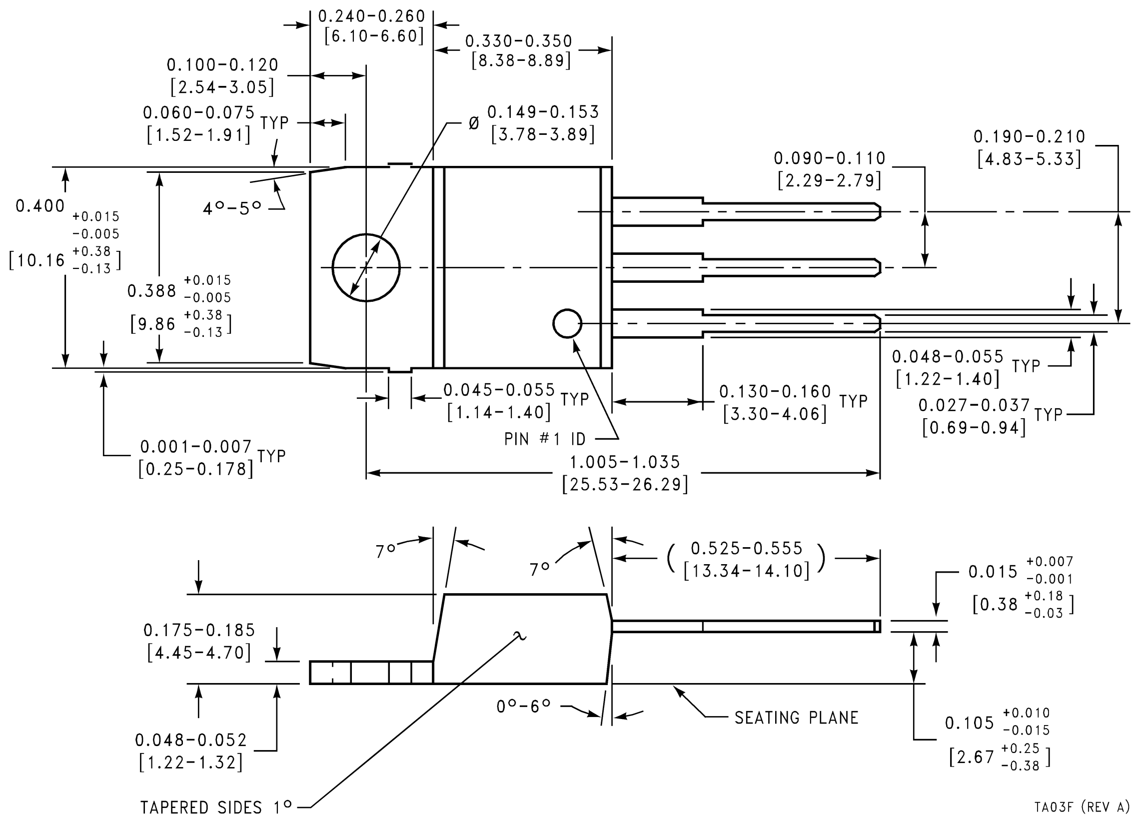


TO-46 Metal Can Package (H)
Order Number LM35H, LM35AH, LM35CH, LM35CAH, or LM35DH
NS Package Number H03H



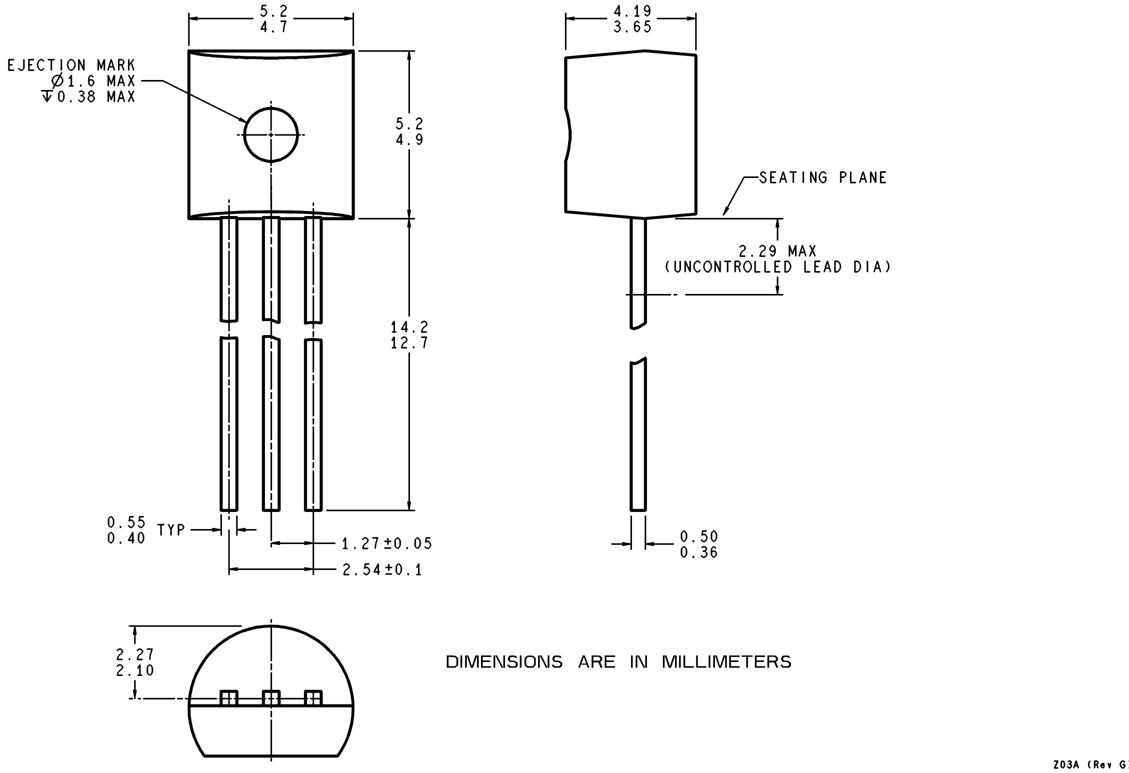
SO-8 Molded Small Outline Package (M)
Order Number LM35DM
NS Package Number M08A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Power Package TO-220 (T)
Order Number LM35DT
NS Package Number TA03F

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



TO-92 Plastic Package (Z)
Order Number LM35CZ, LM35CAZ or LM35DZ
NS Package Number Z03A

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1N4001 - 1N4007

Features

- Low forward voltage drop.
- High surge current capability.

DO-41
COLOR BAND DENOTES CATHODE

General Purpose Rectifiers (Glass Passivated)

Absolute Maximum Ratings* T_A = 25°C unless otherwise noted

Symbol	Parameter	Value							Units
		4001	4002	4003	4004	4005	4006	4007	
V_{RRM}	Peak Repetitive Reverse Voltage	50	100	200	400	600	800	1000	V
$I_{F(AV)}$	Average Rectified Forward Current, .375 " lead length @ T_A = 75°C	1.0							A
I_{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	30							A
T_{stg}	Storage Temperature Range	-55 to +175							°C
T_J	Operating Junction Temperature	-55 to +175							°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
P_D	Power Dissipation	3.0	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	50	°C/W

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Device							Units
		4001	4002	4003	4004	4005	4006	4007	
V_F	Forward Voltage @ 1.0 A	1.1							V
I_{rr}	Maximum Full Load Reverse Current, Full Cycle T_A = 75°C	30							µA
I_R	Reverse Current @ rated V_R T_A = 25°C T_A = 100°C	5.0 500							µA µA
C_T	Total Capacitance V_R = 4.0 V, f = 1.0 MHz	15							pF

Typical Characteristics

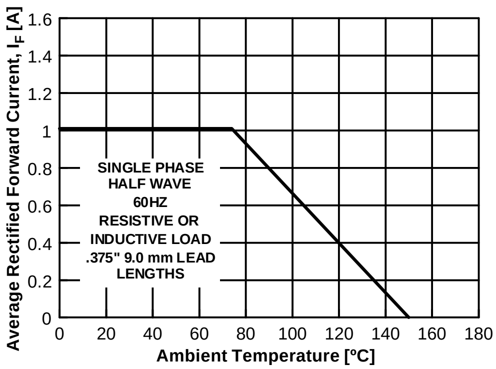

Figure 1. Forward Current Derating Curve

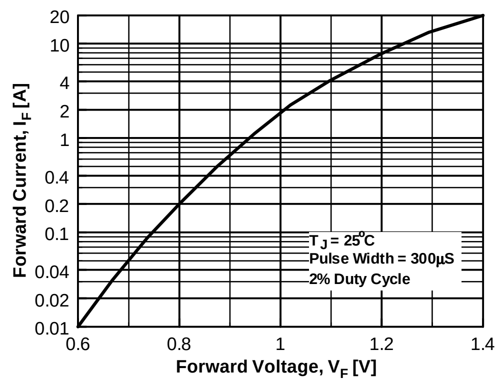

Figure 2. Forward Voltage Characteristics

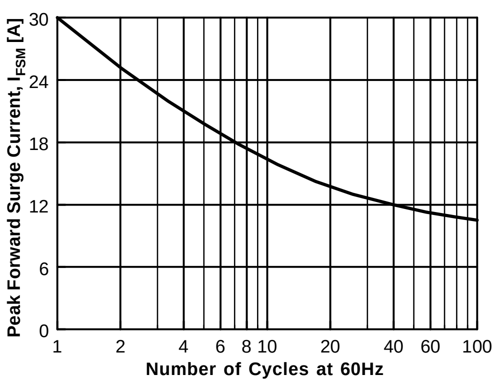

Figure 3. Non-Repetitive Surge Current

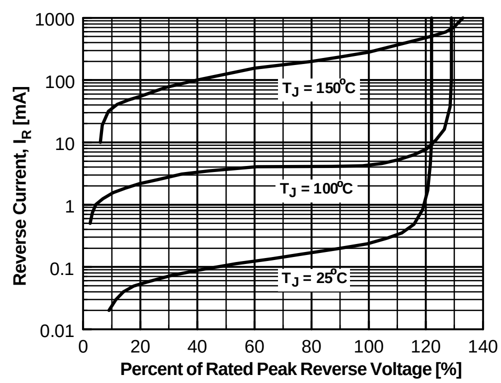

Figure 4. Reverse Current vs Reverse Voltage

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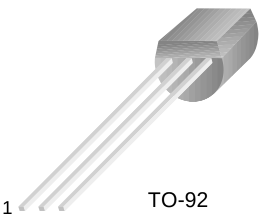
Rev. H4

FAIRCHILD
SEMICONDUCTOR®

BC546/547/548/549/550

Switching and Applications

- High Voltage: BC546, V_{CEO}=65V
- Low Noise: BC549, BC550
- Complement to BC556 ... BC560



1 TO-92

1. Collector 2. Base 3. Emitter

NPN Epitaxial Silicon Transistor

Absolute Maximum Ratings T_a=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage : BC546 : BC547/550 : BC548/549	80 50 30	V V V
V_{CEO}	Collector-Emitter Voltage : BC546 : BC547/550 : BC548/549	65 45 30	V V V
V_{EBO}	Emitter-Base Voltage : BC546/547 : BC548/549/550	6 5	V V
I_C	Collector Current (DC)	100	mA
P_C	Collector Power Dissipation	500	mW
T_J	Junction Temperature	150	°C
T_{STG}	Storage Temperature	-65 ~ 150	°C

Electrical Characteristics T_a=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
I_{CBO}	Collector Cut-off Current	V_{CB}=30V, I_E=0			15	nA
h_{FE}	DC Current Gain	V_{CE}=5V, I_C=2mA	110		800	
V_{CE} (sat)	Collector-Emitter Saturation Voltage	I_C=10mA, I_B=0.5mA I_C=100mA, I_B=5mA		90 200	250 600	mV mV
V_{BE} (sat)	Base-Emitter Saturation Voltage	I_C=10mA, I_B=0.5mA I_C=100mA, I_B=5mA		700 900		mV mV
V_{BE} (on)	Base-Emitter On Voltage	V_{CE}=5V, I_C=2mA V_{CE}=5V, I_C=10mA	580	660	700 720	mV mV
f_T	Current Gain Bandwidth Product	V_{CE}=5V, I_C=10mA, f=100MHz		300		MHz
C_{ob}	Output Capacitance	V_{CB}=10V, I_E=0, f=1MHz		3.5	6	pF
C_{ib}	Input Capacitance	V_{EB}=0.5V, I_C=0, f=1MHz		9		pF
NF	Noise Figure : BC546/547/548 : BC549/550 : BC549 : BC550	V_{CE}=5V, I_C=200μA f=1KHz, R_G=2KΩ V_{CE}=5V, I_C=200μA R_G=2KΩ, f=30~15000MHz		2 1.2 1.4 1.4	10 4 4 3	dB dB dB dB

h_{FE} Classification

Classification	A	B	C
h_{FE}	110 ~ 220	200 ~ 450	420 ~ 800

Typical Characteristics

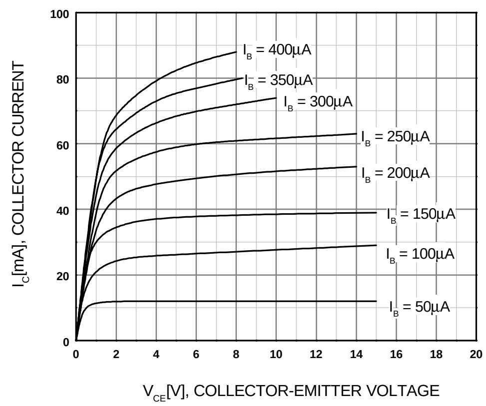


Figure 1. Static Characteristic

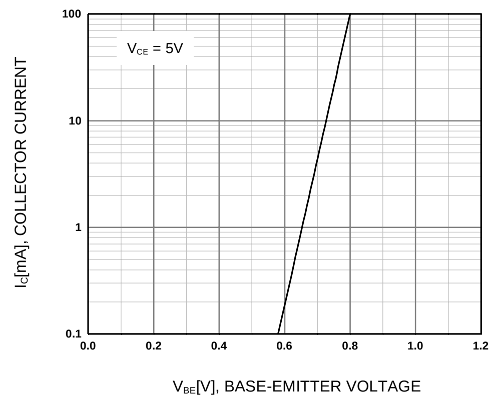


Figure 2. Transfer Characteristic

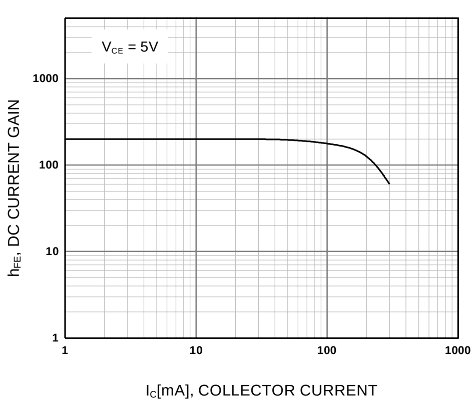


Figure 3. DC current Gain

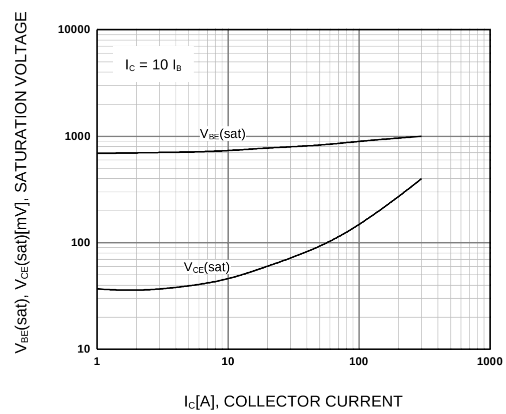


Figure 4. Base-Emitter Saturation Voltage Collector-Emitter Saturation Voltage

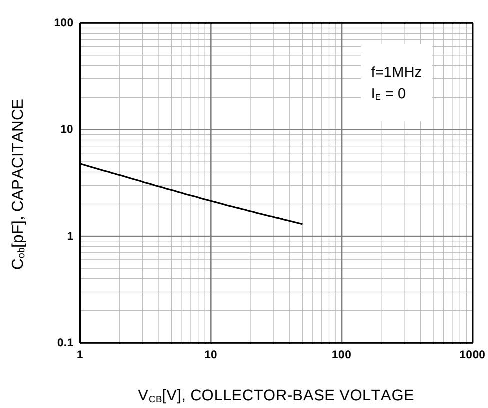


Figure 5. Output Capacitance

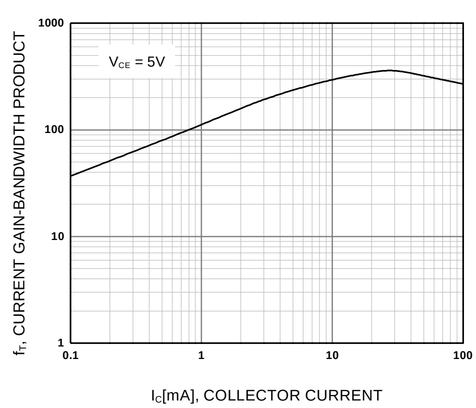
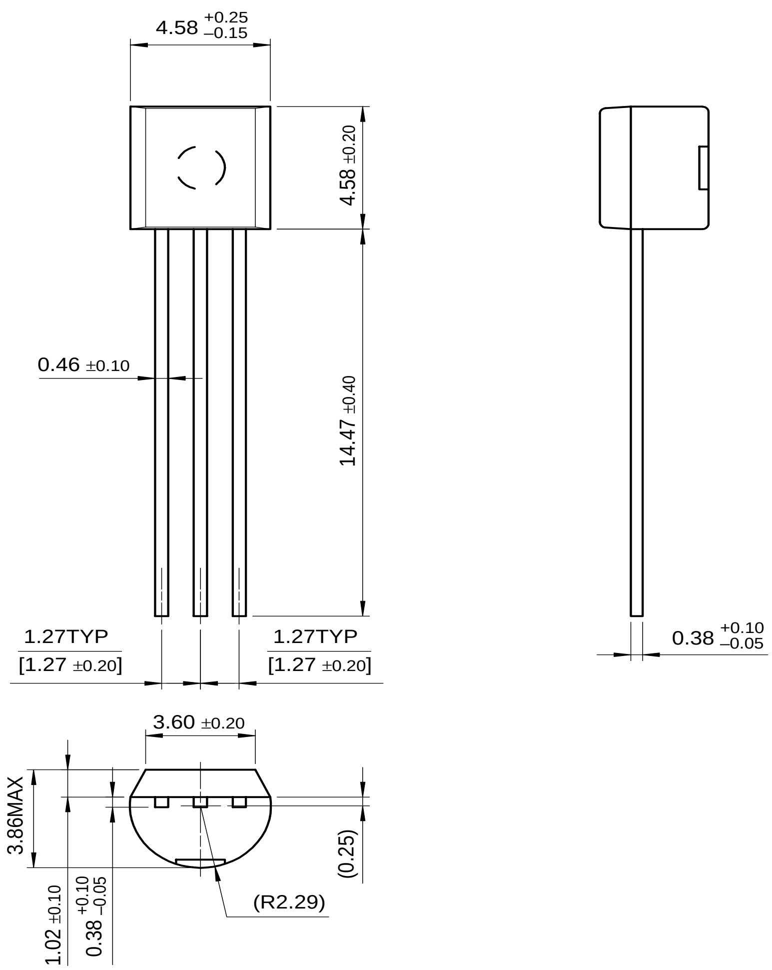


Figure 6. Current Gain Bandwidth Product

Package Dimensions

TO-92



Dimensions in Millimeters

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CoolFET™	FASTr™	MicroFET™	PowerTrench®	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	QS™	SyncFET™
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Across the board. Around the world.™		OCXPro™	RapidConnect™	UltraFET®
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CHAPTER 1

INTRODUCTION

1.1 Background

A greenhouse is a structure with a glass or plastic roof and frequently glass or plastic walls; it heats up because incoming solar radiation from the sun warms plants, soil, and other things inside the building. In other word, a greenhouse is a structure usually made of glass or clear plastic that provides protection and a controlled environment for raising plants indoors.

Water is the most important element in our life. Without it, we cannot survive. As we know, most of the gardener uses manual system to water their plant in the garden and also in the greenhouse. This system is inefficient. When we water manually, the possibility to over watering is high. Some plant can drown when we supply too much water to them.

In order to overcome this problem, automatic greenhouse watering system is used. Sensors such as temperature sensor and soil moisture detector are used to control the watering system in a greenhouse.

The system also has the capability to control the water level. As we know, some parts of Malaysia sometimes faces draught problem. So, there will be a tank that will act as a reservoir tank in case of water problem. In this tank, there is a sensor to ensure the water level is always at its maximum level.

1.2 Objectives

The main objective of this project is to automatically control the watering system in greenhouse using temperature sensor.

1.3 Scope

This project involves the evolution of watering manually to watering automatically. The controlling of the automatic watering system is use in a greenhouse. Sensor used to control the watering system is temperature sensor. Other than that, this system should also monitor the water level. Temperature of 26°C is used as the indicator value of turning on and off the valve.

1.4 Problem Statement

Irrigation is the most important cultural practice and most labor intensive task in daily greenhouse operation. Knowing when and how much to water is two important aspects of irrigation. To do this automatically, sensors and methods are available to determine when plants may need water.

1.5 Methodology

In this project, the two main parts that are evaluated are the 68HC11 and temperature sensor. The testing includes:

- Testing the evaluation board before writing the software.
- Using a 3 pin integrated circuit (IC) temperature sensor unit (IC LM35DZ) that will convert the current temperature to an appropriate voltage level. The three pins are ground (GND), voltage source (V_s) and output voltage (V_{out}). The signal will be converting to digital value using the Analogue to Digital Converter (ADC). This signal will be the input for the microcontroller.

Overall steps taken to achieve the objectives are:

i. Testing the microcontroller functionality.
ii. Downloading program into the microcontroller to test the MAX233.
iii. Testing program in the THRSim11.
iv. Testing the temperature sensor.
v. Testing the relay.
vi. Testing the valve.

1.6 Thesis Outline

Chapter 1 discuss on the background of the project, objectives, scope of the project, problem statement, methodology and also the thesis outline.

Chapter 2 focuses on literature reviews of this project based on journals and other references.

Chapter 3 mainly discuss on the system design of the project. Details on the progress of the project are explained in this chapter.

Chapter 4 presents the results of the project. The discussion focused on the result based on the experiment.

Chapter 5 concludes overall about the project. Obstacle faces and future recommendation are also discussed in this chapter.

CHAPTER 2

LITERATURE REVIEW

2.1 Introduction

"The development of models and strategies to control the environment of greenhouse crops started with the shoot environment, that is, with the greenhouse climate. One important reason was that influencing variables such as temperature, humidity, irradiation or CO2 concentration are easier to measure and to control." [Hans Peter Klaring, 2000]

From this research, we can see that there are a few factors that need to be control in a greenhouse. Those factors that need to be considered are temperature, humidity, irradiation or carbon dioxide concentration. But, in this project, factors that are going to be considered are only the temperature and humidity in a greenhouse.

2.2 Microcontroller

A microcontroller is a highly integrated chip which performs controlling functions. A microcontroller, or embedded controller, is similar to a microprocessor as used in a personal computer, but with a great deal of additional functionality combined onto the same monolithic semiconductor substrate. Microcontrollers, sometimes referred to as one-chip microcomputers, are used to control a wide range of electrical and mechanical appliances. Since they were first introduced, microcontrollers have evolved to the point where they can use for increasing complex applications. Some microcontrollers in use today are also programmable, expanding the number of application in which they can be used.

2.3 Sensors

Temperature sensor is often sensing devices embedded within some sort of insulation. The insulation may often be for electrical purposes - to isolate the sensor electrically.

"Irrigation is the most important cultural practice and most labor intensive task in daily greenhouse operation. Knowing when and how much to water is two important aspects of irrigation. To do this automatically, sensors and methods are available to determine when plants may need water." [Dr. Peter Ling, 2005]

In this article, it suggested we use soil moisture detector to do irrigation. Two suggested soil moisture detector are tensiometer and dielectric sensor. Advantage of a tensiometer is that they are not affected by the temperature of the soil water solution or the osmotic potential (the amount of salts dissolved in the soil water), as the salts can move into and out of the ceramic cup freely. Therefore tensiometer readings are not affected by electroconductivity (EC) or soil temperature. But, this type of sensor will need maintenance. Water in the tensiometer cavity needs frequent refilling when tensiometers are used in dry environments where the tensiometer becomes a source of water that seeps out due to drier surrounding soil.

"A sensor is a device placed in the system that produces an electrical signal directly related to the parameter that is to be measured. In general, there are two types of sensors, continuous and discrete." [Fedro S. Zazueta et al., 1993]

Continuous sensors produce a continuous electrical signal, such as a voltage, current, conductivity, capacitance, or any other measurable electrical property. For example, sensors of different kinds can be used to measure temperature, such as thermistors and thermocouples. A thermocouple will produce a voltage difference that increases as the temperature increases. Continuous sensors are used where values taken by a state variable are required and an on/off state is not sufficient, for example, to measure pressure drop across a sand filter.

Discrete sensors are basically switches, mechanical or electronic, that indicate whether an on or off condition exists. Discrete sensors are useful for indicating thresholds, such as the opening and closure of devices (vents, doors, alarms, valves, etc.). They can also be used to determine if a threshold of an important state variable has been reached. Some examples of discrete sensors are a float switch to detect if the level in a storage tank is below a minimum desirable level, a switching tensiometer to detect if soil moisture is above a desired threshold, and a thermostat to indicate if a certain temperature has been reached.

Sensors are an extremely important component of the control loop because they provide the basic data that drive an automatic control system. Understanding the operating principle of a sensor is very important. Sensors many times do not react directly to the variable being measured. For example, when a mercury thermometer is used to measure temperature, temperature is not being measured; rather, a change in volume due to a change in temperature is measured. Because there is a unique relationship between the volume and the temperature the instrument can be directly calibrated to provide temperature readings. The ideal sensor responds only to the "sensed" variable, without responding to any other change in the environment.

"It is important to understand that sensors always have a degree of inaccuracy associated with them and they may be affected by other parameters besides the "sensed" variable. The classical example is that of soil moisture measurement using electrical conductivity probes. The electrical signal produced by this sensor is closely related to soil moisture, but is greatly affected by temperature and dissolved salts (fertilizers, etc.) in the soil. Another important factor related to the sensor is its time response. A sensor must deliver a signal that reflects the state of the system within the frame of time required by the application. Using the soil moisture measurement example, the sensor must be able to "keep up" with the changes in soil moisture that are caused by evapotranspiration. Thus, proper selection of the sensors and understanding the principle of operation is critical to the success of a control system." [Fedro S. Zazueta et al., 1993]

In this patent, it stated a few factors that need to be consider when we are choosing our sensors. Factors that need to be considered are such as sensors accuracy and time response. In certain project, if we will need a system that has high accuracy and fast response so sensor with high accuracy and fast response are needed. In certain cases, the factors are not essential.

"A controlled irrigation system can include a control device for determining whether to irrigate soil and at least one irrigation structure having an actuator for

*controlling water flow. The actuator can be communicably coupled to the control device for delivering water to irrigate a region. The controlled irrigation system further can include at least one time domain reflectometry sensor ("TDRS") located in the soil and communicably coupled to the control device for measuring soil moisture where the control device determines whether to irrigate the soil based on data from the at least one TDRS. Additionally, a method for controlling an irrigation system can include providing multiple. TDRS's having probes, distributing each TDRS at a different soil depth, measuring soil moisture content, and irrigating soil based on the measuring step*ò [Dukes, Michael D. *et al.*, 2005]

2.4 Valve

"*Solenoid valves are electromechanical valves that are controlled by stopping or running an electrical current through a solenoid, in order to change the state of the valve. A solenoid is a coil of wire that is magnetized when electricity runs through it. The solenoid valve makes use of this solenoid in order to activate a valve, thus controlling water flow, airflow and other things with electricity. Basically, there are three types of solenoid valves: the general-purpose type, low-pressure steam type and the high pressure steam type."* [Jimmy Sturo, 2006]

In this article, it stated that there are three types of solenoid valve which are general-purpose type, low pressure steam type and the high pressure steam type. Valve is one the components that will need maintenance. The solenoid valve can get damaged after a period of time. Thus, a replacement solenoid will be needed.

2.5 Water Level Monitoring

"The model consists of a series of tanks arranged one below the other. The volume of the tanks is in descending order (The highest tank being the largest). Water flows from the top tank through outlets at the bottom. Three tanks or trophic levels chosen for the model is the optimum number required to analyze the effect of top down and bottom up controls. Each tank has two outlets, outlet a and outlet b. Each outlet has the water flow through it regulated by means of valves. These valves are controlled by floats in the tanks. Valve a of each tank is controlled by the level of water in the tank above it (preceding) while valve b is controlled by the level of the water in the given tank itself. The water from the last tank and outlets a flow into a large basin from which the water is re-circulated to the 1st tank." [Maurice S. Devaraj, 2005]

In this journal, it discuss on the model of a flow control. This model can used to control the flow control of the water in the tank. From this model, the idea for monitoring water level is produced. This is to ensure that the plant will always get water even though drought happens.

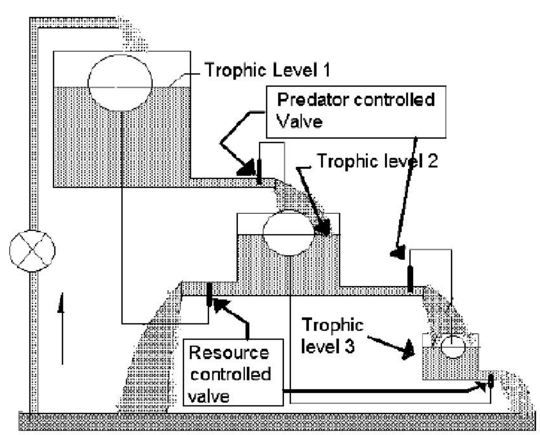


Figure 2.1: Three Tank Model

CHAPTER 3

SYSTEM DESIGN

3.1 Overall System Design

Basically, this project consists of an input and an output. The input is the temperature sensor and the output is the irrigation valve. The block diagram is shown in Figure 3.1.

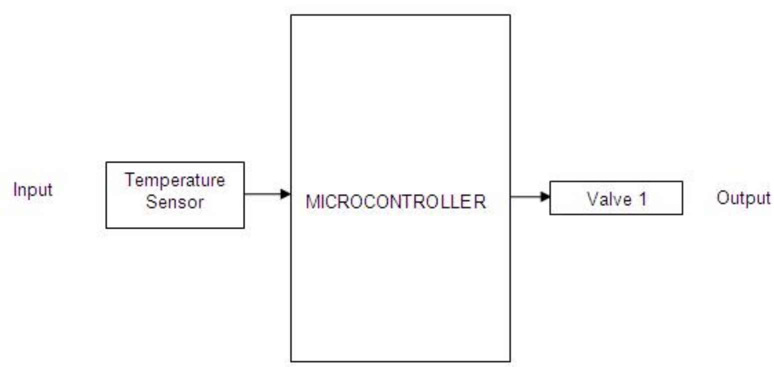


Figure 3.1: Block Diagram

Temperature sensor gives input to the microcontroller and the output of the microcontroller will drive the valve to activate. The output of the microcontroller is driven by the temperature sensor itself. A relay is needed to drive the valve since the valve uses the on/off switching. In this project, a relay of 6V is used. The value of the relay is not important since it is only used to drive the valve. The connection of the valve and the relay is isolated in the relay itself.

For this project, temperature of 26°C is the value indicated to turn on and off the valve. If the temperature is higher than 26°C, the valve will turn on and vice versa. At first, the microcontroller will scan the environment temperature. The LED will display running light indicating that the program is running. Once the microcontroller detected that the temperature is higher than 26°C, all of the LED at Port B and the indicator light at the valve will turn on. Thus, the valve is turn on. As long as the microcontroller does not detect the temperature is higher than 26°C, all of the LED and indicator light at the valve will not turn on meaning the valve is in off state. The overall schematic design is shown in Figure 3.2.

Figure 3.3 shows the overall system design of the project while Figure 3.4 shows the controller of the watering system. The lighting LED indicates there is power supply supplied to the board.

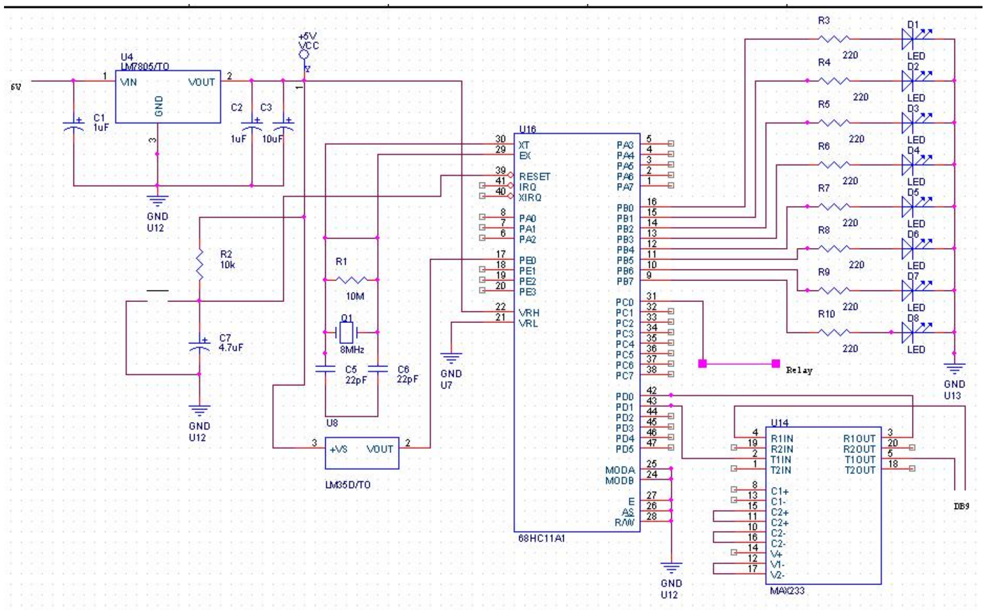


Figure 3.2: Full Circuit Design

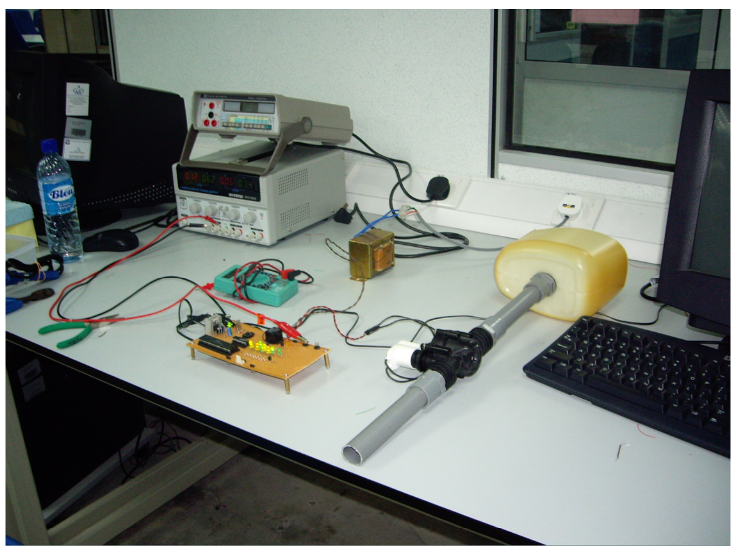


Figure 3.3: Overall System Design

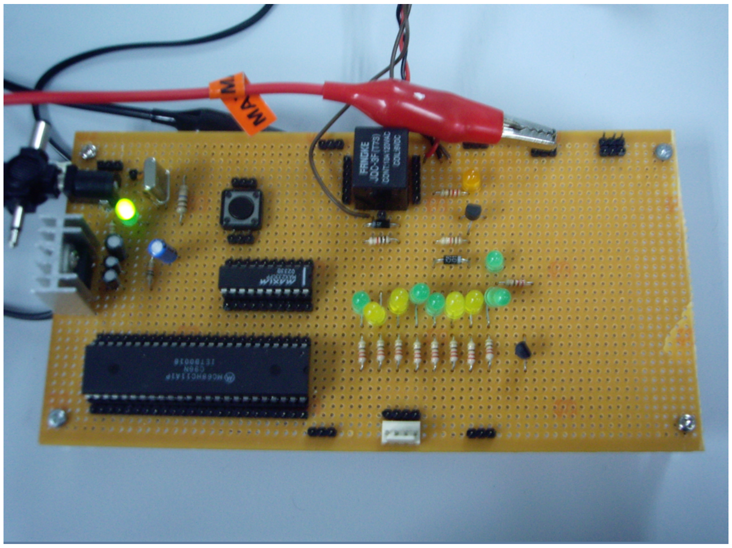


Figure 3.4: Controller of the Watering System

3.2 MC68HC11 Evaluation Board

The microcontroller that will be used in this project is MC68HC11A1 that consists of 256 RAM. Port E is used for input port. While Port B and Port C are use for output port

The main part that will need to be done is constructing the bootstrap mode circuit. In this stage, the clock needs to be generated. Once the circuit has been constructed, we will test the clock. By giving supply to the microcontroller, output is tapped from pin 27 of the microcontroller to an oscilloscope. From there, we will see that there is a waveform generated on the oscilloscope. This waveform is the waveform of the pulse generated by the microcontroller.

Figure 3.5 shows the memory map of 68HC11 that we should know before the software part is developed.

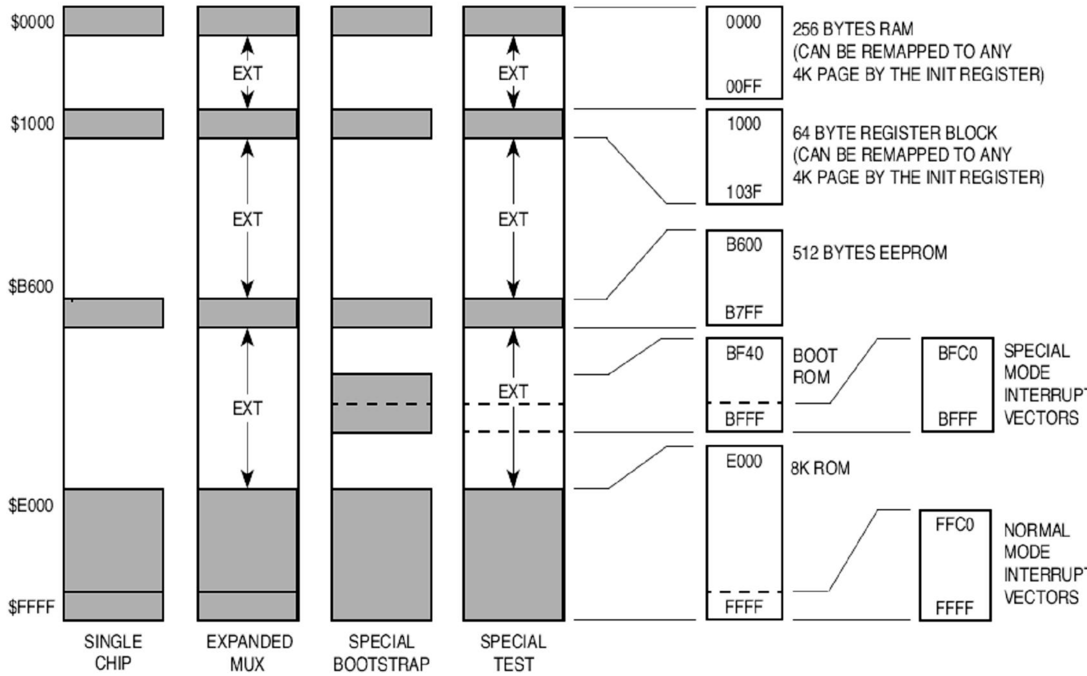


Figure 3.5: Memory Map

The microcontroller is programmed by using software named WP11. Figure 3.6 shows WP11 software. Before programming the microcontroller, we will need to perform communication test and initialize the board by clicking the communication test and initialize device button.

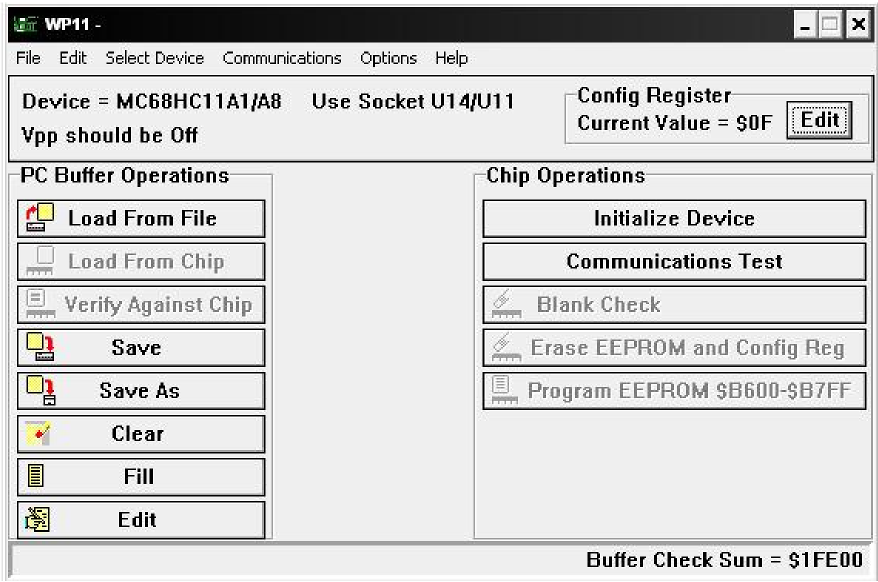


Figure 3.6: Software WP11

When clicking on the initialize device button, a box saying òPress Programmer Reset Button the click OKò will appear (Figure 3.7). If the device is success to be initialized, then it may proceed to programming the microcontroller.

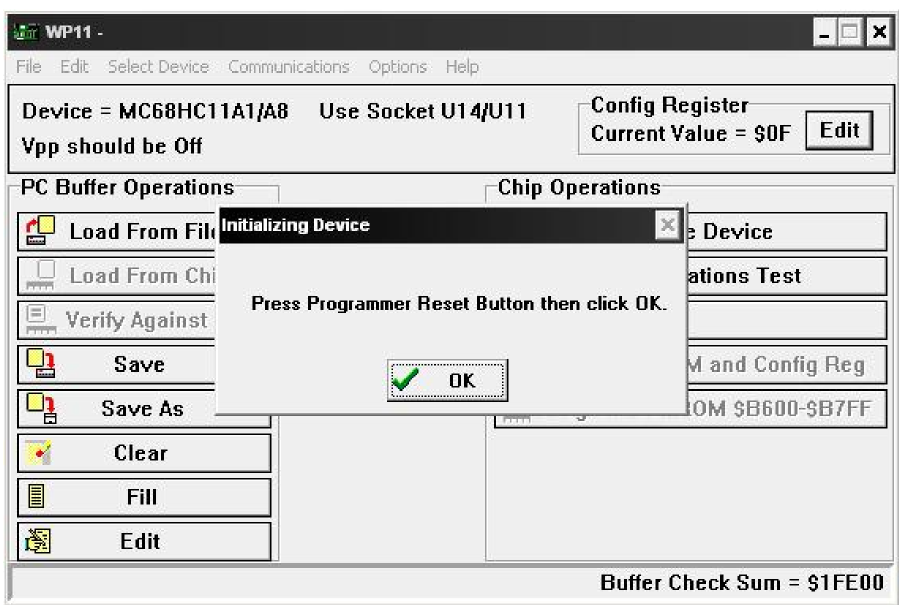


Figure 3.7: Clicking the Initialize Device Button

After initializing the device, erase the program by clicking the erase EEPROM and Config Reg button and perform blank check to ensure that there is no other program inside the microcontroller. Finally, click on the load from file button to download the program.

Figure 3.8 shows step to initialize the Analog-to-Digital Converter (ADC). Firstly, we need to set the ADPU to 1 so that the ADC is turn on. ADPU stand for analog to digital power unit. Then CSEL is set to 0 since we use the internal clock. CSEL stand for clock select. Lastly, a 100εs delay is required to stabilize the system.

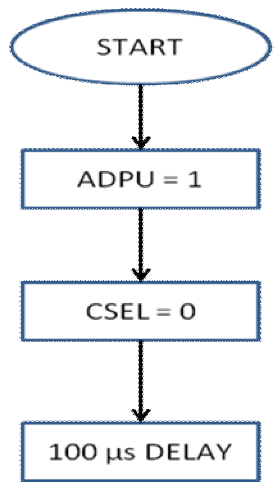


Figure 3.8: Flowchart of Initializing ADC

3.3 THRSim11 Software

The Motorola 68HC11 microcontroller is a popular microcontroller used in many applications. Before downloading program into the microcontroller, the program needs to be assembled. With the THRSim11 program you can edit, assemble, simulate and debug programs for the 68HC11 on your windows PC. You can also use THRSim11 to debug the program on your target EVM or EVB compatible board. The simulator simulates the CPU, ROM, RAM, and all memory mapped I/O ports. It also simulates the on board peripherals such as:

- timer (including pulse accumulator),
- analog to digital converter,
- parallel ports (including handshake),
- serial port,
- I/O pins (including analog and interrupt pins).

While debugging the graphical user interface makes it possible to view and control every register (CPU registers and I/O registers), memory location (data, program, and stack), and pin of the simulated microcontroller even when the program is running. It is possible to stop the simulation at any combination of events. For example, stop when RxD becomes low and RAM location $003F contains $BD or I/O register TCNT is greater than $3456.

A number of (simulated) external components can be connected to the pins of the simulated 68HC11 while debugging. For example:

- LED's,
- switches,
- analog sliders (variable voltage potential).
- serial transmitter and receiver.

There is also a 4 x 20 LCD character display mapped in the address space of the 68HC11. THRSim11 can communicate with the Motorola EVM and EVB boards or with any other board running the BUFFALO monitor program. This monitor program can be downloaded (for free) from the Motorola website. When your assembly program is loaded into the target board the graphical user interface makes it possible to view and control every register (CPU registers and I/O registers) and memory location (data, program, and stack) of the real microcontroller. It is possible to stop the execution at any address and inspect or change the registers and memory.

3.3.1 THRSim11 User's Manual for This Project

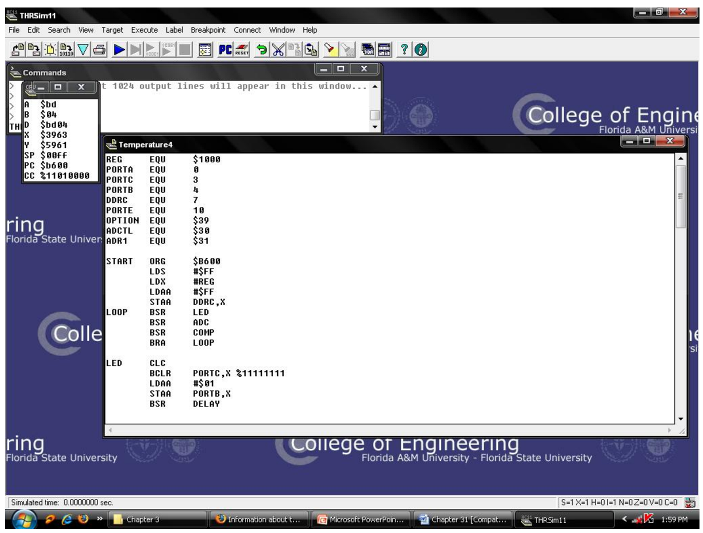


Figure 3.9: Opening a Program File

 Click this button to assemble the program. All the programs need to be assembled before downloading it into the microcontroller.

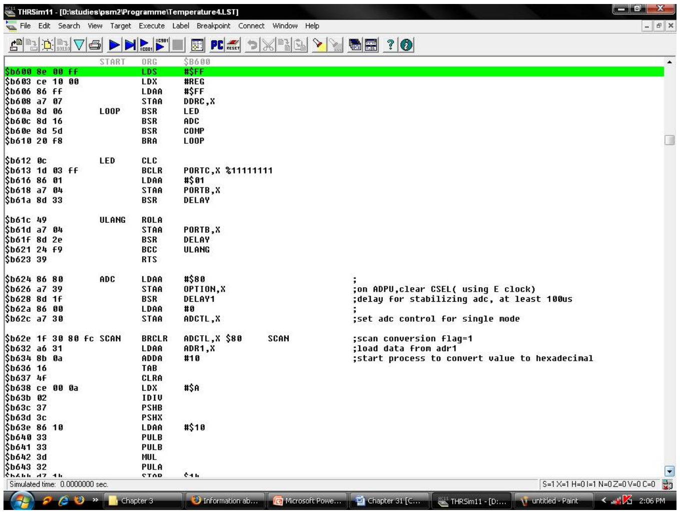


Figure 3.10: Program after Assembled

Once it is assembled, a window like this will appear (Figure 3.10). In this window, the program is assembled into assembly language.

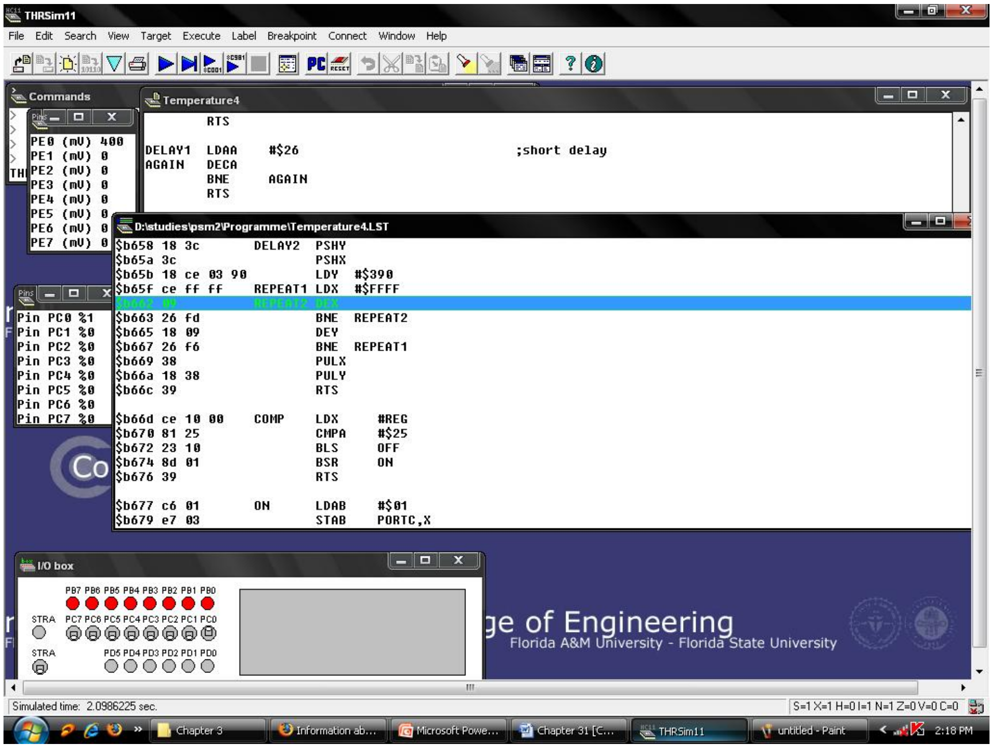
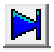
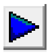
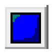


Figure 3.11: Output after Program Run

 This button is used to run the program step by step. We can easily detect the error by using this button and also we can see what is done by the microcontroller step by step.

 This button is used to run the program.

 This button is used to stop the running program.

In this software, we can directly assemble and test our program whether it does function as we wanted it or not. As an example, we can see in Figure 3.11 that when an input of 400mV is given at Port E, all the LED at Port B is turn on indicating that the valve is turn on.

3.4 Temperature Sensor

The LM35 is an integrated circuit sensor that can be used to measure temperature with an electrical output proportional to the temperature (in ^{o}C). With an LM35, temperature can be measured more accurately than using a thermistor. The sensor circuitry is sealed and not subject to oxidation. The LM35 generates a higher output voltage than thermocouples and may not require that the output voltage be amplified.

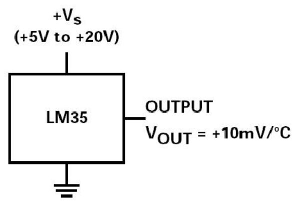


Figure 3.12: Pin Configuration of LM35

For LM35, the scale factor is 0.01V/°C meaning the nominal output voltage is 250mV at 25°C and 1.000V at 100°C. It does not require any external calibration or trimming. The most important characteristic of the LM35 is that it draws only 60ε Amps from its supply and produces a low self heating capability.

The output of temperature sensor is sensed by using a voltmeter. The output voltage is converted to temperature by a simple conversion method. The general equation used to convert from the output temperature to temperature is:

$$\text{Temperature } (°C) = V_{out} * 100\ °C/V$$

The right connection of LM35 is important to make sure that we can obtain the result. Common mistake that student will do is connecting the V_s and ground pin in reverse meaning ground will be connected to V_s and vice versa. This is due to the way student views the ic from bottom view or upper view. As in the datasheet, the ic is view based on the bottom view (Figure 3.13). In this circuit, parameter value that commonly used is 5V.

Figure 3.13: Connection Diagram for LM35DZ

3.5 Relay

In order to test the relay, it is connected to a LED. When there is input from both the 5V and 6V, the LED will turn on. If one of the inputs is not given, the LED will not turn on. Then, the LED is change to the irrigation valve (Figure 3.15). The configuration for the relay circuit is as shown in Figure 3.14 below.

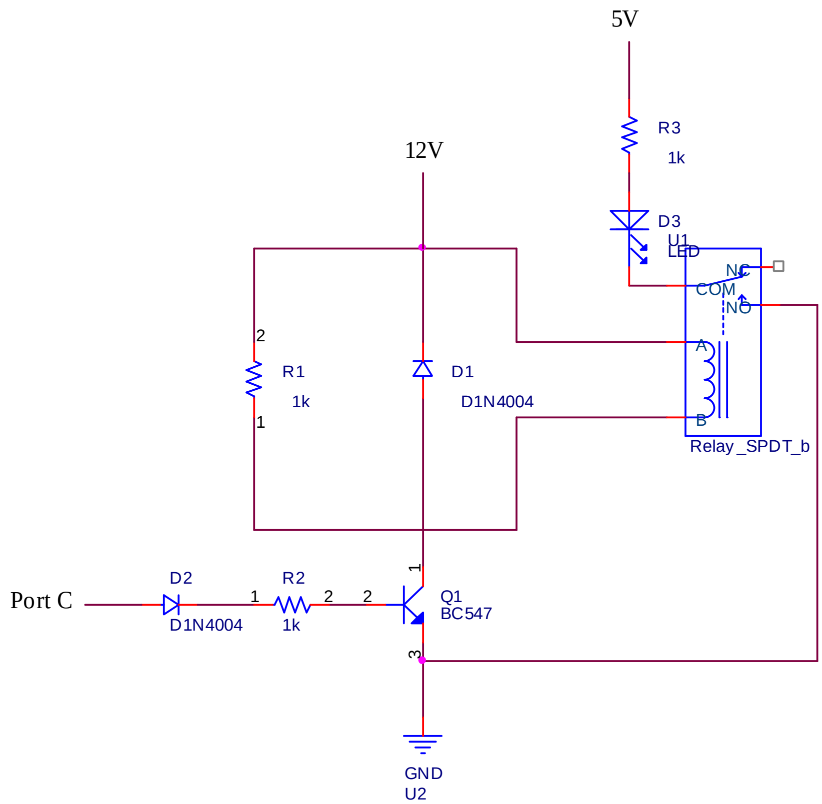


Figure 3.14: Relay Connection to Test the Functionality of the Relay

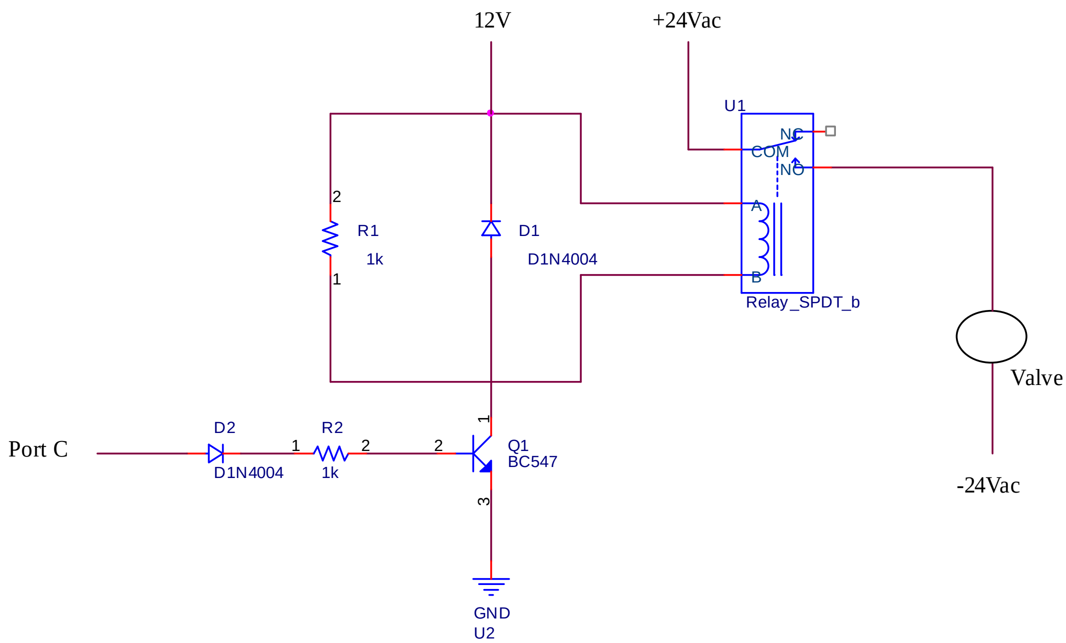


Figure 3.15: Relay Connection to the Valve

3.6 Irrigation Valve

Irrigation valve is one of the solenoid valves. A solenoid valve has two main parts: the solenoid and the valve. The solenoid converts electrical energy into mechanical energy which, in turn, opens or closes the valve mechanically. In this project, the irrigation valve works on $24V_{ac}$. The valve is testing by simply connecting the valve to a transformer that produce $24V_{ac}$. After making sure that the valve is functioning, it is connected to the relay. A relay (normally open) is needed to drive the valve. The normally open relay is used to connect the output Port C of the microcontroller with the irrigation valve. When there is output at Port C it will close the relay and turn on the valve. A diode is placed at Port C0 to avoid reverse current that can harm the microcontroller. Figure 3.17 shows the photograph of the actual valve. The detail configuration is shown in Figure 3.16.

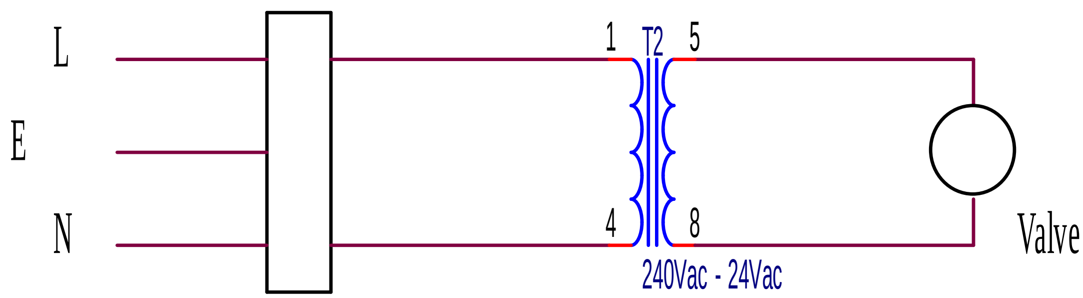


Figure 3.16: Testing Valve

Figure 3.17: The Actual Irrigation Valve

CHAPTER 4

RESULTS

4.1 Microcontroller (MC68HC11A1)

Figure 4.1 shows the pin configuration of microcontroller (MC68HC11A1).

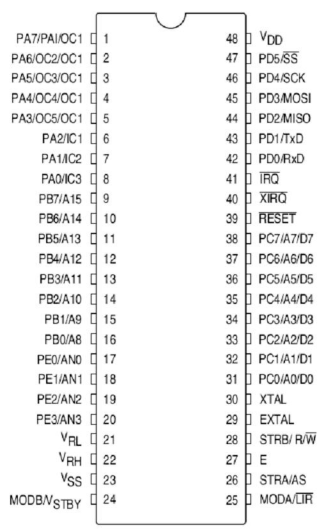


Figure 4.1: Pin Configuration of MC68HC11A1

The main part that was tested is the MC68HC11A1. Figure 4.2 shows the circuit configurations for a bootstrap mode. The system clock need to be tested to assure the controller is fully functioning. An 8 MHz crystal is connected to the crystal pins which are EXTAL (pin 29) and XTAL (pin30). The internal clock frequency is one fourth of the supplied frequency. Hence, the internal clock frequency is 2 MHz as shown in Figure 4.3. This frequency is generated at E (pin 27).

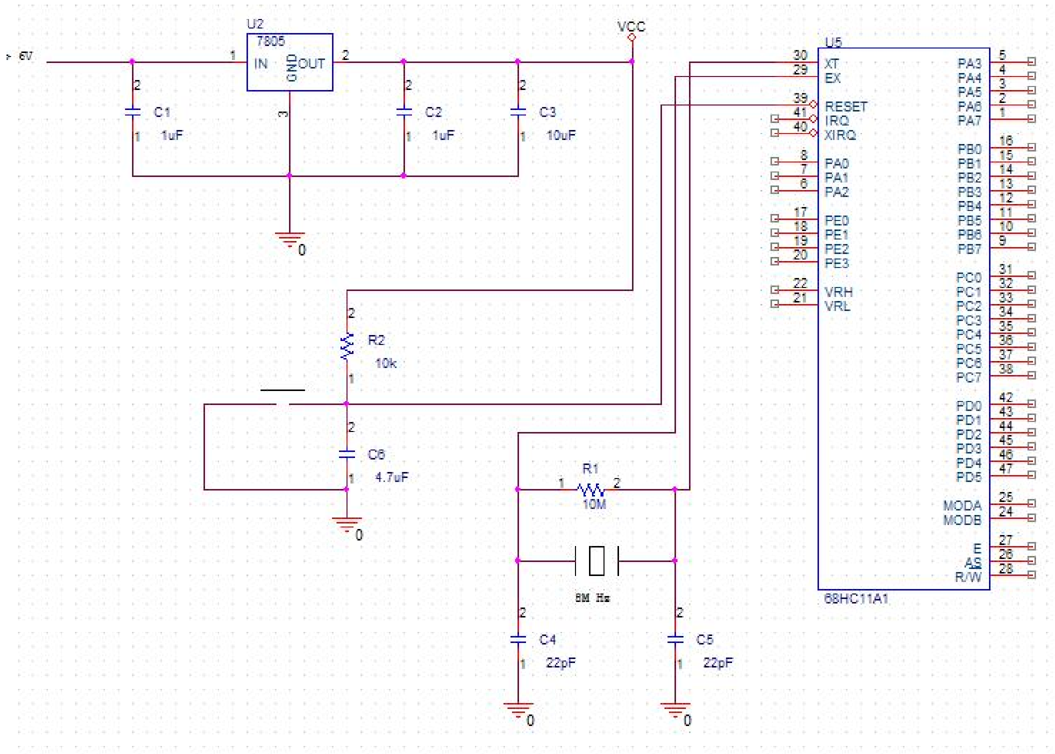


Figure 4.2: Circuit for Bootstrap Mode

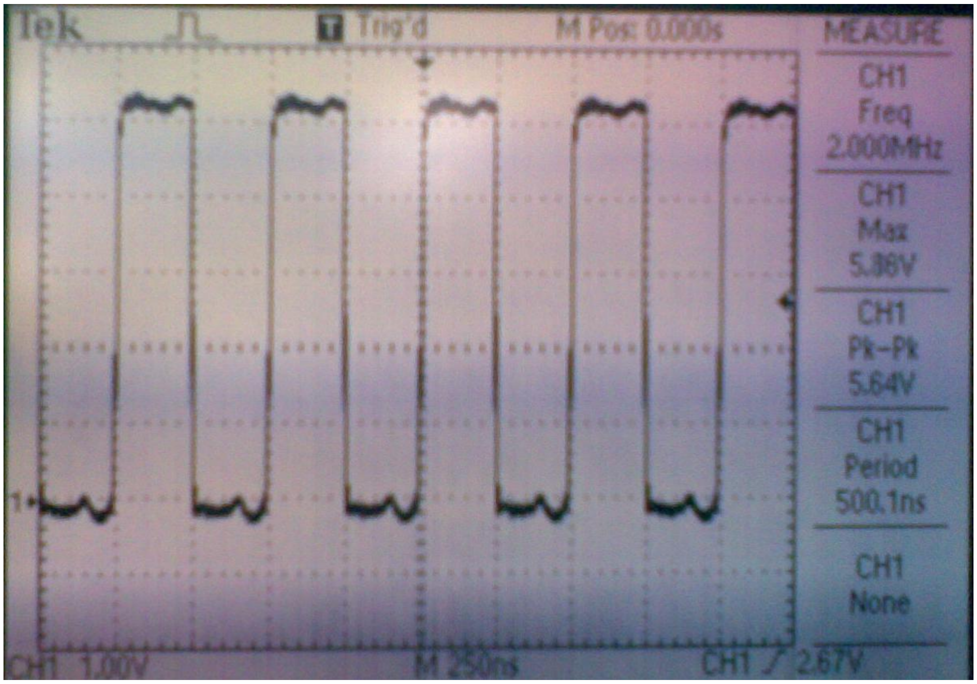


Figure 4.3: Output Waveform at Pin 27

Scale: For x axis, 1cm: 1V

For y axis, 1cm: 1V

The clock speed or frequency is:

1/4 x 8 MHz = 2 MHz

Thus, the frequency is 2MHz.

4.2 MAX 233

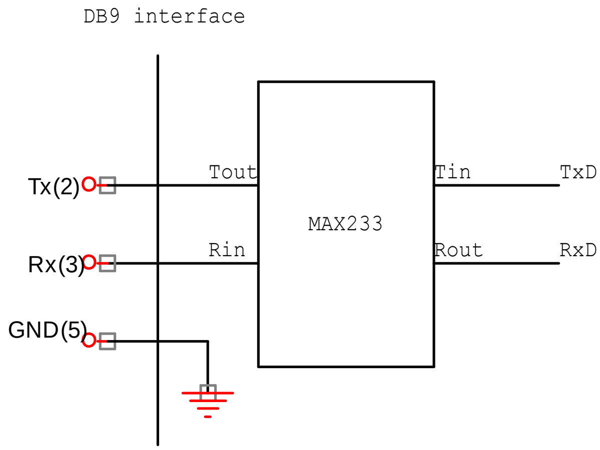


Figure 4.4: EIA232 Interface

Figure 4.4 shows the interface of the EIA232. MAX 233 is used for translating signals between a microcontroller and a standard computer serial port. From Figure 4.5, we can see that the MAX 233 is connected to the PD0 (pin 42) and PD1 (pin 43). These two pins are for communications port in order to communicate with a personal computer. Then, from the MAX233 it is connected to DB9 to interface the board with the computer. DB9 interface uses pin 2, 3 and 5 of the female connector where pin 2 is for the transmission, pin 3 for receiver and pin 5 will be grounded. A flashing LED program is uploaded to test the MAX 233. The output was displayed on the LED.

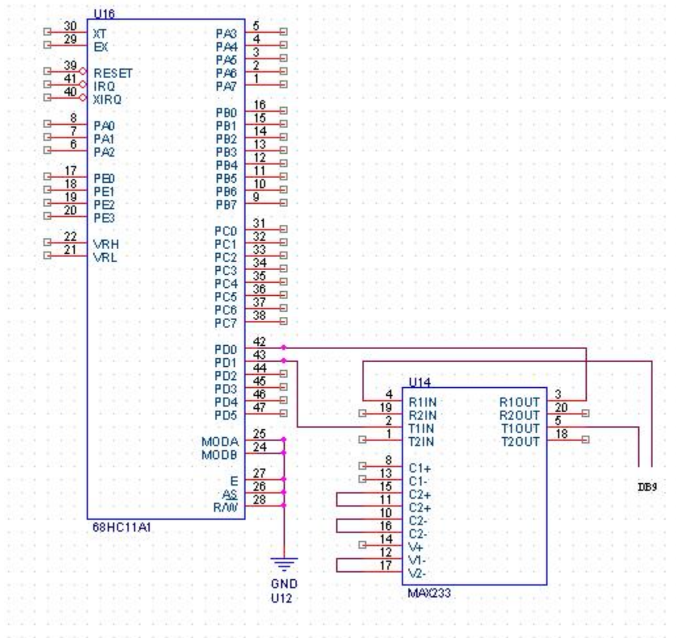


Figure 4.5: MAX 233 Connections to Microcontroller

Below is the flashing LED program that was used to test MAX 233:

```
REGS      EQU   $1000
PORTB     EQU   $04
          ORG   $B600
          LDX   #REGS

AGAIN     CLC
          LDAA #$01
          STAA  PORTB, X
          BSR   DELAY
ULANG     ROLA
          STAA  PORTB, X
          BSR   DELAY
          BCC   ULANG
          BRA   AGAIN
DELAY     LDY   #$1010
REPEAT    DEY
          BNE   REPEAT
          RTS
          END
```

4.3 Temperature Sensor (LM35DZ)

The temperature sensor used in this project is the LM35DZ ic. The rated for full temperature range is between -55° and +150°. But in this project, it only uses the basic centigrade temperature sensor which is +2° and +150° (Figure 4.6). The temperature sensor is shown as below

Figure 4.6: Temperature Sensor

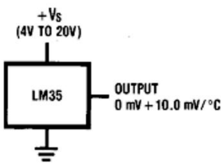


Figure 4.7: Basic Centigrade Temperature Sensor (+2°C to +150°C)

The output voltage is linear, which is:

V_{out} = 10mV x Temperature (°C)

Table 4.1 is the reading of the tested temperature sensor. The temperature sensor is tested in the laboratory using the lab temperature. From the table, we can see that the value of temperature for a range of given voltage from 4V to 20V is almost the same. In this project, we use 5V as the sensor voltage input since the input of the microcontroller is 5V.

Table 4.1: Data of Temperature Sensor

V_s(V)	V_{out} (mV)	Temperature (°C)
4	273	27.3
5	276	27.6
6	275	27.5
7	276	27.6
8	275	27.5
9	275	27.5
10	275	27.5
11	276	27.6
12	277	27.7
13	275	27.5
14	276	27.6
15	275	27.5
16	275	27.5
17	274	27.4
18	276	27.6
19	275	27.5
20	276	27.6

4.4 Final Result

Table 4.2 shows the result of the project. Since the demonstration is done at the lab, the predetermined temperature is set as 26°C. When the temperature is higher than 26°C, the valve will turn on. When the temperature is lower or equal than 26°C, the valve will turn off.

Table 4.2: Data for operation of Greenhouse Watering System

Input (Temperature, °C)	Output (Valve)
T > 26 °C	ON
T Ò26 °C	OFF

When the valve is turn on, it will be activated for 3 minutes. After 3 minutes, it will automatically turn off and scan for the temperature once more. Below is the operating system of the valve.

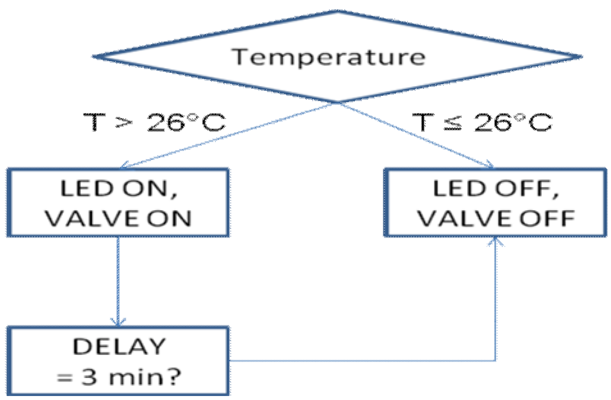


Figure 4.8: Flow Chart of Valve Operation

CHAPTER 5

CONCLUSION AND RECOMMENDATIONS

5.1 Conclusion

Greenhouse is becoming popular planting habit nowadays especially in countries that have many seasons in a year such as Europe. This is due to some plants need specific environment control such as temperature and soil moisture control for growing.

In this project, we can automatically control the watering system using the temperature sensor. The temperature sensor which is LM35DZ is a precision temperature sensor. The main advantage of this chosen sensor was it output voltage is linearly proportional to the Celsius temperature.

5.2 Obstacle Faces

Firstly, components such as the irrigation valve is difficult to find since most of the source on the internet stated that the valve are from overseas.

Next, I have been having difficulties in initializing the microcontroller board. This is due to two factors which are the stability of the board and the USB to RS232 cable itself.

Last but not least, obstacle faces is to predetermine the value of the temperature. The temperature values are different for different places and area. As an example, most of the testing is done in the hostel but for the day of presentation it is in the laboratory. Thus, different temperature is sensed. To overcome this problem, setting the predetermine temperature according to the temperature in the laboratory is done which is 26 °C.

5.3 Recommendations

As an individual opinion, this project is fascinating to be continued. In the future, this project can be further studied by adding the soil moisture sensor and the monitoring of the water level.

Other than that, student can also add some of the recommendations as stated below:

i. Adding LCD display so that we can easily read the temperature of the system.
ii. Changing the 68HC11 to PIC since PIC has much more memory without adding other icös such as EEPROM.
iii. Further investigation on the effectiveness of the system by implementing other sensors such as humidity sensor.
iv. Adding heating and cooling system to the greenhouse.
v. Develop the same system but using the wireless link to the sensors that can prevent from using large lengths of wire.

5.2.1 Costing & Commercialization

a. Costing

Table 5.1 shows the overall costing for the project:

Table 5.1: Cost for Project

Component	Price per Unit	Quantity	Price
MC68HC11A1	RM 40.00	1	RM 40.00
MAX233	RM 8.00	1	RM 8.00
LM35DZ	RM 6.00	1	RM 6.00
Voltage Regulator (7805)	RM 1.00	1	RM 1.00
DB9	RM 0.50	1	RM 0.50
Connector 4 Way	RM 0.17	1	RM 0.17
3 pin Plug Top Sirim	RM 2.50	1	RM 2.50
Crystal (8 MHz)	RM 1.20	1	RM 1.20
DC Jack	RM 0.60	1	RM 0.60
Heat Sink	RM 0.90	1	RM 0.90
LED	RM 0.15	10	RM 1.50
PCB Header	RM 0.50	6	RM 3.00
PCB Stand	RM 1.00	4	RM 4.00
Relay	RM 2.50	1	RM 2.50
Reset Button	RM 1.00	2	RM 1.00
Strip Board	RM 3.00	1	RM 3.00
Valve	RM 60.00	1	RM 60.00
Wire Wrapping	RM 15.00	1	RM 15.00
Capacitor (1εF)	RM 0.08	2	RM 0.16
Capacitor (100εF)	RM 0.15	1	RM 0.15
Capacitor (4.7εF)	RM 0.07	2	RM 0.14
Capacitor (22pF)	RM 0.08	2	RM 0.16
IC Base (48 pin)	RM 0.65	1	RM 0.65
IC Base (20 pin)	RM 0.23	1	RM 0.23
Resistor (220Ý)	RM 0.05	10	RM 0.50
Resistor (10kÝ)	RM 0.01	1	RM 0.01
Resistor (10MÝ)	RM 0.04	1	RM 0.04
		Total:	RM 152.91

b. Commercialization

Communities nowadays usually search for products that are users friendly. Since this project has only one sensor, it is not very suitable to commercialize. On the other hand, if this project is improved as suggested above it is quite an interesting product that can be commercialized. This product can save water, money and also time since it is automatically control.

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11. National Semiconductorôs Temperature Sensor Handbook, LM35, LM45 Celsius Sensors, http://www.national.com/appinfo/tempsensors/files/temphb.pdf

APPENDICES

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Signature : ______________________________

Author : MASAYU BINTI HUSSEIN

Date : 30 NOVEMBER 2007

Specially dedicated to my beloved family,

Hairul Izuwan Hashami and all my friends

[UN]IVERSITI MALAYSIA PAHANG

BORANG PENGESAHAN STATUS TESIS♦

JUDUL: **AUTOMATIC GREENHOUSE WATERING SYSTEM USING MICROCONTROLLER**

SESI PENGAJIAN: **2007/2008**

Saya **MASAYU BINTI HUSSEIN (851109-13-5060)**
(HURUF BESAR)

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"I hereby acknowledge that the scope and quality of this thesis is qualified for the award of the Bachelor Degree of Electrical Engineering (Electronics)"

Signature : ____

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